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Mei et al.

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(54) **RANDOM SPARSITY HANDLING IN A SYSTOLIC ARRAY**

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(73) Assignee: **Intel Corporation**, Santa Clara, CA (US)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 644 days.

(21) Appl. No.: **17/211,627**

(22) Filed: **Mar. 24, 2021**

(65) **Prior Publication Data**

US 2022/0309124 A1 Sep. 29, 2022

(51) **Int. Cl.**

G06F 17/16	(2006.01)
G06F 7/544	(2006.01)
G06F 9/30	(2018.01)
G06F 15/80	(2006.01)
G06F 17/11	(2006.01)

(52) **U.S. Cl.**

CPC ***G06F 17/16*** (2013.01); ***G06F 7/5443*** (2013.01); ***G06F 9/3001*** (2013.01); ***G06F 9/30043*** (2013.01); ***G06F 15/8046*** (2013.01); ***G06F 17/11*** (2013.01)

(58) **Field of Classification Search**

CPC G06F 7/5443; G06F 15/8046; G06F 9/30036; G06F 9/3893; G06F 9/5027; G06N 3/048; G06N 3/0495; G06N 3/063; G06N 3/082; G06N 20/00; G06T 1/20

USPC 708/520

See application file for complete search history.

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2022/0261456	A1 *	8/2022	Gladding	G06F 17/16
2022/0309124	A1	9/2022	Mei et al.	

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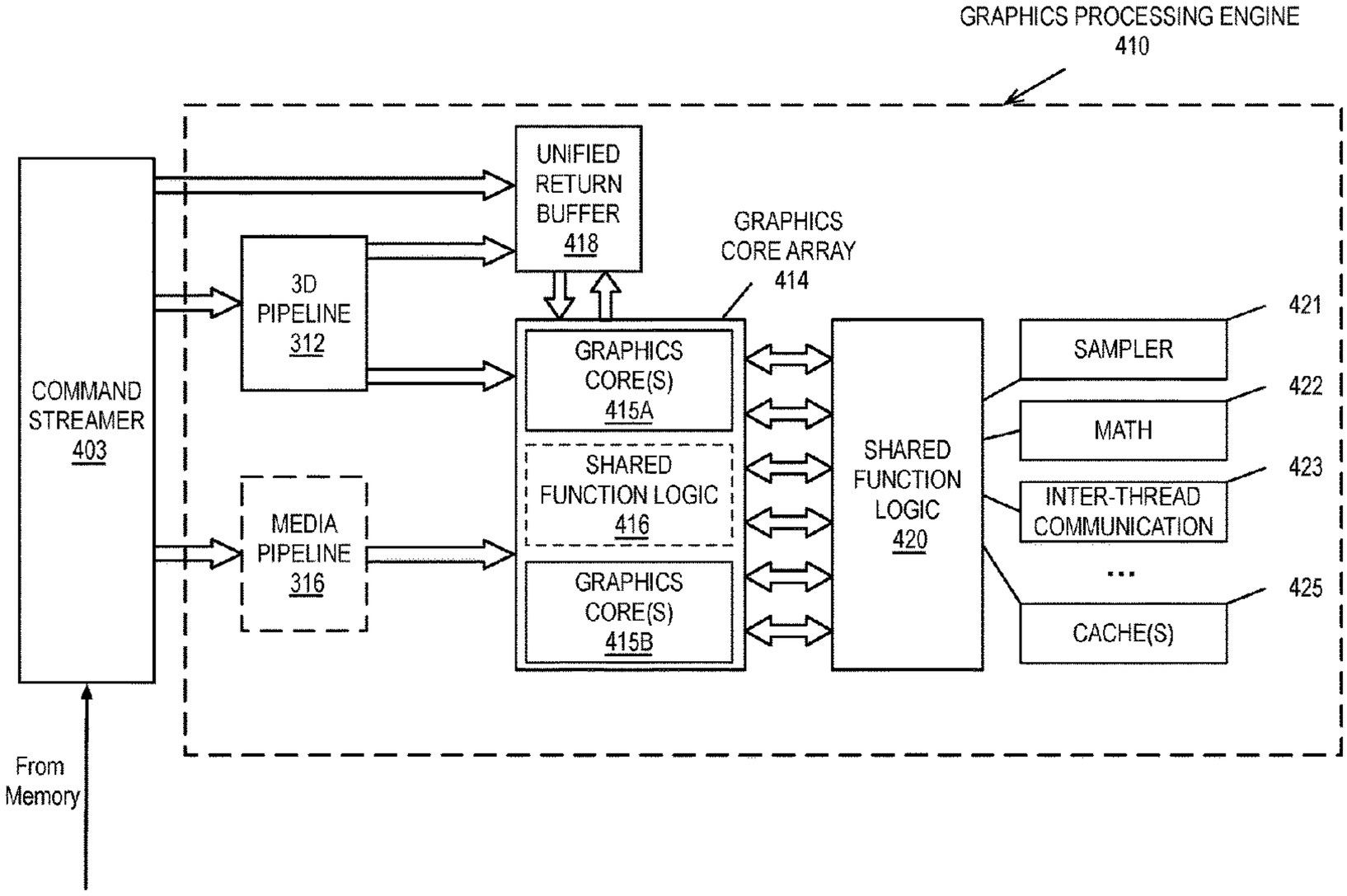
Primary Examiner — Tan V Mai

(74) *Attorney, Agent, or Firm* — Jaffery Watson Mendonsa & Hamilton LLP

(57) **ABSTRACT**

Matrix multiply units can take advantage of input sparsity by zero gating ALUs, which saves power consumption, but compute throughput does not increase. To improve compute throughput from sparsity, processing resources in a matrix accelerator can skip computation with zero involved in input or output. If zeros in input can be skipped, the processing units can focus calculations on generating meaningful non-zero output.

20 Claims, 39 Drawing Sheets



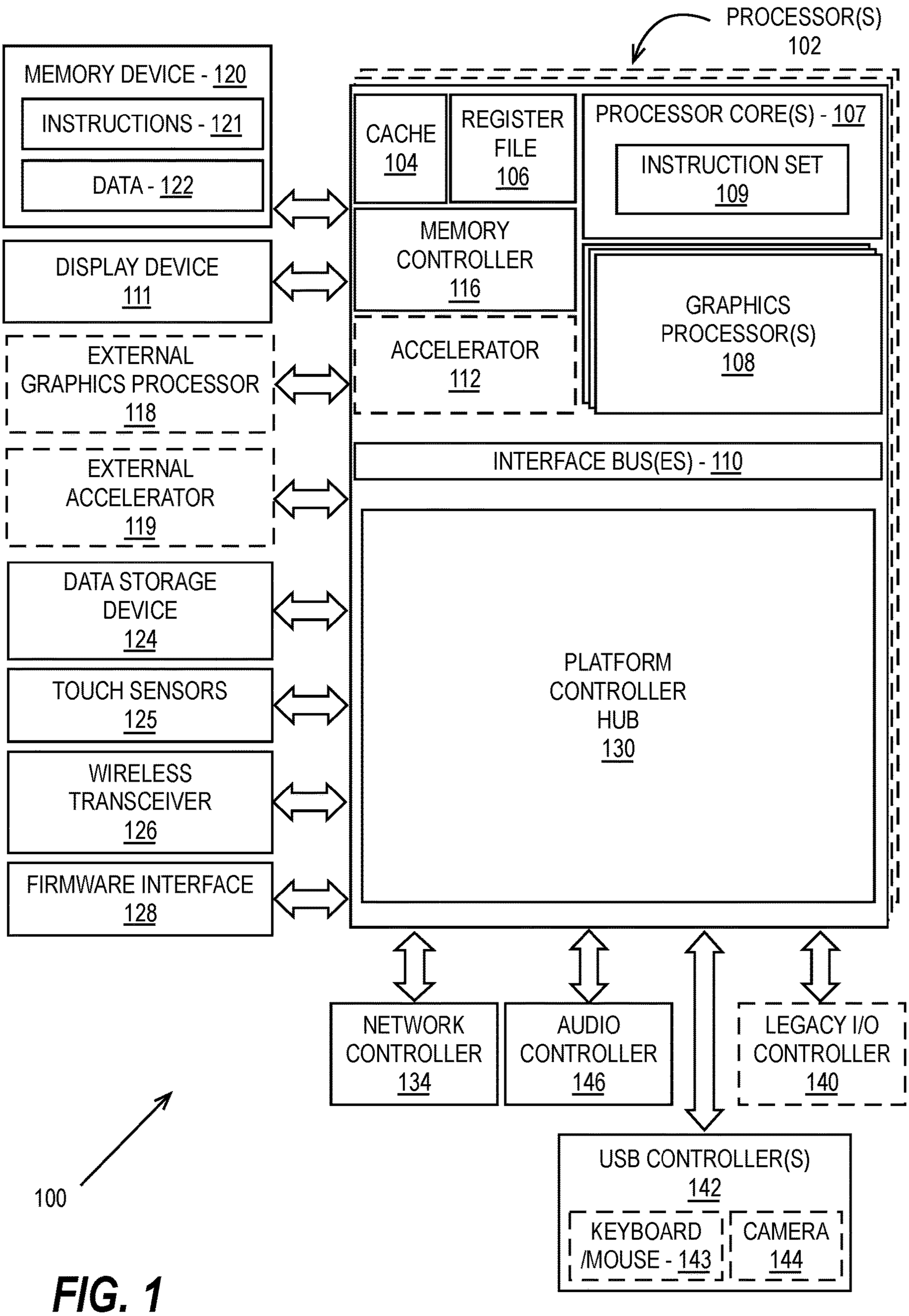

PROCESSOR(S)
102
MEMORY DEVICE - 120
INSTRUCTIONS - 121
DATA - 122
DISPLAY DEVICE
111
EXTERNAL
GRAPHICS PROCESSOR
118
EXTERNAL
ACCELERATOR
119
DATA STORAGE
DEVICE
124
TOUCH SENSORS
125
WIRELESS
TRANSCEIVER
126
FIRMWARE INTERFACE
128
CACHE
104
REGISTER
FILE
106
PROCESSOR CORE(S) - 107
INSTRUCTION SET
109
MEMORY
CONTROLLER
116
ACCELERATOR
112
GRAPHICS
PROCESSOR(S)
108
INTERFACE BUS(ES) - 110
PLATFORM
CONTROLLER
HUB
130
NETWORK
CONTROLLER
134
AUDIO
CONTROLLER
146
LEGACY I/O
CONTROLLER
140
USB CONTROLLER(S)
142
KEYBOARD
/MOUSE - 143
CAMERA
144
100

FIG. 1

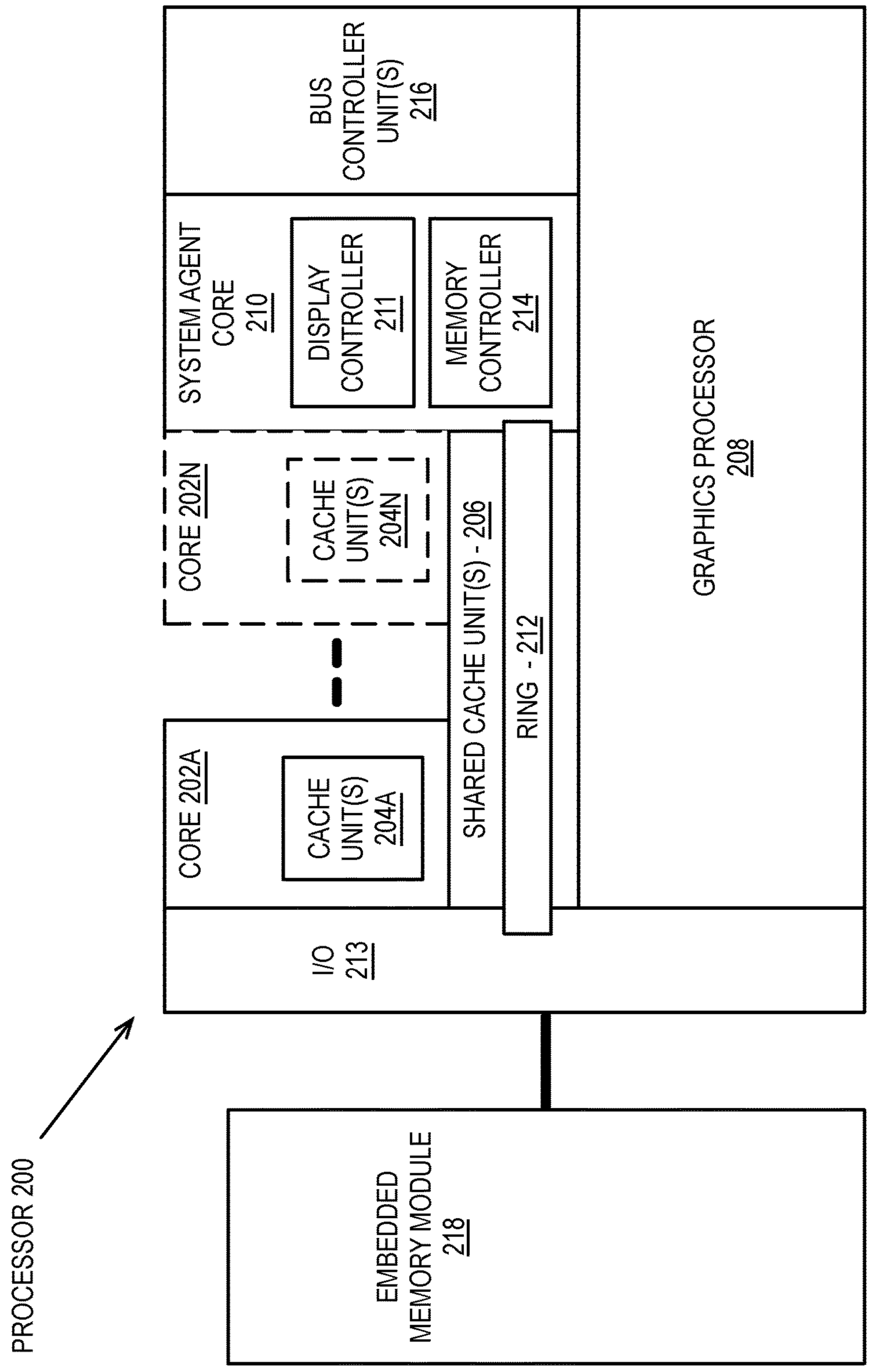

PROCESSOR 200
I/O 213
CORE 202A
CACHE UNIT(S) 204A
CORE 202N
CACHE UNIT(S) 204N
SHARED CACHE UNIT(S) - 206
RING - 212
SYSTEM AGENT CORE 210
DISPLAY CONTROLLER 211
MEMORY CONTROLLER 214
BUS CONTROLLER UNIT(S) 216
GRAPHICS PROCESSOR 208
EMBEDDED MEMORY MODULE 218

FIG. 2A

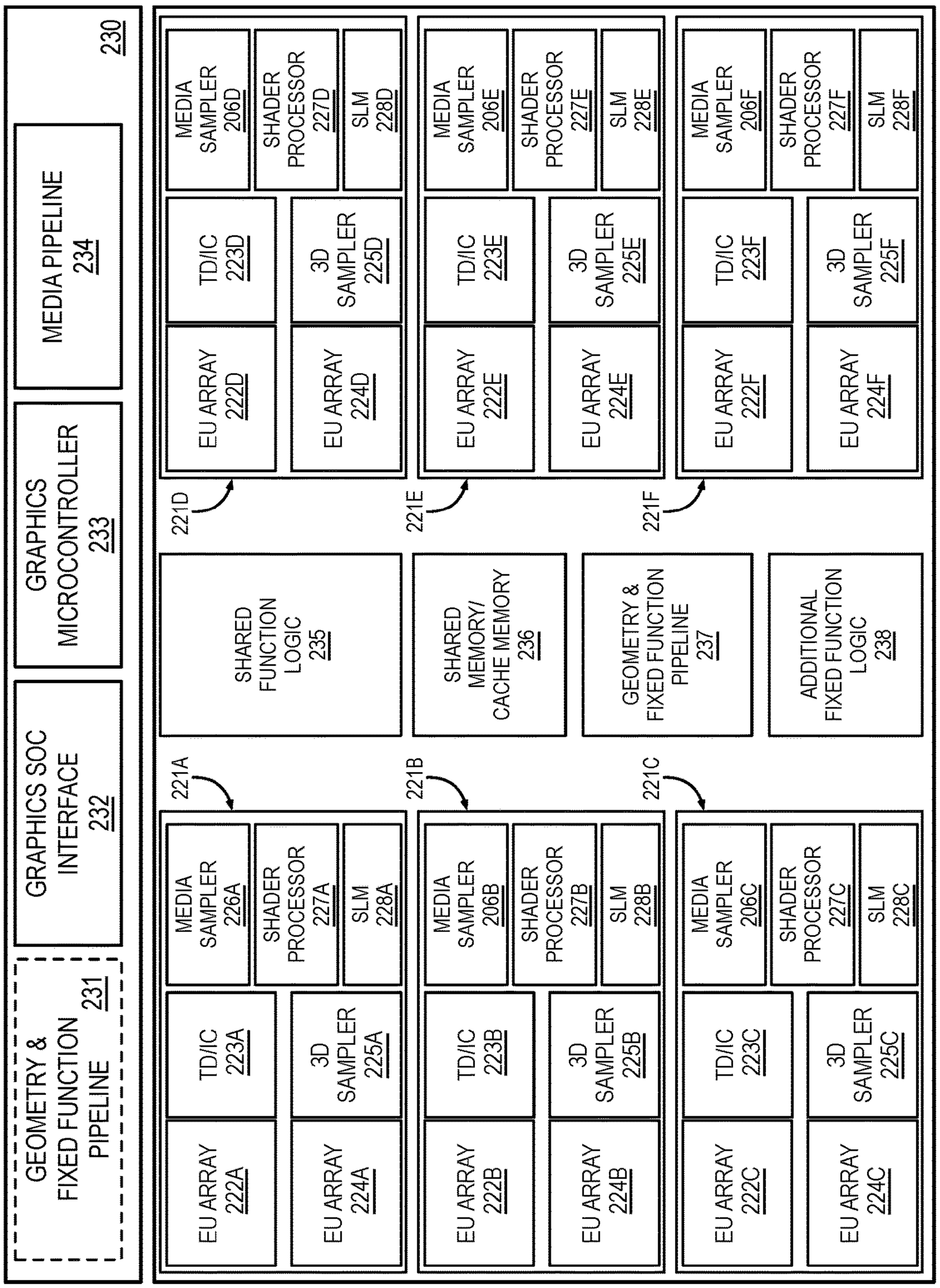

219
GEOMETRY & FIXED FUNCTION PIPELINE 231
GRAPHICS SOC INTERFACE 232
GRAPHICS MICROCONTROLLER 233
MEDIA PIPELINE 234
230
EU ARRAY 222A
TD/IC 223A
3D SAMPLER 225A
MEDIA SAMPLER 226A
SHADER PROCESSOR 227A
SLM 228A
EU ARRAY 224A
EU ARRAY 222B
TD/IC 223B
3D SAMPLER 225B
MEDIA SAMPLER 206B
SHADER PROCESSOR 227B
SLM 228B
EU ARRAY 224B
EU ARRAY 222C
TD/IC 223C
3D SAMPLER 225C
MEDIA SAMPLER 206C
SHADER PROCESSOR 227C
SLM 228C
EU ARRAY 224C
EU ARRAY 222D
TD/IC 223D
3D SAMPLER 225D
MEDIA SAMPLER 206D
SHADER PROCESSOR 227D
SLM 228D
EU ARRAY 224D
EU ARRAY 222E
TD/IC 223E
3D SAMPLER 225E
MEDIA SAMPLER 206E
SHADER PROCESSOR 227E
SLM 228E
EU ARRAY 224E
EU ARRAY 222F
TD/IC 223F
3D SAMPLER 225F
MEDIA SAMPLER 206F
SHADER PROCESSOR 227F
SLM 228F
EU ARRAY 224F
221A
221B
221C
221D
221E
221F
SHARED FUNCTION LOGIC 235
SHARED MEMORY/ CACHE MEMORY 236
GEOMETRY & FIXED FUNCTION PIPELINE 237
ADDITIONAL FIXED FUNCTION LOGIC 238

FIG. 2B

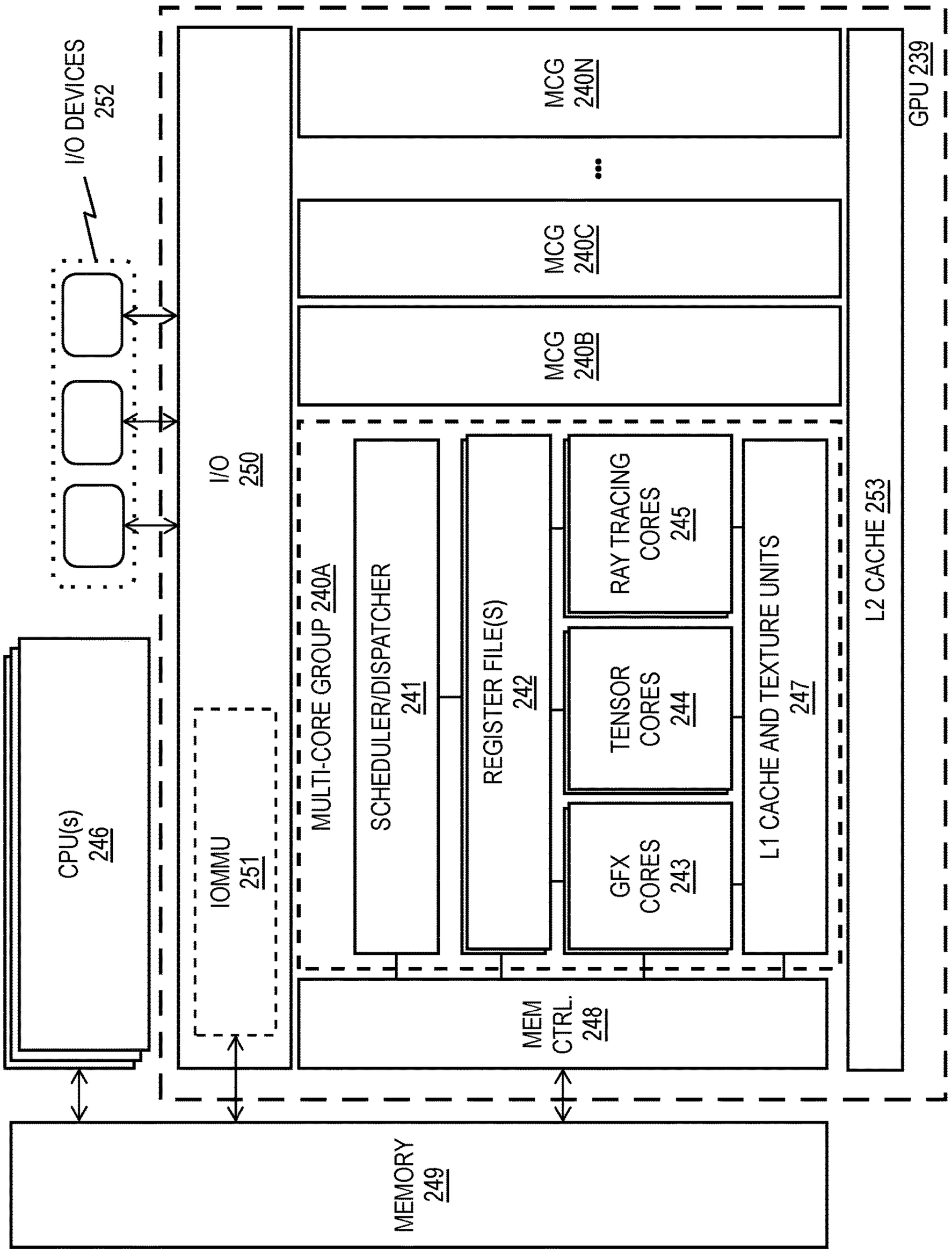

I/O DEVICES 252
GPU 239
MCG 240N
MCG 240C
MCG 240B
I/O 250
CPU(s) 246
IOMMU 251
MULTI-CORE GROUP 240A
SCHEDULER/DISPATCHER 241
REGISTER FILE(S) 242
RAY TRACING CORES 245
TENSOR CORES 244
GFX CORES 243
L1 CACHE AND TEXTURE UNITS 247
L2 CACHE 253
MEM CTRL. 248
MEMORY 249

FIG. 2C

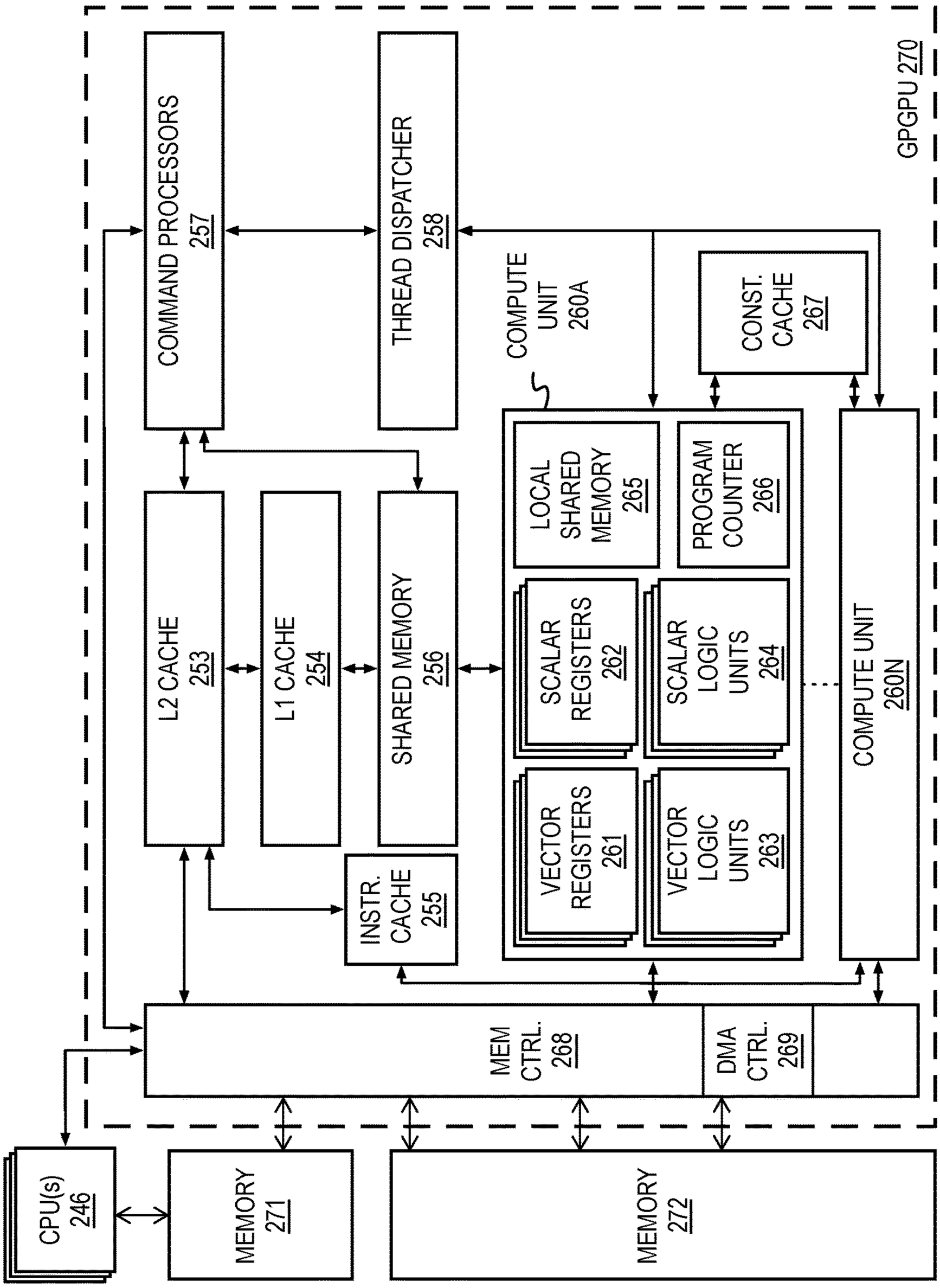

GPGPU 270
COMMAND PROCESSORS 257
THREAD DISPATCHER 258
COMPUTE UNIT 260A
L2 CACHE 253
L1 CACHE 254
SHARED MEMORY 256
INSTR. CACHE 255
LOCAL SHARED MEMORY 265
PROGRAM COUNTER 266
CONST. CACHE 267
SCALAR REGISTERS 262
SCALAR LOGIC UNITS 264
VECTOR REGISTERS 261
VECTOR LOGIC UNITS 263
COMPUTE UNIT 260N
MEM CTRL. 268
DMA CTRL. 269
CPU(s) 246
MEMORY 271
MEMORY 272

FIG. 2D

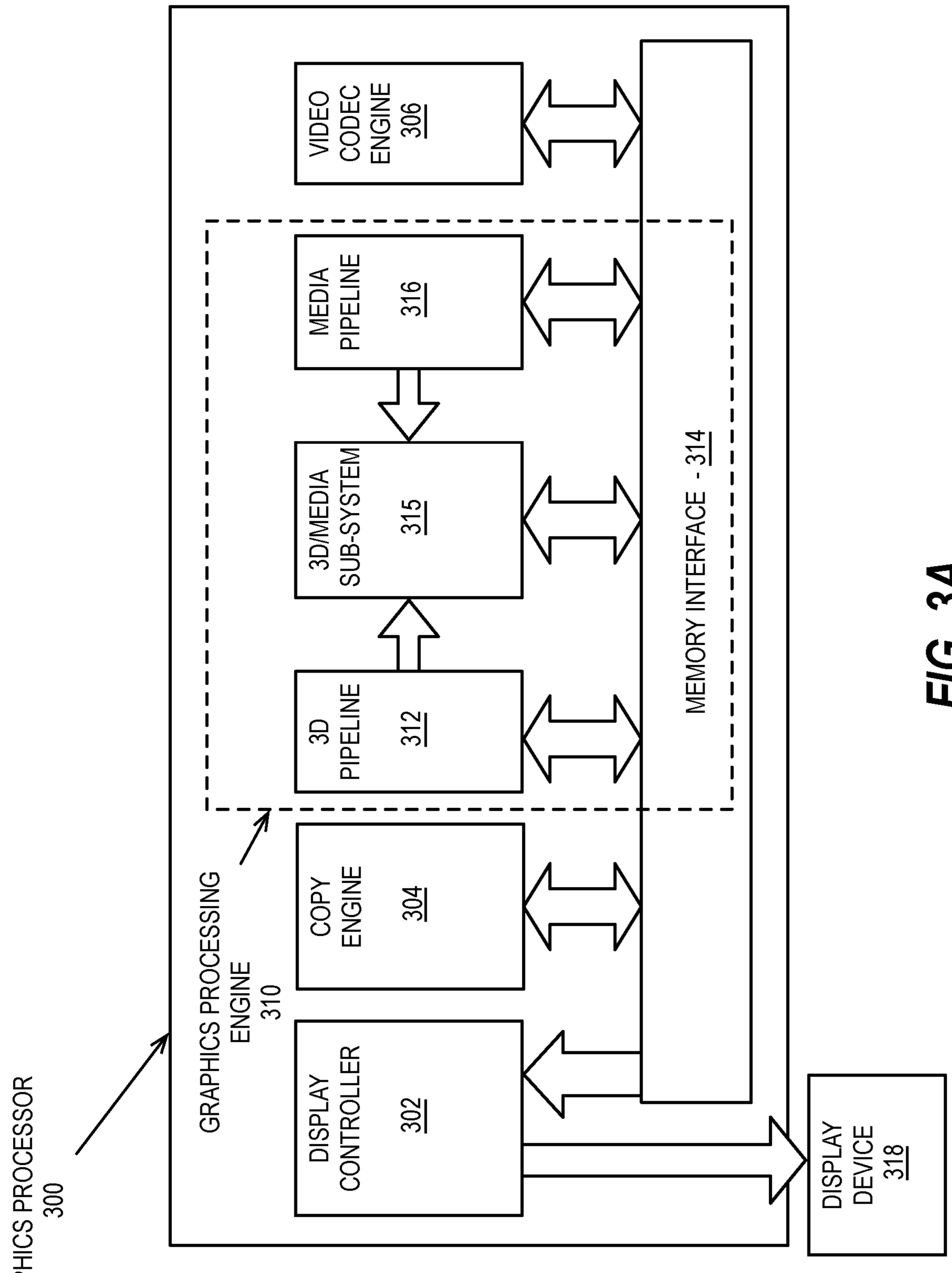

GRAPHICS PROCESSOR
300
GRAPHICS PROCESSING ENGINE
310
VIDEO CODEC ENGINE
306
MEDIA PIPELINE
316
3D/MEDIA SUB-SYSTEM
315
3D PIPELINE
312
COPY ENGINE
304
DISPLAY CONTROLLER
302
MEMORY INTERFACE - 314
DISPLAY DEVICE
318

FIG. 3A

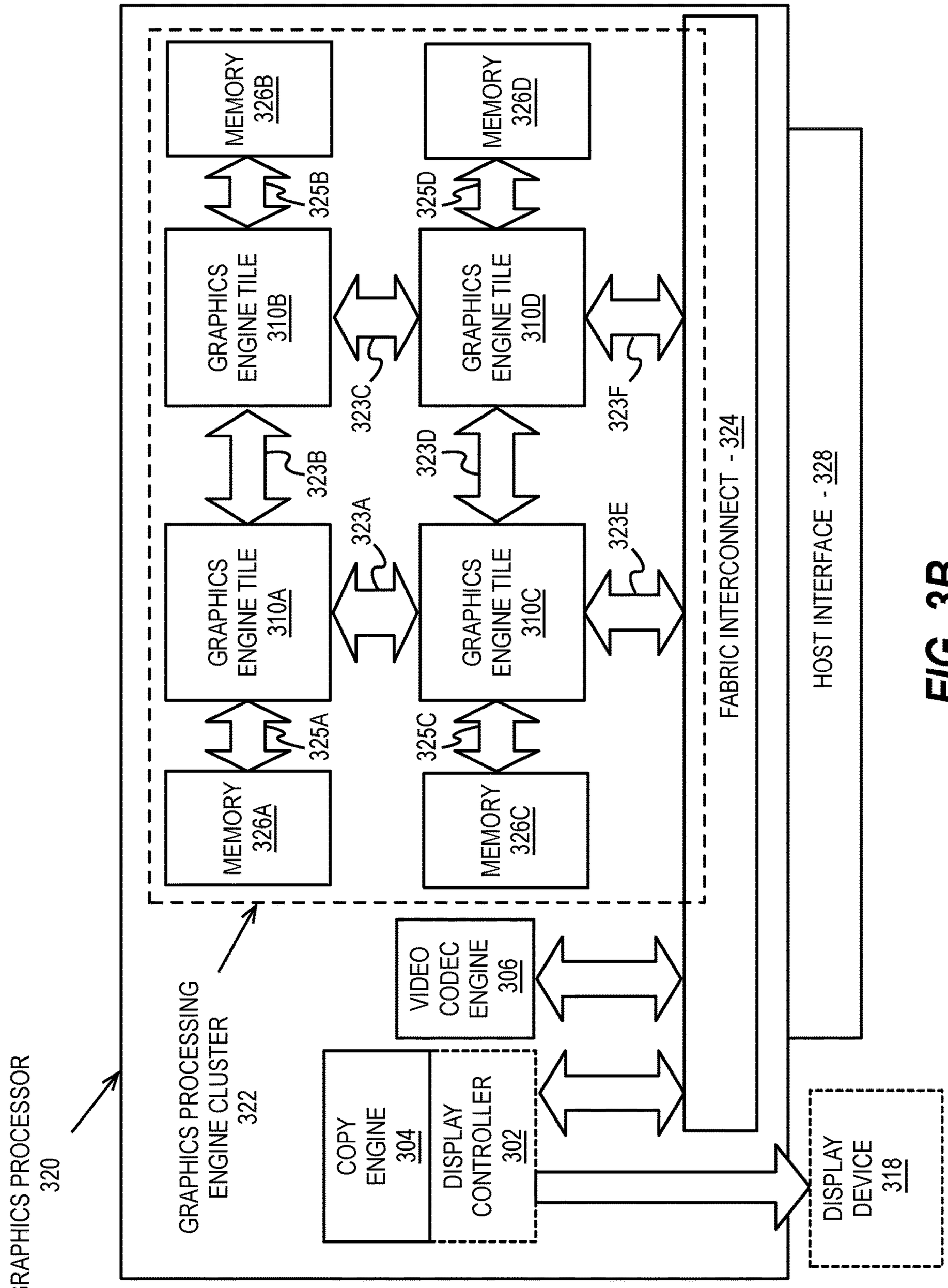

GRAPHICS PROCESSOR 320
GRAPHICS PROCESSING ENGINE CLUSTER 322
GRAPHICS ENGINE TILE 310A
GRAPHICS ENGINE TILE 310B
GRAPHICS ENGINE TILE 310C
GRAPHICS ENGINE TILE 310D
MEMORY 326A
MEMORY 326B
MEMORY 326C
MEMORY 326D
325A
325B
325C
325D
323A
323B
323C
323D
323E
323F
FABRIC INTERCONNECT - 324
HOST INTERFACE - 328
VIDEO CODEC ENGINE 306
COPY ENGINE 304
DISPLAY CONTROLLER 302
DISPLAY DEVICE 318

FIG. 3B

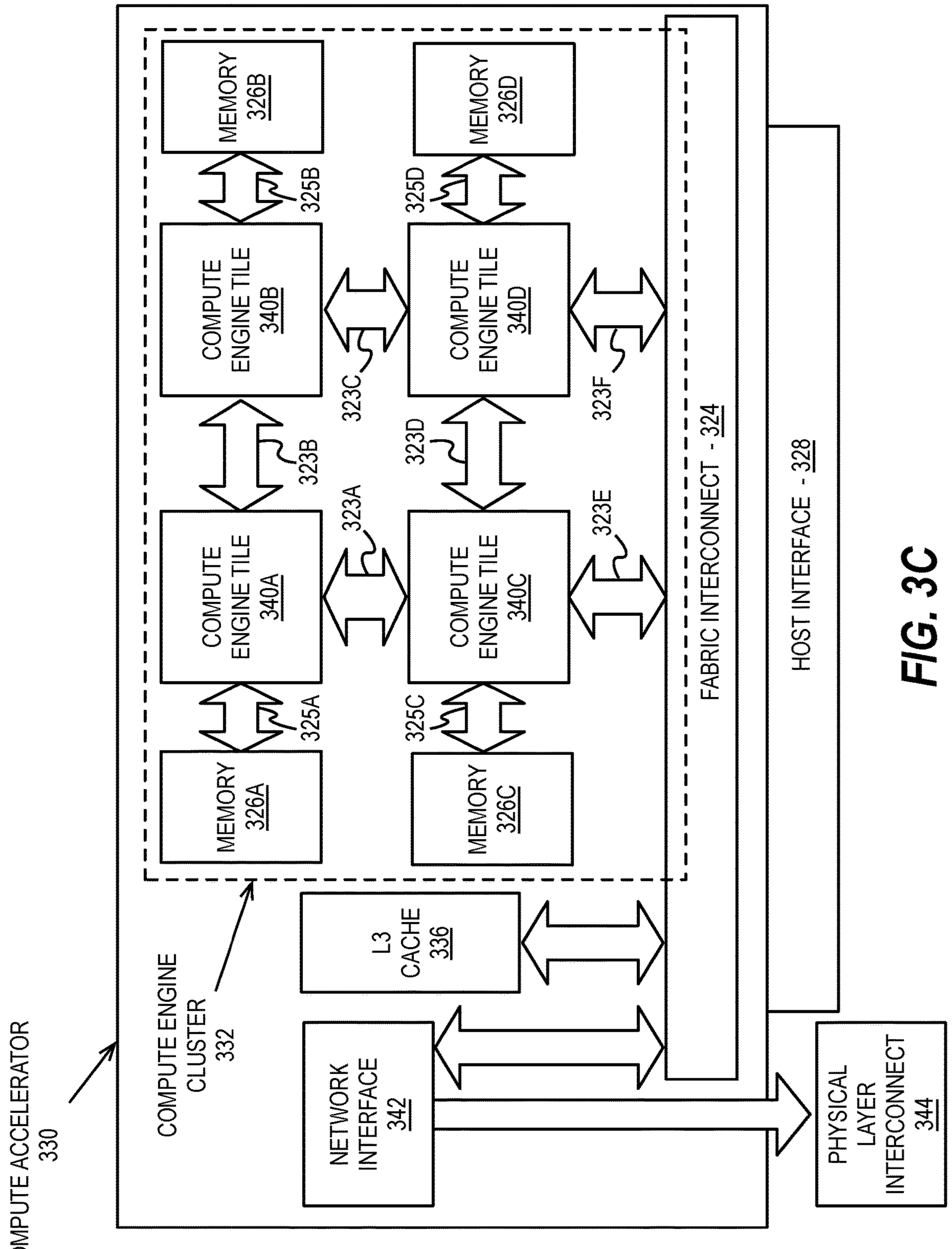

COMPUTE ACCELERATOR 330
COMPUTE ENGINE CLUSTER 332
COMPUTE ENGINE TILE 340A
COMPUTE ENGINE TILE 340B
COMPUTE ENGINE TILE 340C
COMPUTE ENGINE TILE 340D
MEMORY 326A
MEMORY 326B
MEMORY 326C
MEMORY 326D
325A
325B
325C
325D
323A
323B
323C
323D
323E
323F
L3 CACHE 336
NETWORK INTERFACE 342
PHYSICAL LAYER INTERCONNECT 344
FABRIC INTERCONNECT - 324
HOST INTERFACE - 328

FIG. 3C

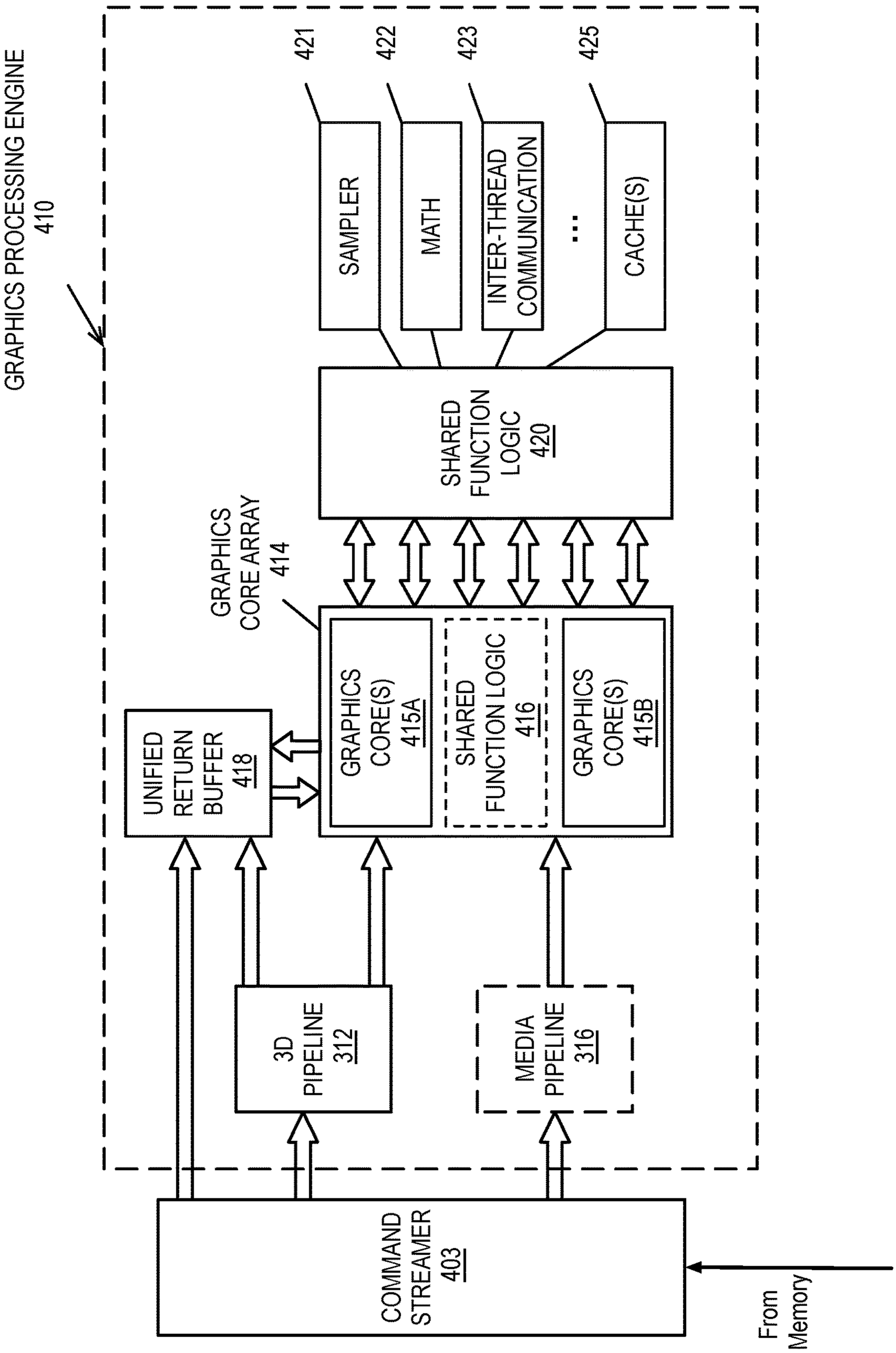

GRAPHICS PROCESSING ENGINE
410
421
422
423
425
SAMPLER
MATH
INTER-THREAD COMMUNICATION
...
CACHE(S)
SHARED FUNCTION LOGIC
420
GRAPHICS CORE ARRAY
414
UNIFIED RETURN BUFFER
418
GRAPHICS CORE(S)
415A
SHARED FUNCTION LOGIC
416
GRAPHICS CORE(S)
415B
3D PIPELINE
312
MEDIA PIPELINE
316
COMMAND STREAMER
403
From Memory

FIG. 4

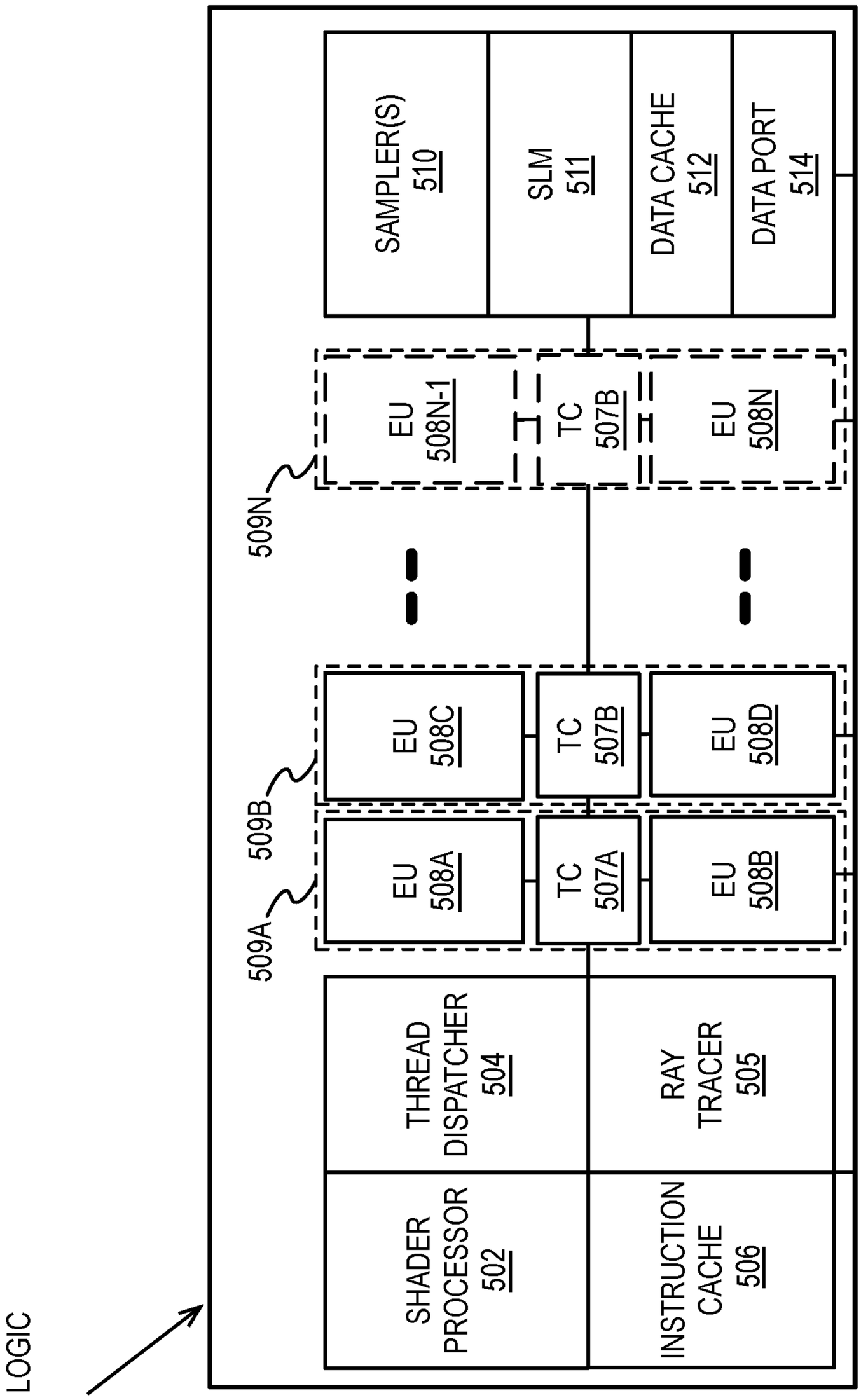

EXECUTION LOGIC
500
SHADER PROCESSOR
502
THREAD DISPATCHER
504
INSTRUCTION CACHE
506
RAY TRACER
505
509A
509B
509N
EU
508A
TC
507A
EU
508B
EU
508C
TC
507B
EU
508D
EU
508N-1
TC
507B
EU
508N
SAMPLER(S)
510
SLM
511
DATA CACHE
512
DATA PORT
514

FIG. 5A

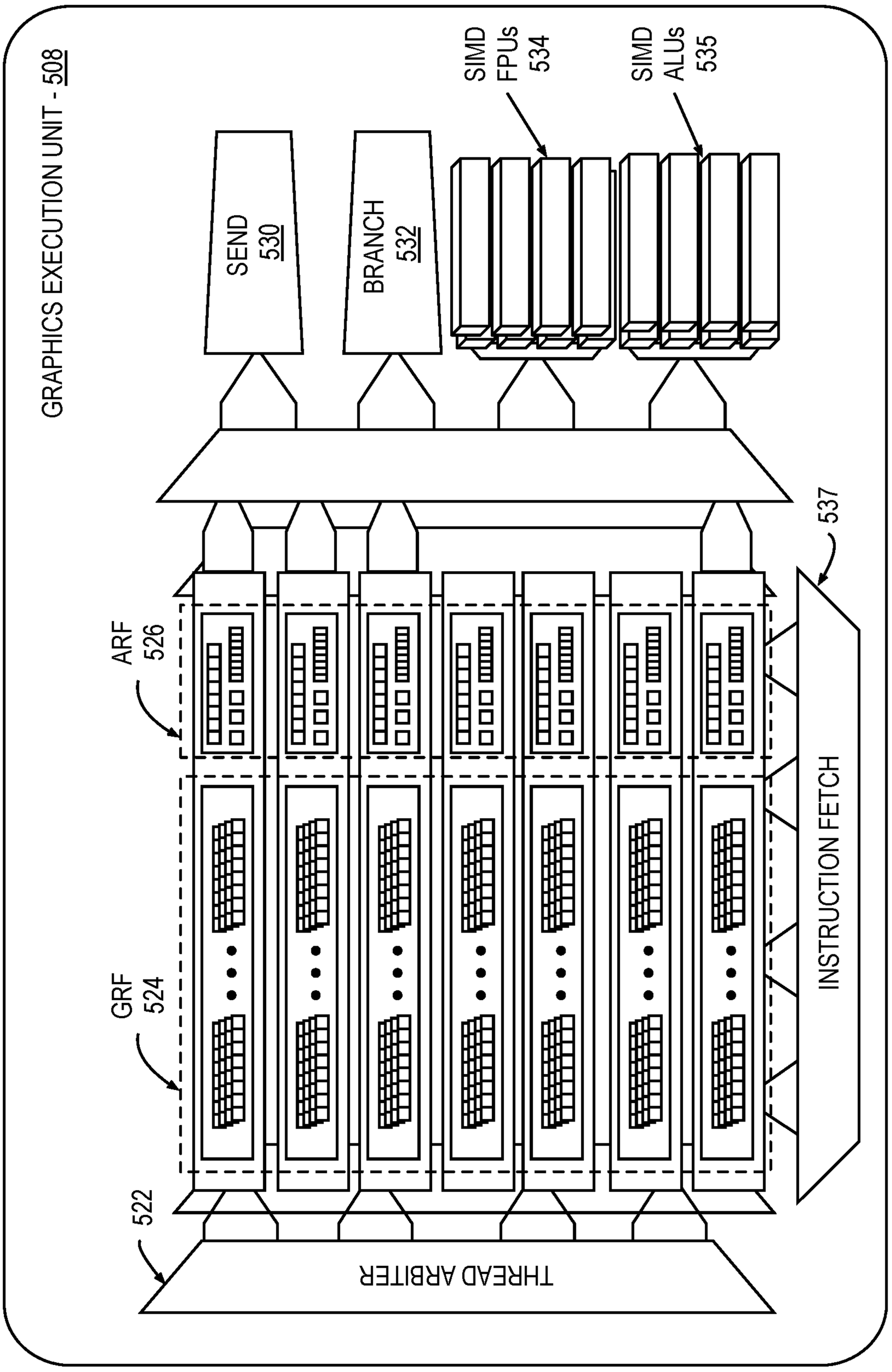

GRAPHICS EXECUTION UNIT - 508
SEND 530
BRANCH 532
SIMD FPUs 534
SIMD ALUs 535
ARF 526
GRF 524
537
INSTRUCTION FETCH
522
THREAD ARBITER

FIG. 5B

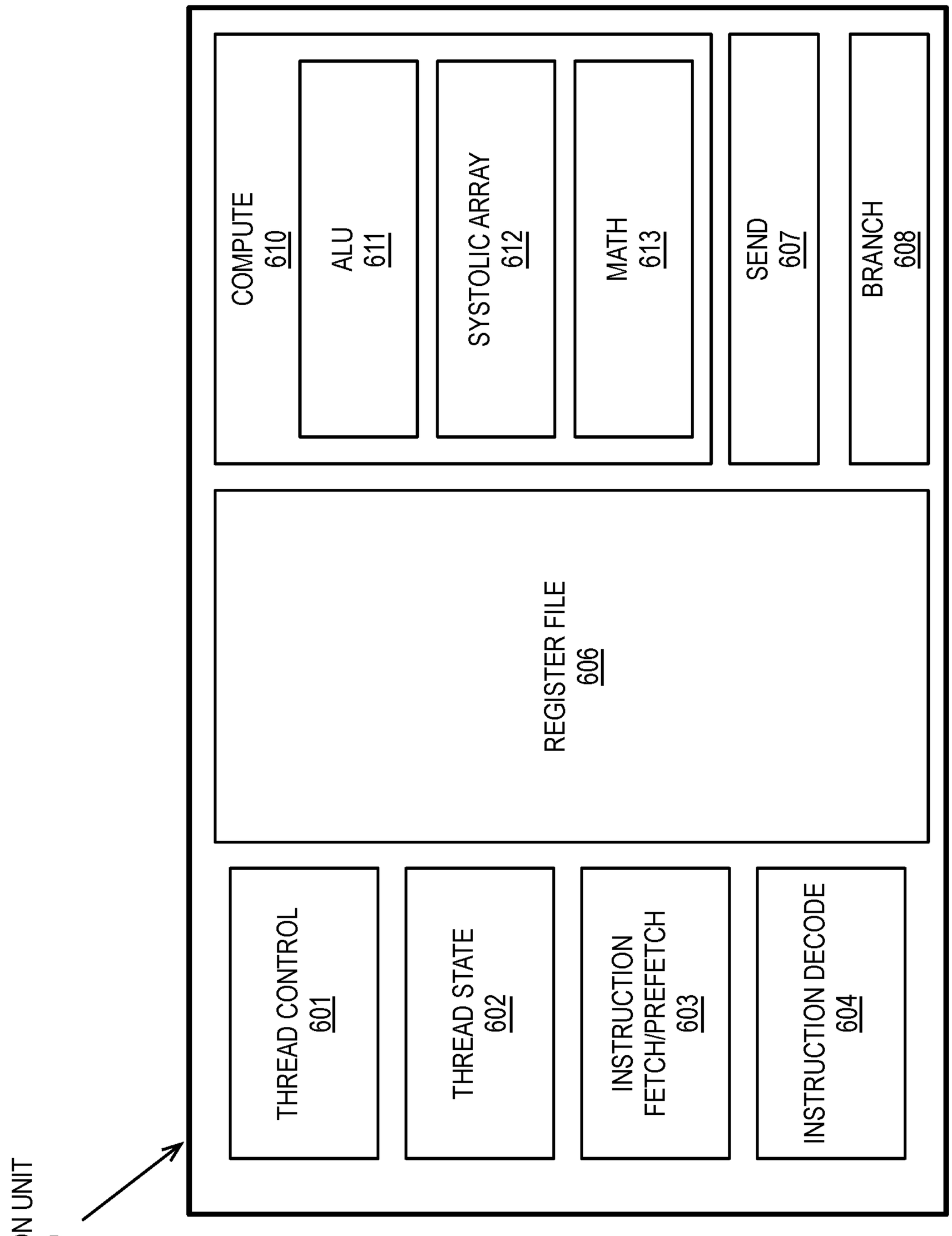

EXECUTION UNIT
600
THREAD CONTROL
601
THREAD STATE
602
INSTRUCTION
FETCH/PREFETCH
603
INSTRUCTION DECODE
604
REGISTER FILE
606
COMPUTE
610
ALU
611
SYSTOLIC ARRAY
612
MATH
613
SEND
607
BRANCH
608

FIG. 6

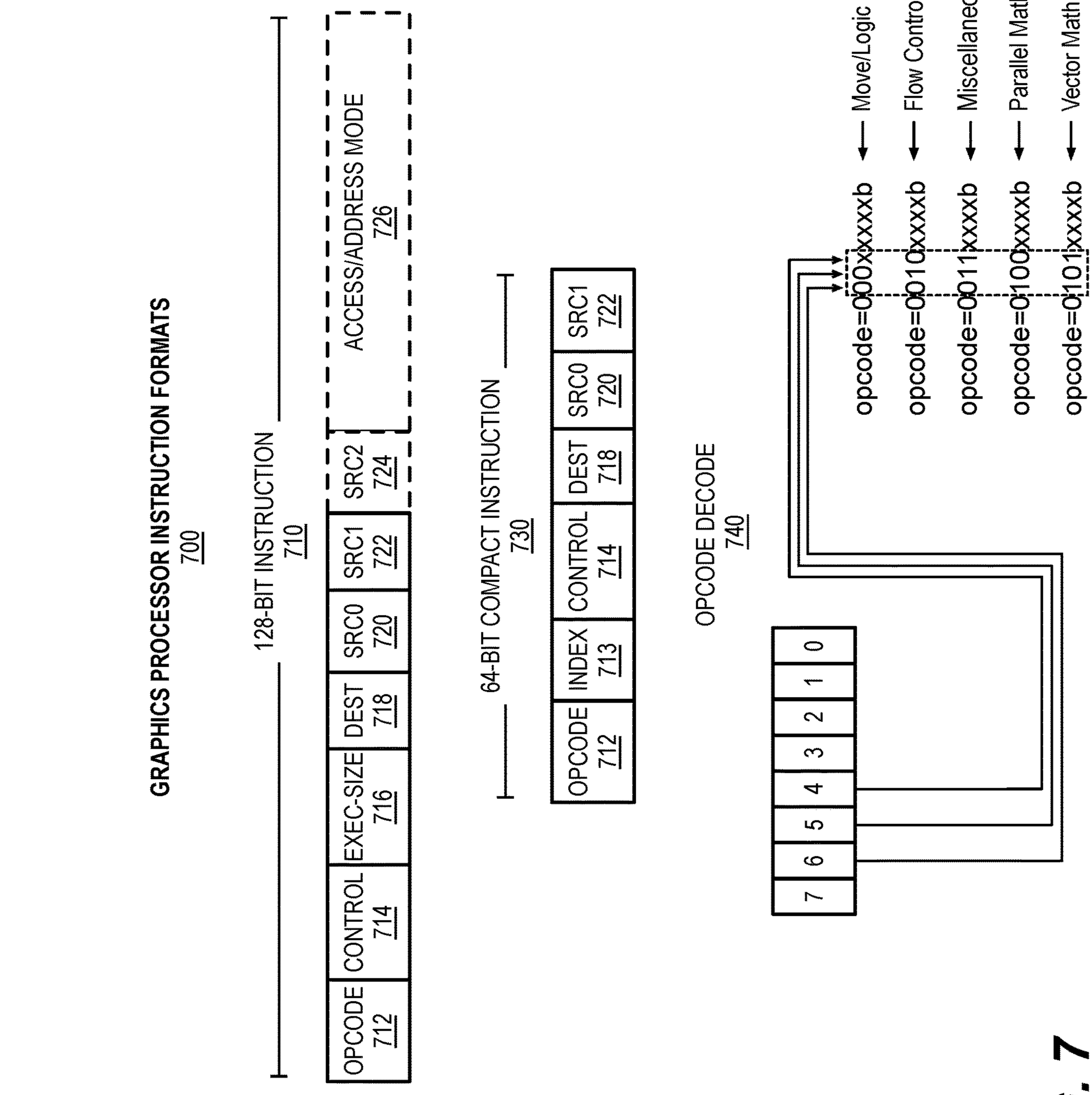

GRAPHICS PROCESSOR INSTRUCTION FORMATS
700
128-BIT INSTRUCTION
710
OPCODE 712
CONTROL 714
EXEC-SIZE 716
DEST 718
SRC0 720
SRC1 722
SRC2 724
ACCESS/ADDRESS MODE
726
64-BIT COMPACT INSTRUCTION
730
OPCODE 712
INDEX 713
CONTROL 714
DEST 718
SRC0 720
SRC1 722
OPCODE DECODE
740
0
1
2
3
4
5
6
7
opcode=0000xxxxb
opcode=0001xxxxb
opcode=0011xxxxb
opcode=0100xxxxb
opcode=0101xxxxb
Move/Logic - 742
Flow Control - 744
Miscellaneous - 746
Parallel Math - 748
Vector Math - 750

FIG. 7

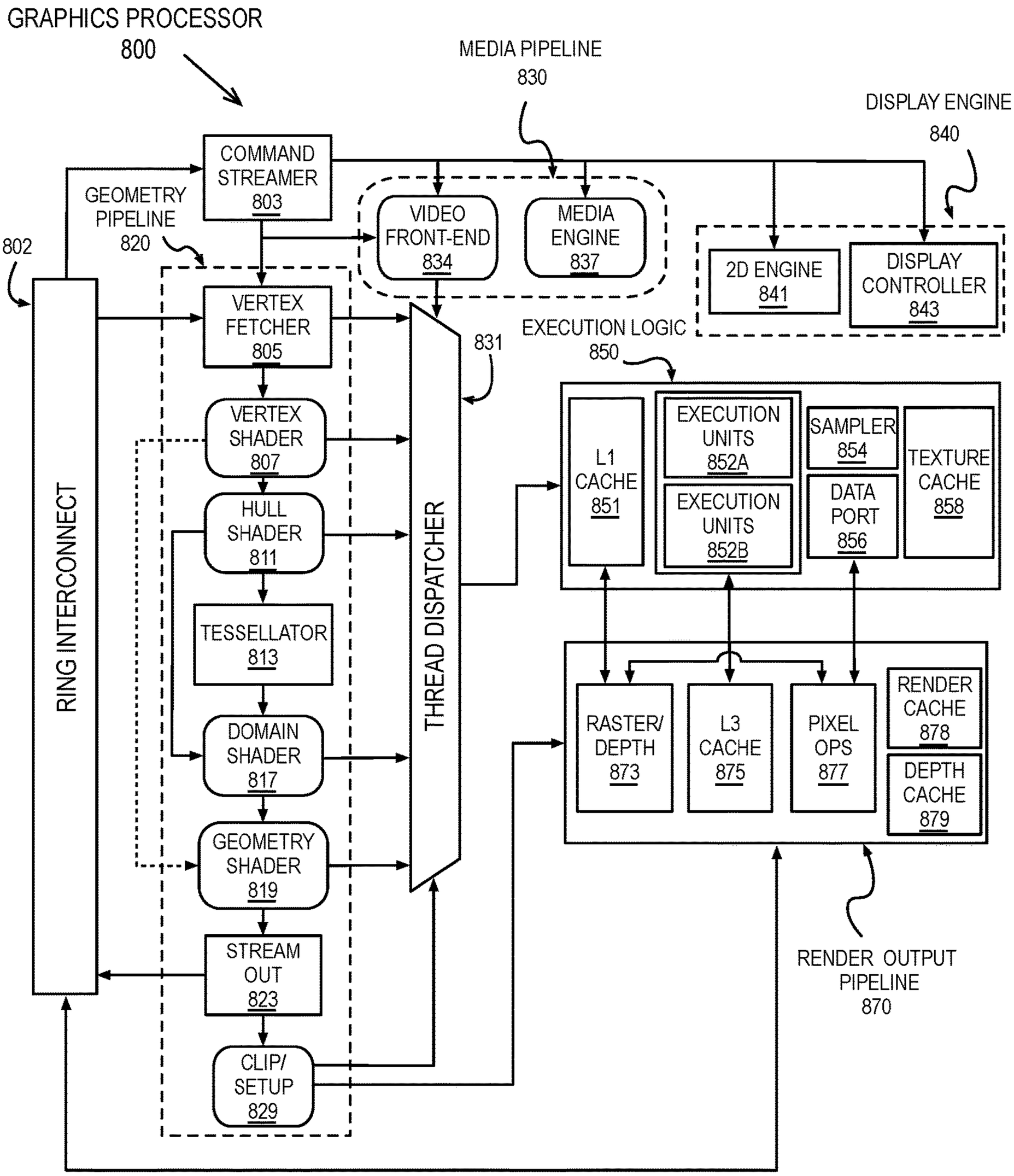

GRAPHICS PROCESSOR
800
MEDIA PIPELINE
830
DISPLAY ENGINE
840
COMMAND STREAMER
803
GEOMETRY PIPELINE
820
802
VIDEO FRONT-END
834
MEDIA ENGINE
837
2D ENGINE
841
DISPLAY CONTROLLER
843
VERTEX FETCHER
805
831
EXECUTION LOGIC
850
VERTEX SHADER
807
HULL SHADER
811
TESSELLATOR
813
DOMAIN SHADER
817
GEOMETRY SHADER
819
STREAM OUT
823
CLIP/ SETUP
829
RING INTERCONNECT
THREAD DISPATCHER
L1 CACHE
851
EXECUTION UNITS
852A
EXECUTION UNITS
852B
SAMPLER
854
DATA PORT
856
TEXTURE CACHE
858
RASTER/ DEPTH
873
L3 CACHE
875
PIXEL OPS
877
RENDER CACHE
878
DEPTH CACHE
879
RENDER OUTPUT PIPELINE
870

FIG. 8

FIG. 9A GRAPHICS PROCESSOR COMMAND FORMAT

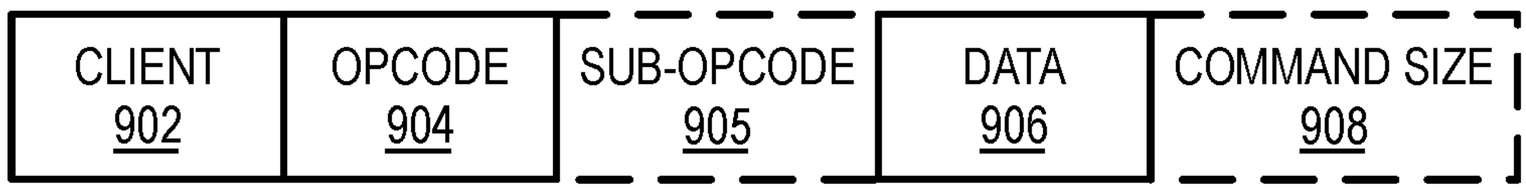
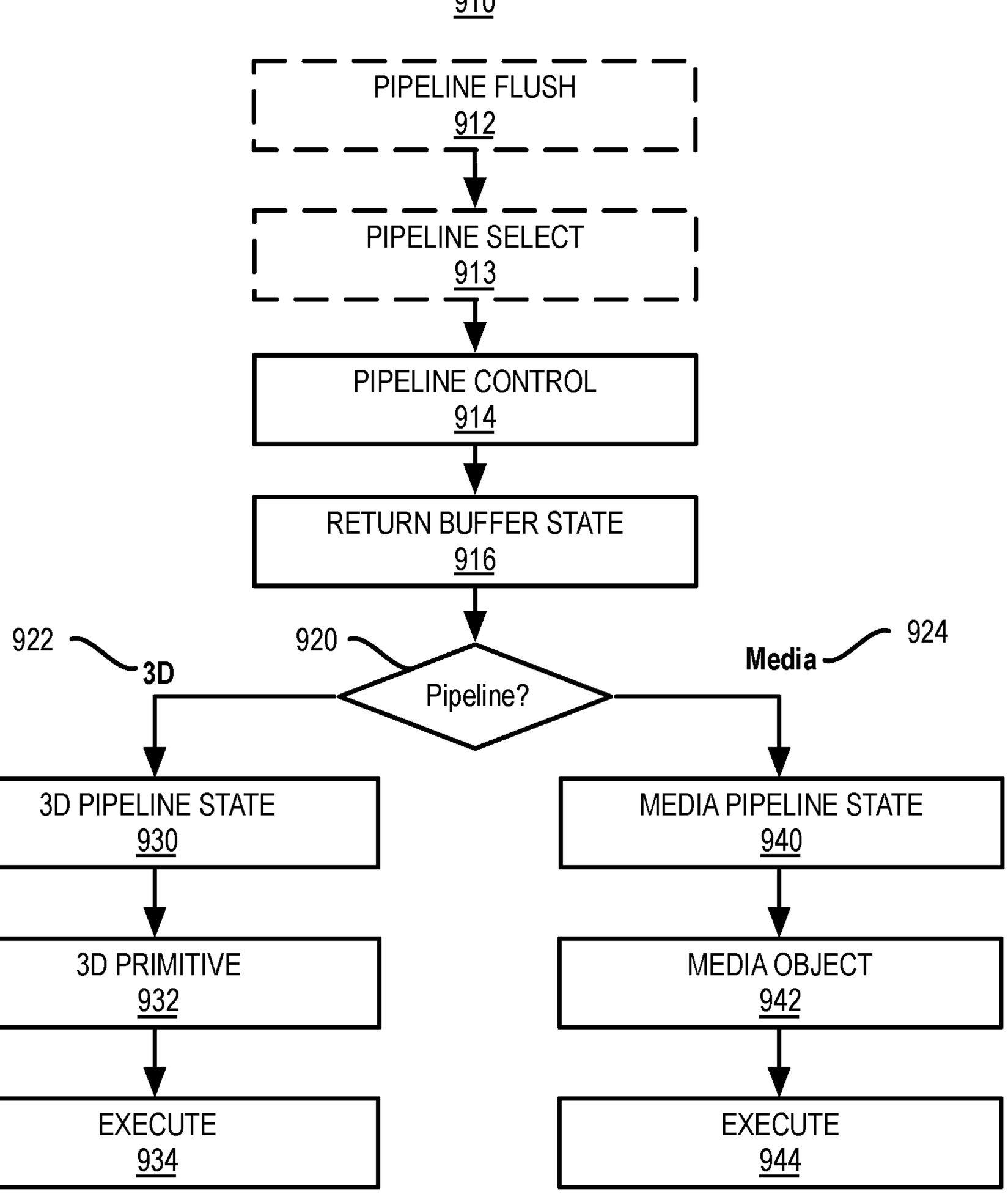


FIG. 9B GRAPHICS PROCESSOR COMMAND SEQUENCE



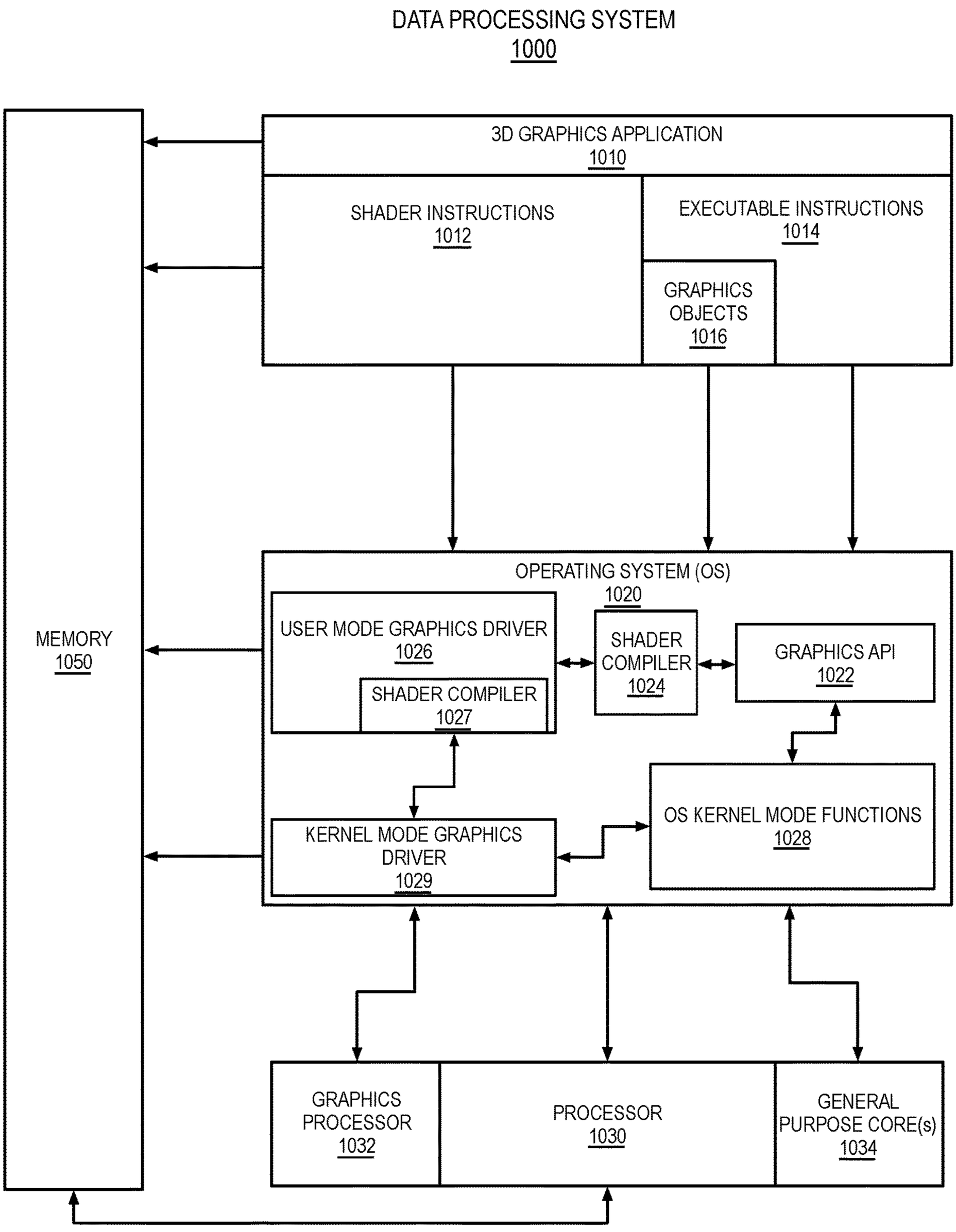

DATA PROCESSING SYSTEM
1000
3D GRAPHICS APPLICATION
1010
SHADER INSTRUCTIONS
1012
EXECUTABLE INSTRUCTIONS
1014
GRAPHICS OBJECTS
1016
MEMORY
1050
OPERATING SYSTEM (OS)
1020
USER MODE GRAPHICS DRIVER
1026
SHADER COMPILER
1027
SHADER COMPILER
1024
GRAPHICS API
1022
KERNEL MODE GRAPHICS DRIVER
1029
OS KERNEL MODE FUNCTIONS
1028
GRAPHICS PROCESSOR
1032
PROCESSOR
1030
GENERAL PURPOSE CORE(s)
1034

FIG. 10

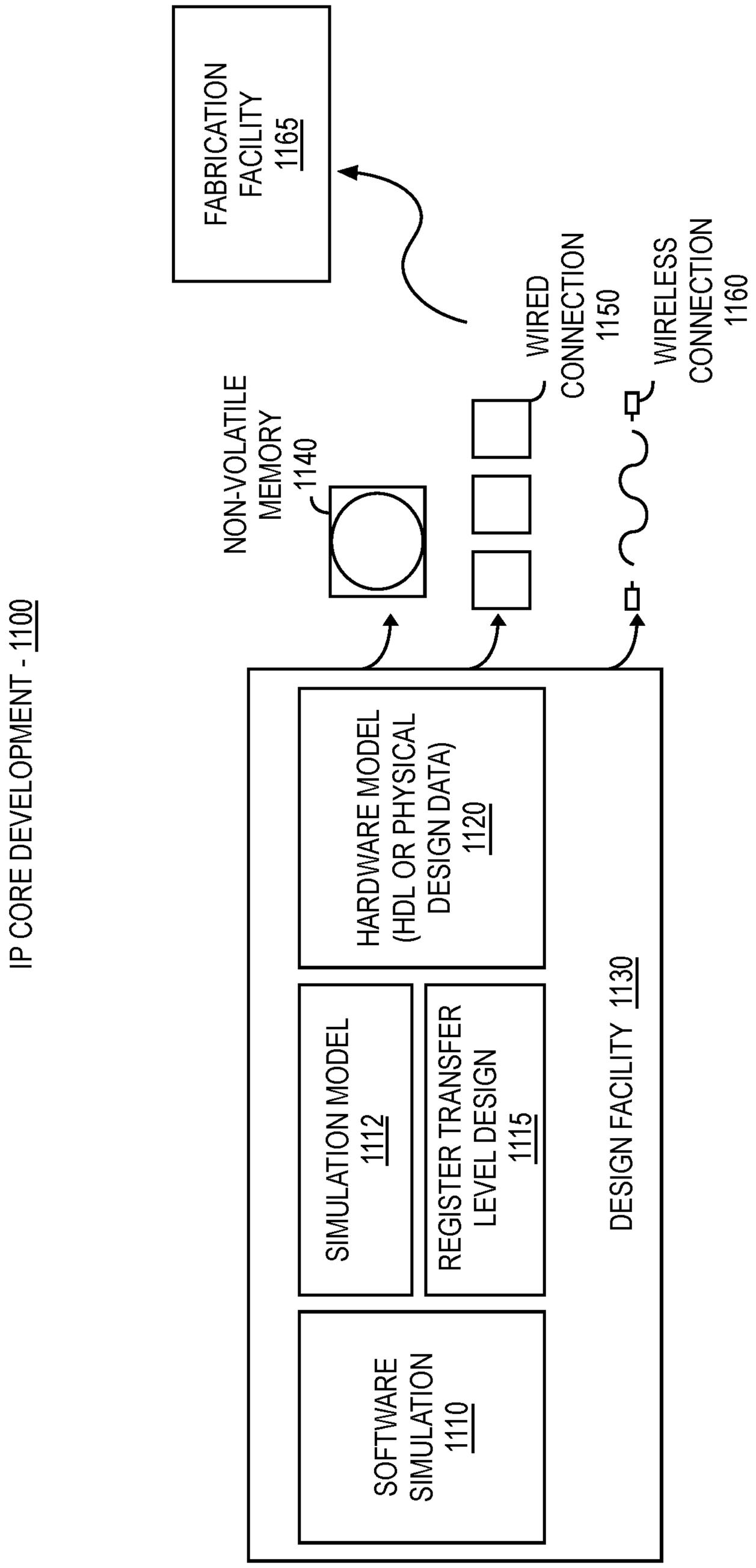

IP CORE DEVELOPMENT - 1100
FABRICATION FACILITY 1165
NON-VOLATILE MEMORY 1140
WIRED CONNECTION 1150
WIRELESS CONNECTION 1160
HARDWARE MODEL (HDL OR PHYSICAL DESIGN DATA) 1120
SIMULATION MODEL 1112
REGISTER TRANSFER LEVEL DESIGN 1115
SOFTWARE SIMULATION 1110
DESIGN FACILITY 1130

FIG. 11A

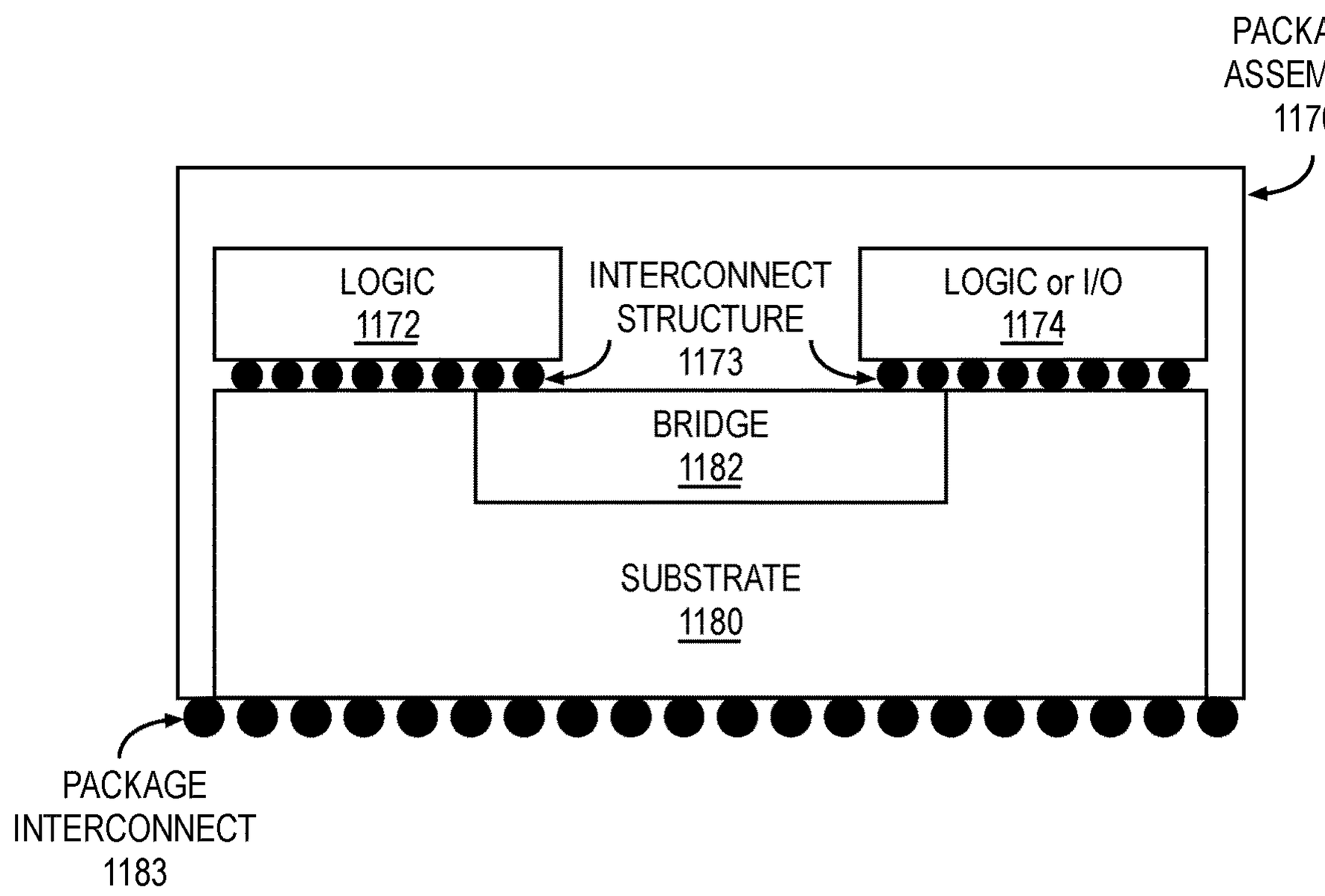

PACKAGE
ASSEMBLY
1170
LOGIC
1172
INTERCONNECT
STRUCTURE
1173
LOGIC or I/O
1174
BRIDGE
1182
SUBSTRATE
1180
PACKAGE
INTERCONNECT
1183

FIG. 11B

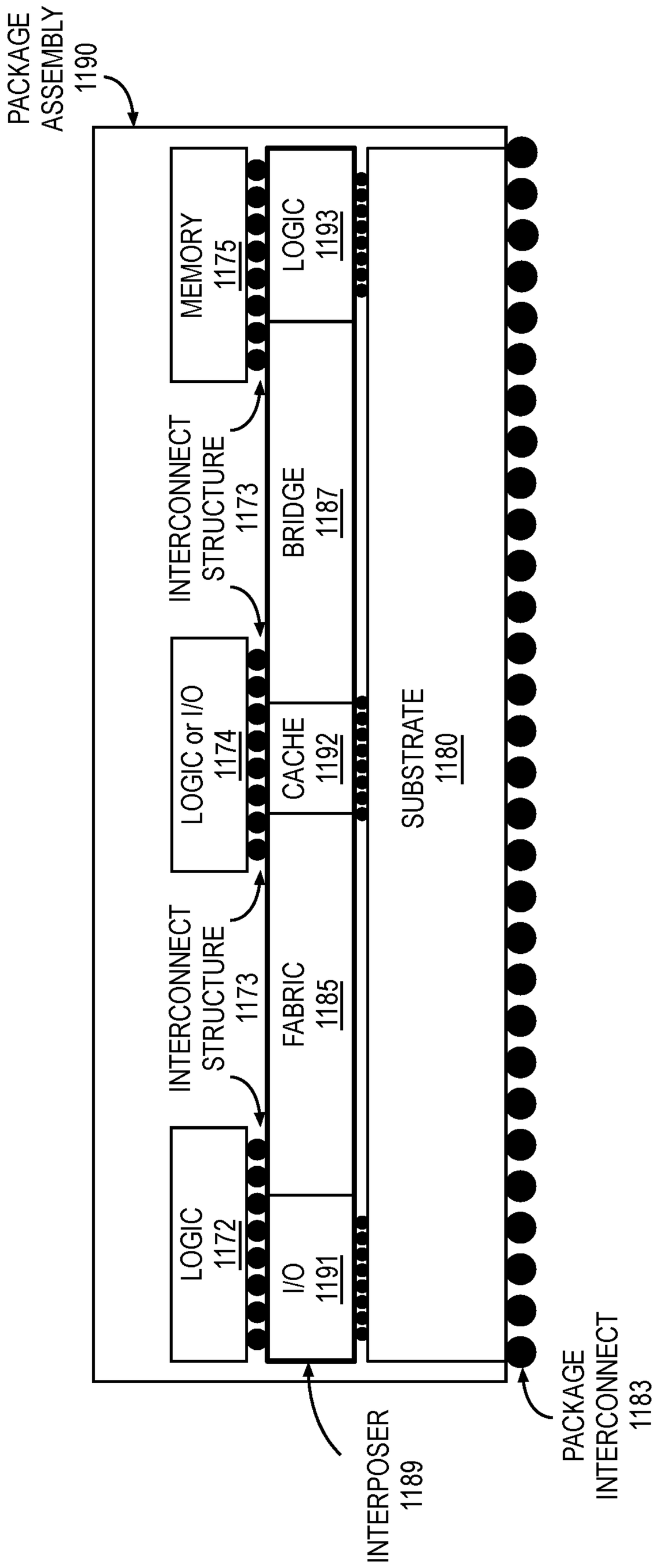

PACKAGE ASSEMBLY 1190
MEMORY 1175
LOGIC 1193
INTERCONNECT STRUCTURE 1173
BRIDGE 1187
LOGIC or I/O 1174
CACHE 1192
INTERCONNECT STRUCTURE 1173
FABRIC 1185
SUBSTRATE 1180
LOGIC 1172
I/O 1191
INTERPOSER 1189
PACKAGE INTERCONNECT 1183

FIG. 11C

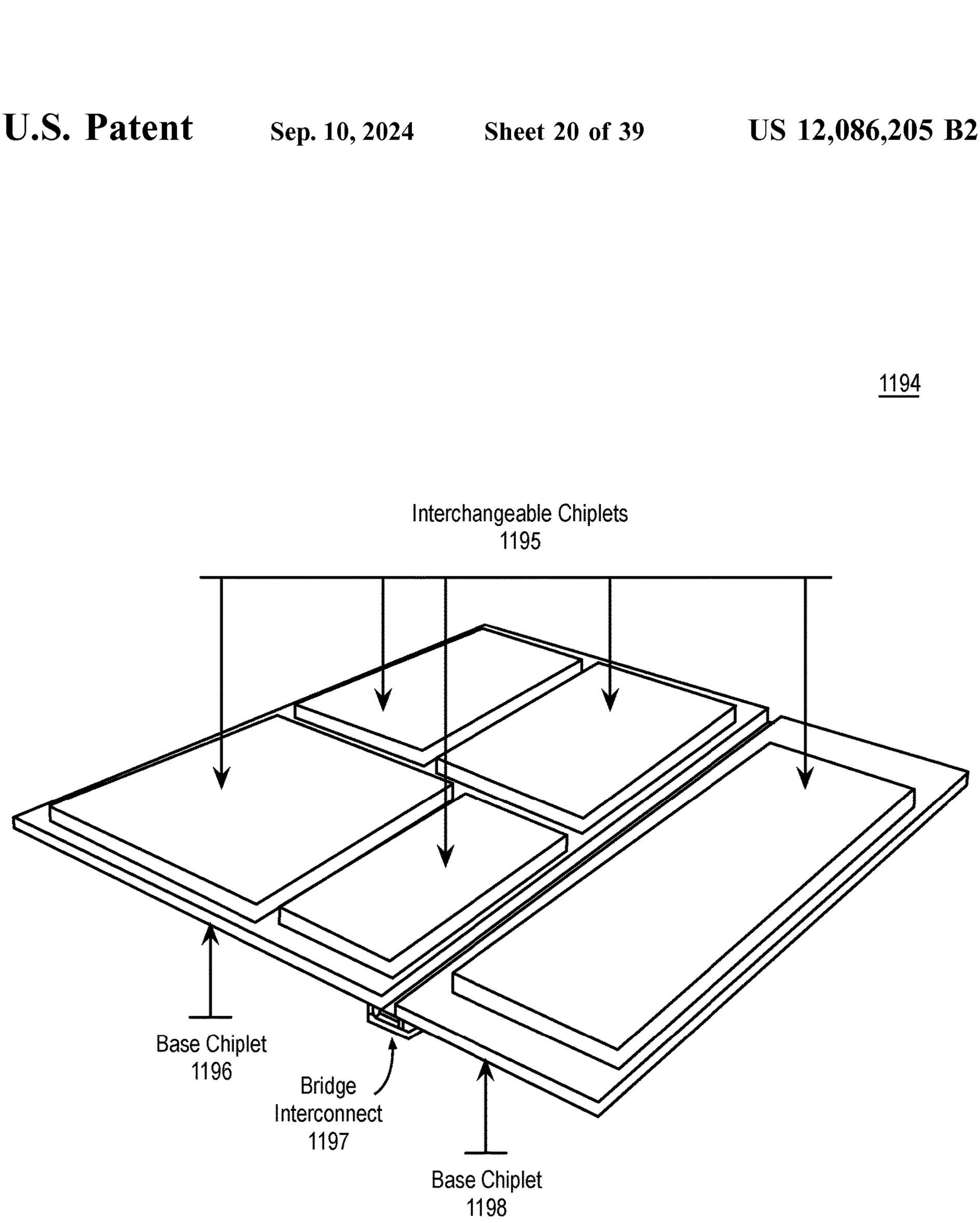

1194
Interchangeable Chiplets
1195
Base Chiplet
1196
Bridge
Interconnect
1197
Base Chiplet
1198

FIG. 11D

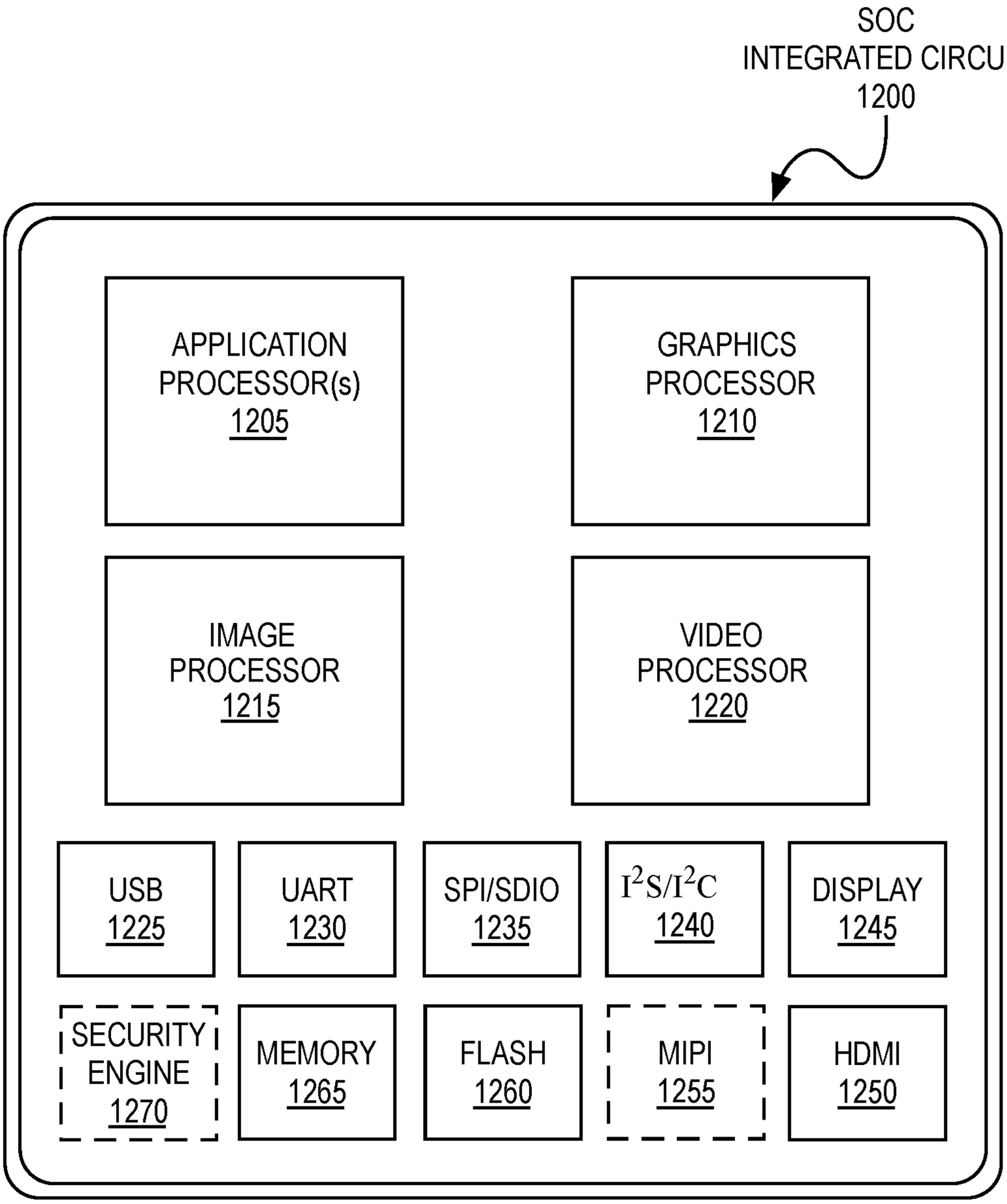

SOC
INTEGRATED CIRCUIT
1200
APPLICATION
PROCESSOR(s)
1205
GRAPHICS
PROCESSOR
1210
IMAGE
PROCESSOR
1215
VIDEO
PROCESSOR
1220
USB
1225
UART
1230
SPI/SDIO
1235
I2S/I2C
1240
DISPLAY
1245
SECURITY
ENGINE
1270
MEMORY
1265
FLASH
1260
MIPI
1255
HDMI
1250

FIG. 12

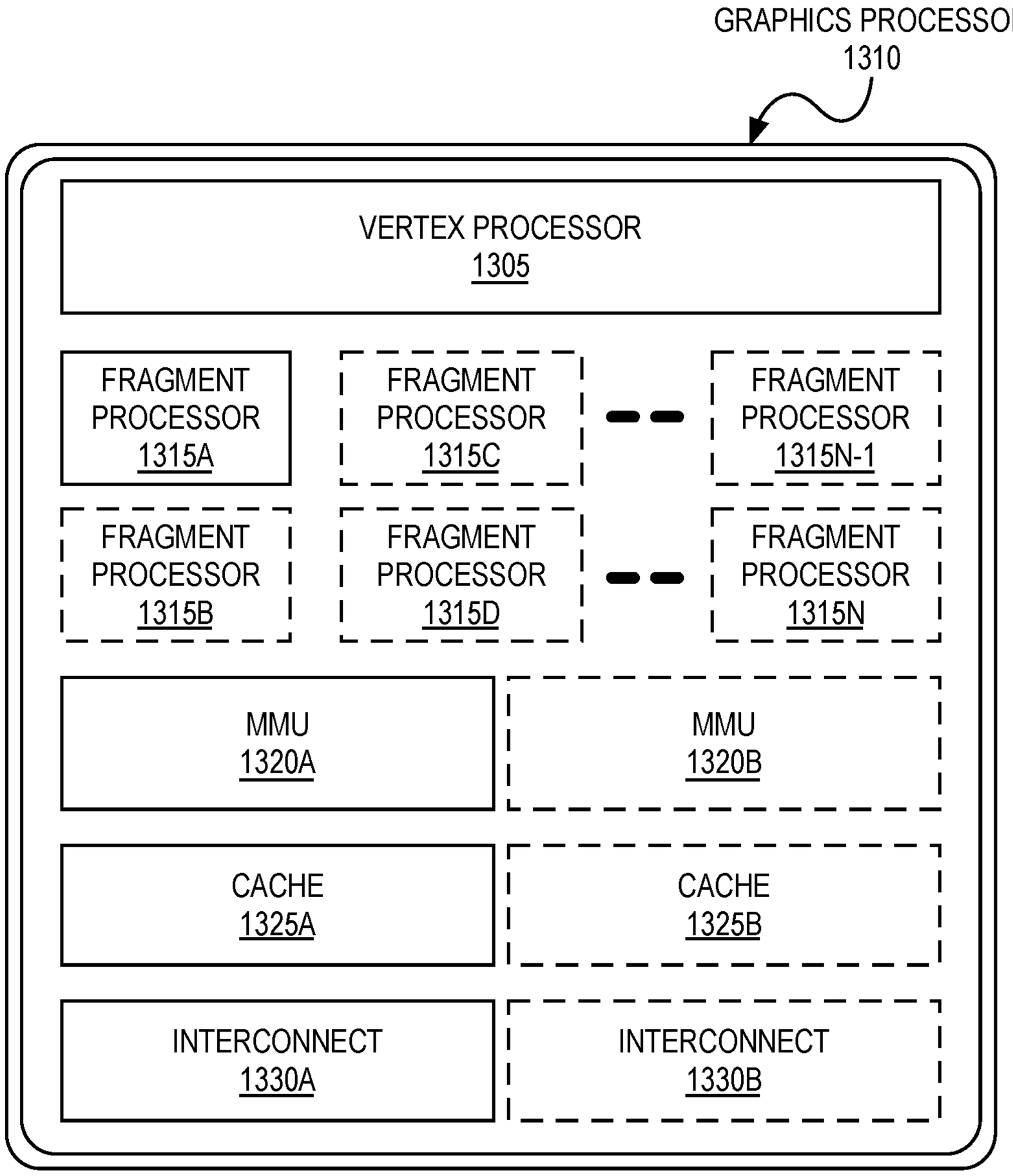

GRAPHICS PROCESSOR
1310
VERTEX PROCESSOR
1305
FRAGMENT PROCESSOR
1315A
FRAGMENT PROCESSOR
1315C
FRAGMENT PROCESSOR
1315N-1
FRAGMENT PROCESSOR
1315B
FRAGMENT PROCESSOR
1315D
FRAGMENT PROCESSOR
1315N
MMU
1320A
MMU
1320B
CACHE
1325A
CACHE
1325B
INTERCONNECT
1330A
INTERCONNECT
1330B

FIG. 13A

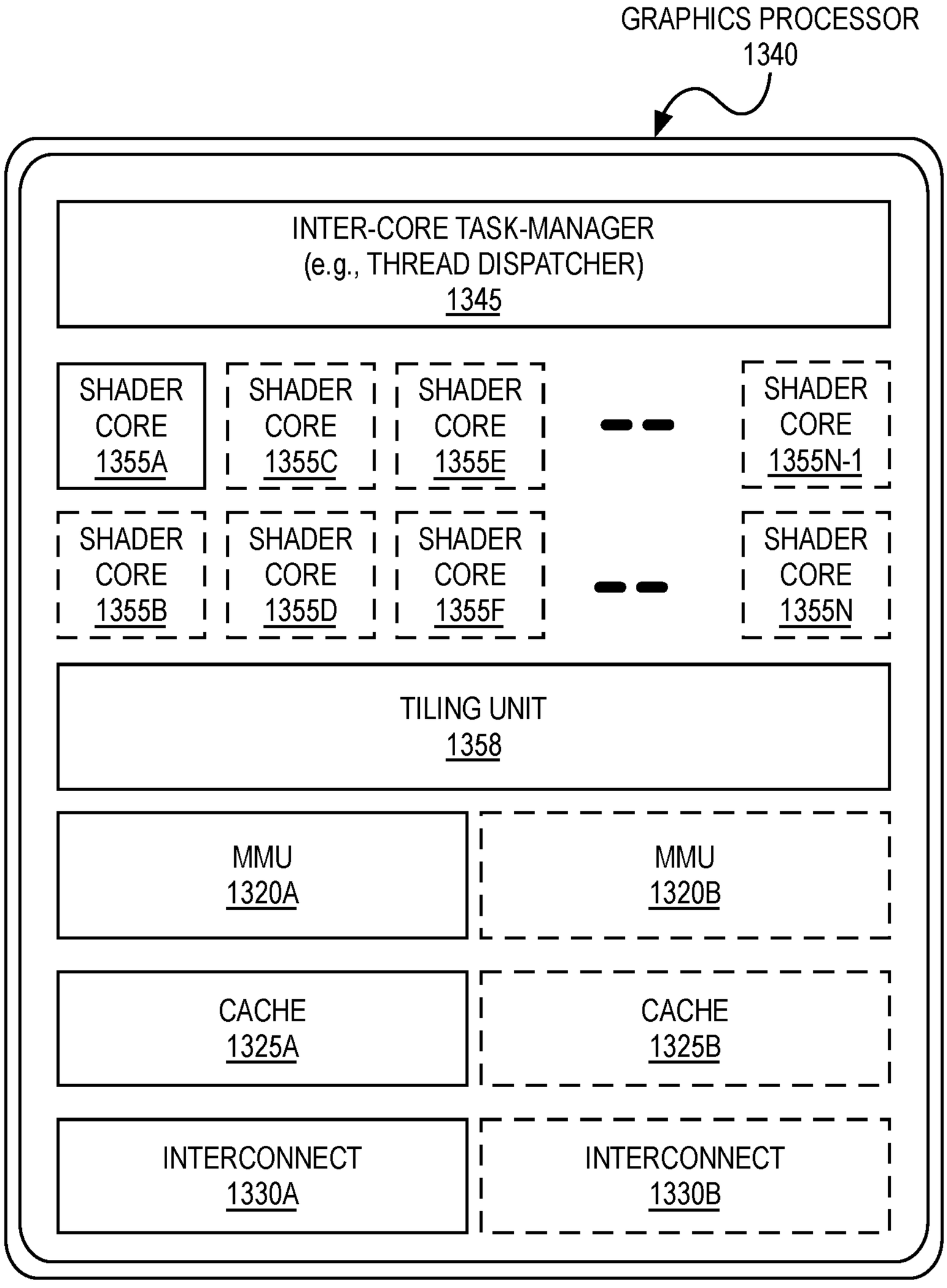

GRAPHICS PROCESSOR
1340
INTER-CORE TASK-MANAGER
(e.g., THREAD DISPATCHER)
1345
SHADER CORE 1355A
SHADER CORE 1355C
SHADER CORE 1355E
SHADER CORE 1355N-1
SHADER CORE 1355B
SHADER CORE 1355D
SHADER CORE 1355F
SHADER CORE 1355N
TILING UNIT
1358
MMU 1320A
MMU 1320B
CACHE 1325A
CACHE 1325B
INTERCONNECT 1330A
INTERCONNECT 1330B

FIG. 13B

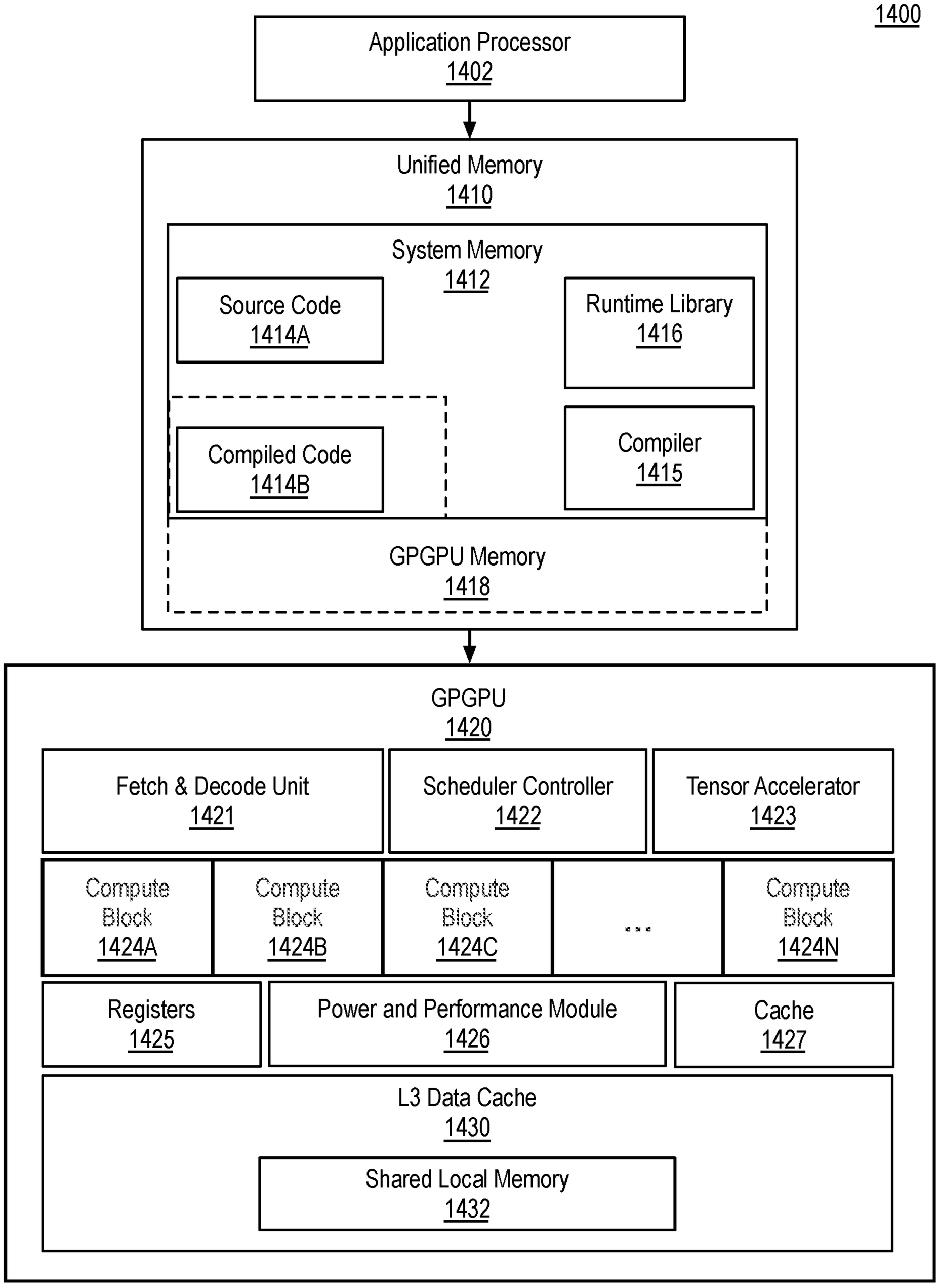

1400
Application Processor
1402
Unified Memory
1410
System Memory
1412
Source Code
1414A
Compiled Code
1414B
Runtime Library
1416
Compiler
1415
GPGPU Memory
1418
GPGPU
1420
Fetch & Decode Unit
1421
Scheduler Controller
1422
Tensor Accelerator
1423
Compute Block
1424A
Compute Block
1424B
Compute Block
1424C
...
Compute Block
1424N
Registers
1425
Power and Performance Module
1426
Cache
1427
L3 Data Cache
1430
Shared Local Memory
1432

FIG. 14

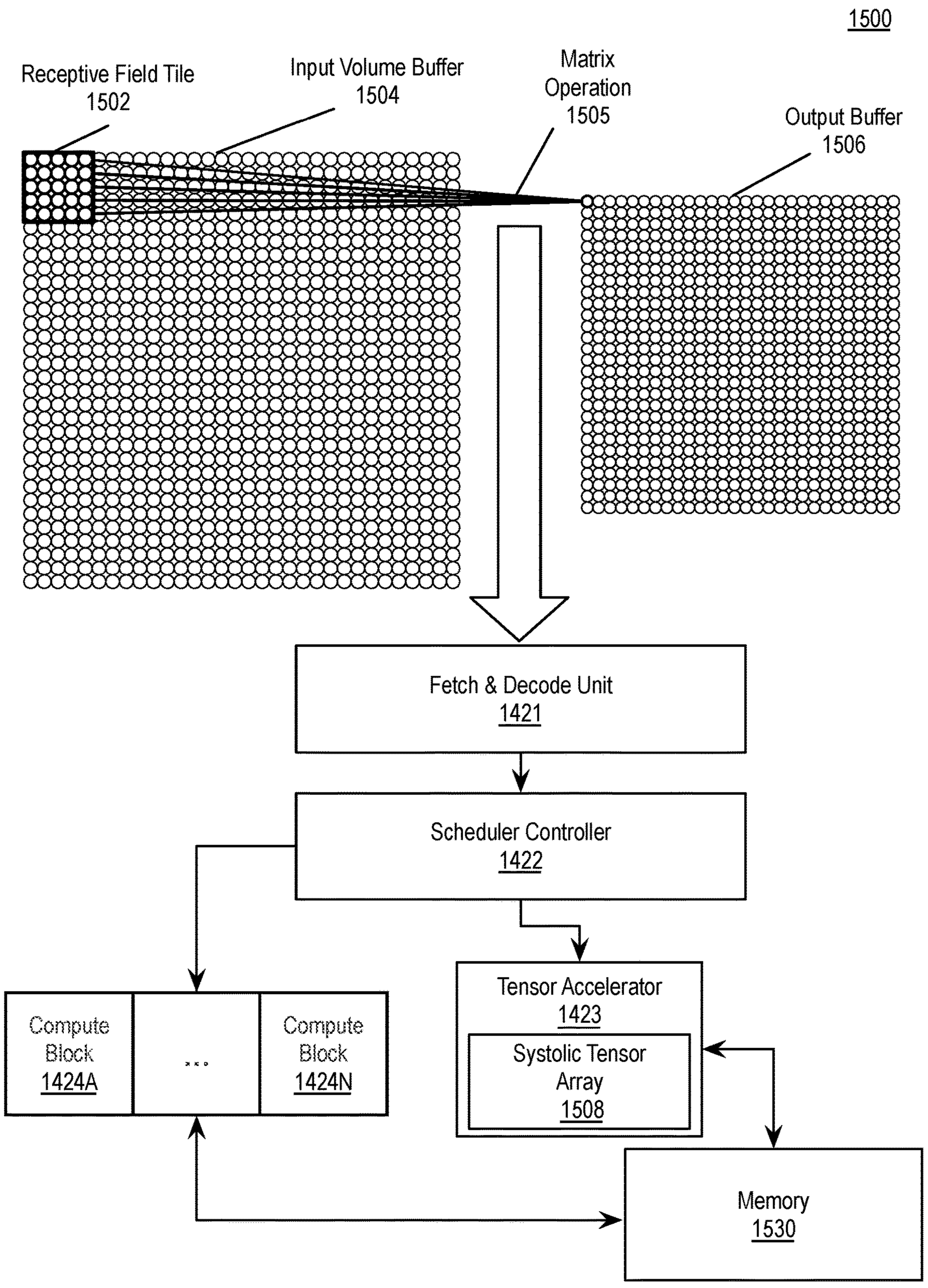

1500
Receptive Field Tile
1502
Input Volume Buffer
1504
Matrix
Operation
1505
Output Buffer
1506
Fetch & Decode Unit
1421
Scheduler Controller
1422
Compute
Block
1424A
...
Compute
Block
1424N
Tensor Accelerator
1423
Systolic Tensor
Array
1508
Memory
1530

FIG. 15

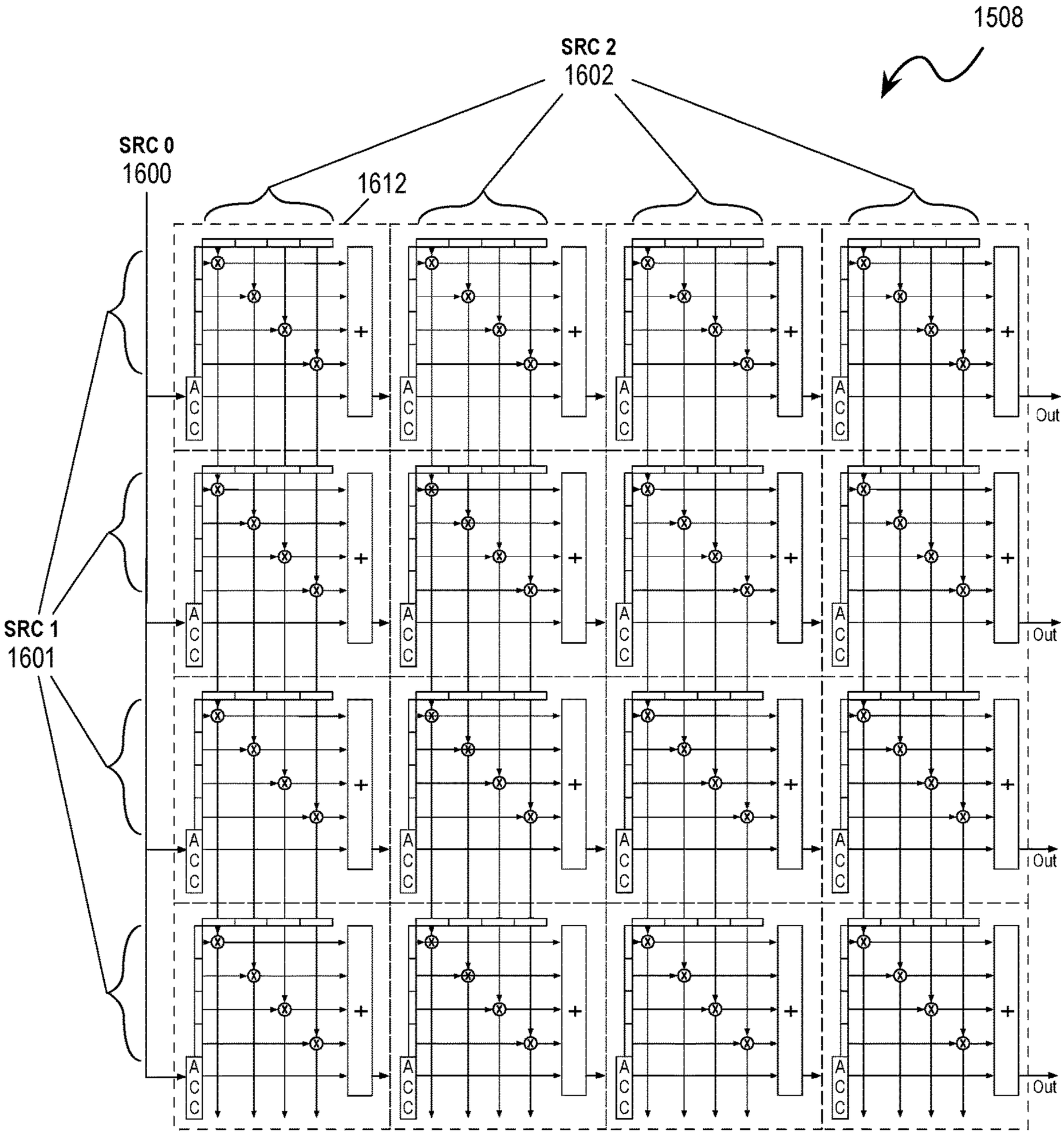


FIG. 16A

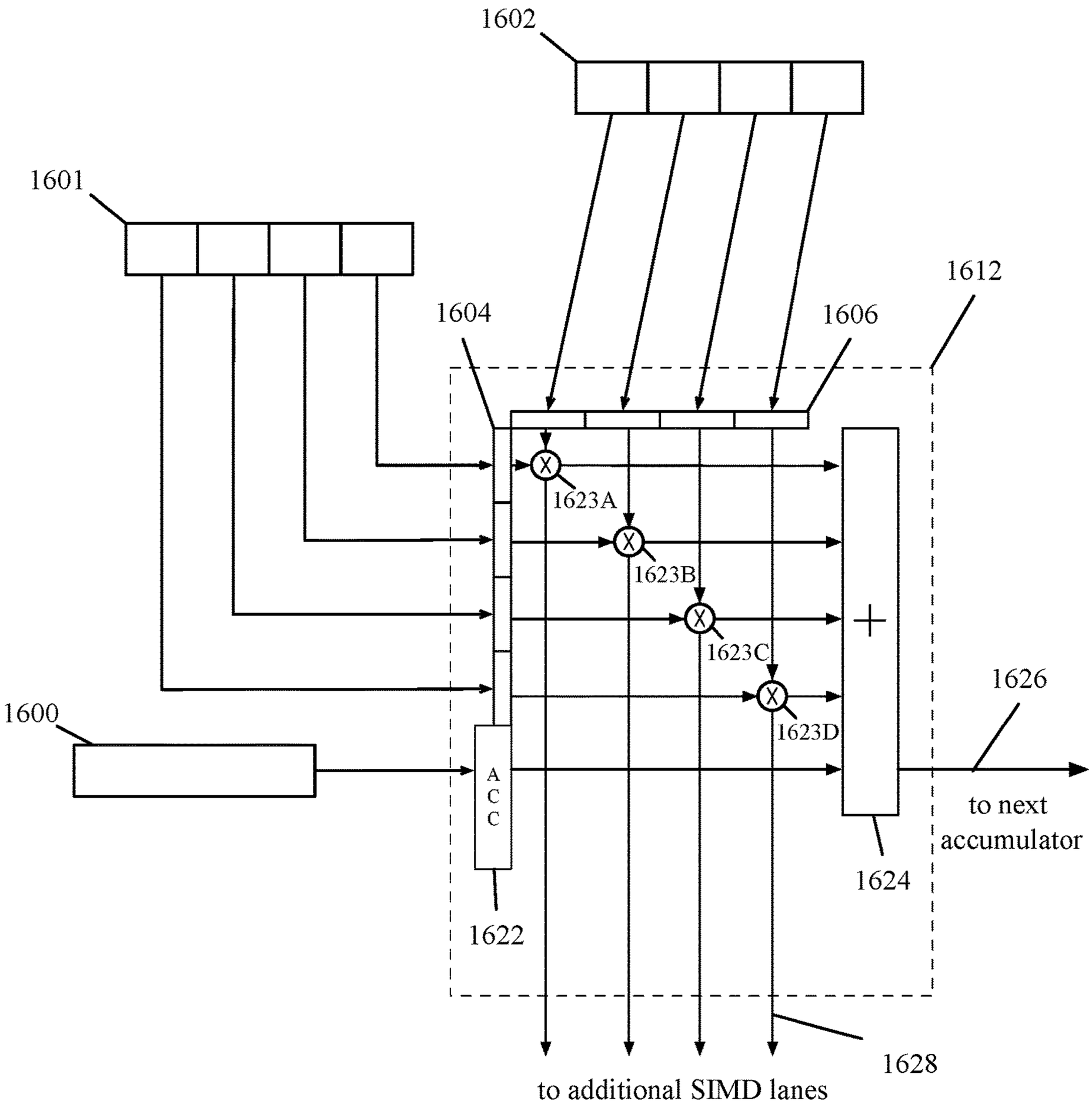

1602
1601
1612
1604
1606
1623A
1623B
1623C
1623D
1626
1600
A
C
C
to next
accumulator
1624
1622
1628
to additional SIMD lanes

FIG. 16B

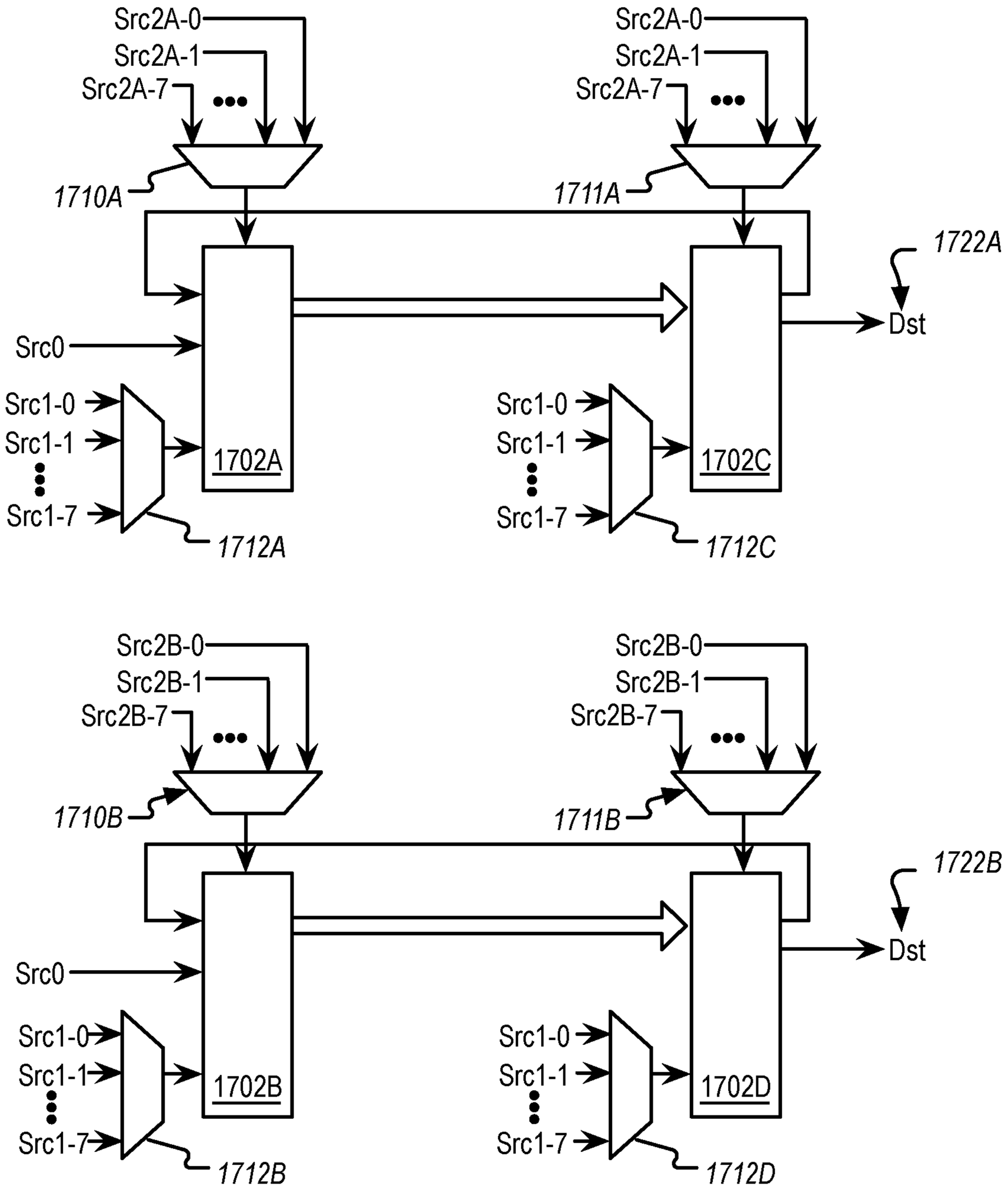

1700
Src2A-0
Src2A-1
Src2A-7
1710A
1711A
1722A
Dst
Src0
Src1-0
Src1-1
Src1-7
1702A
1712A
1702C
1712C
Src2B-0
Src2B-1
Src2B-7
1710B
1711B
1722B
Dst
Src0
Src1-0
Src1-1
Src1-7
1702B
1712B
1702D
1712D

FIG. 17A

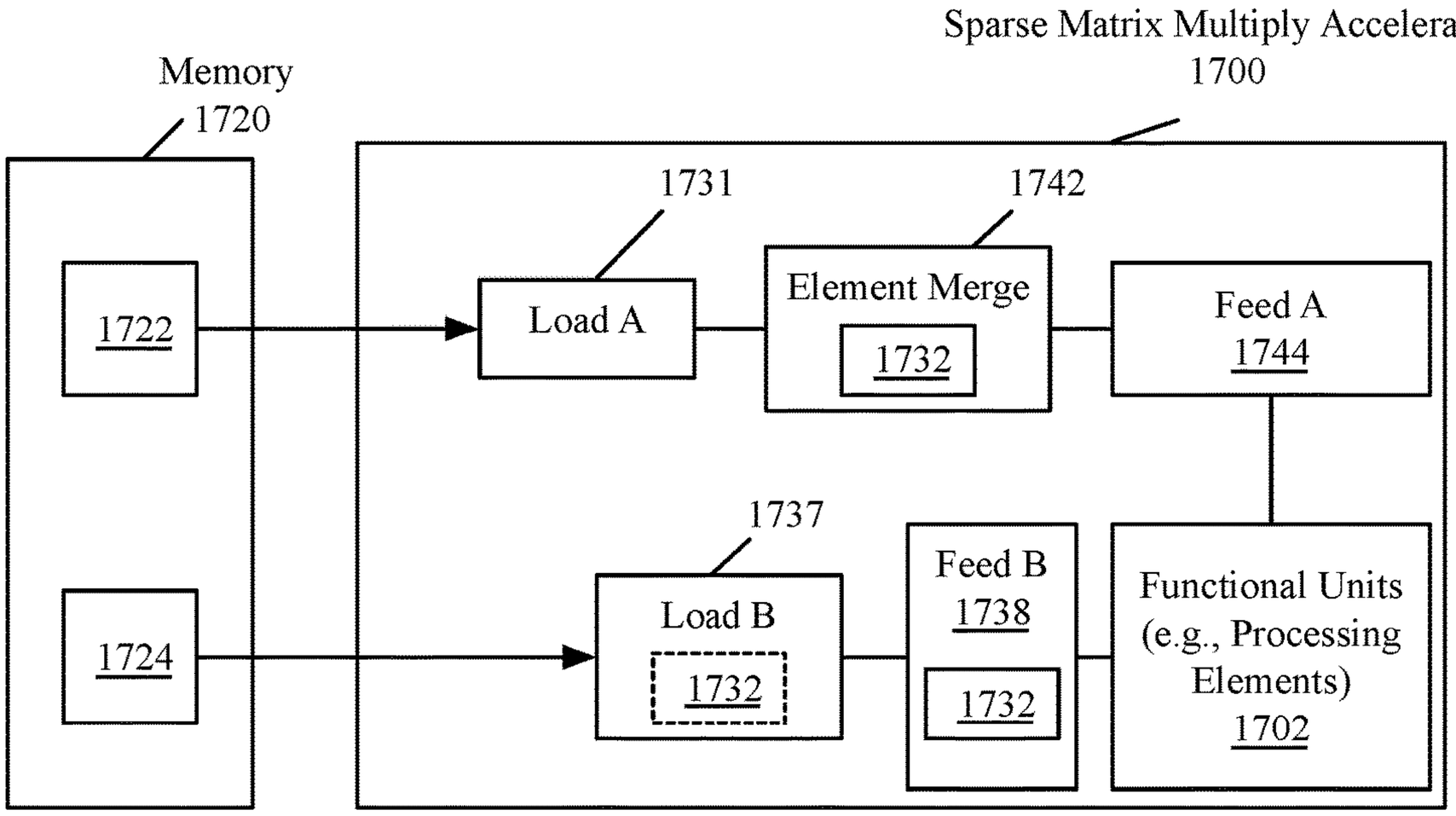


FIG. 17B

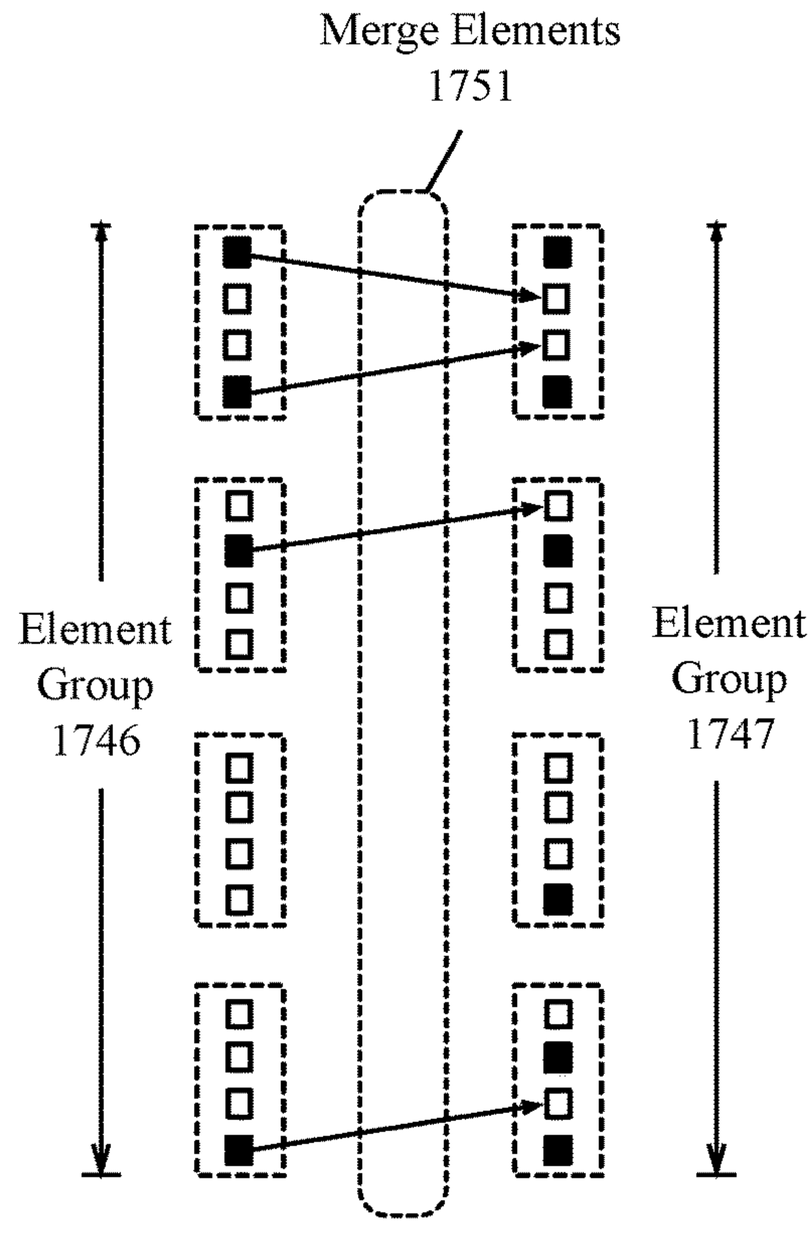


FIG. 17C

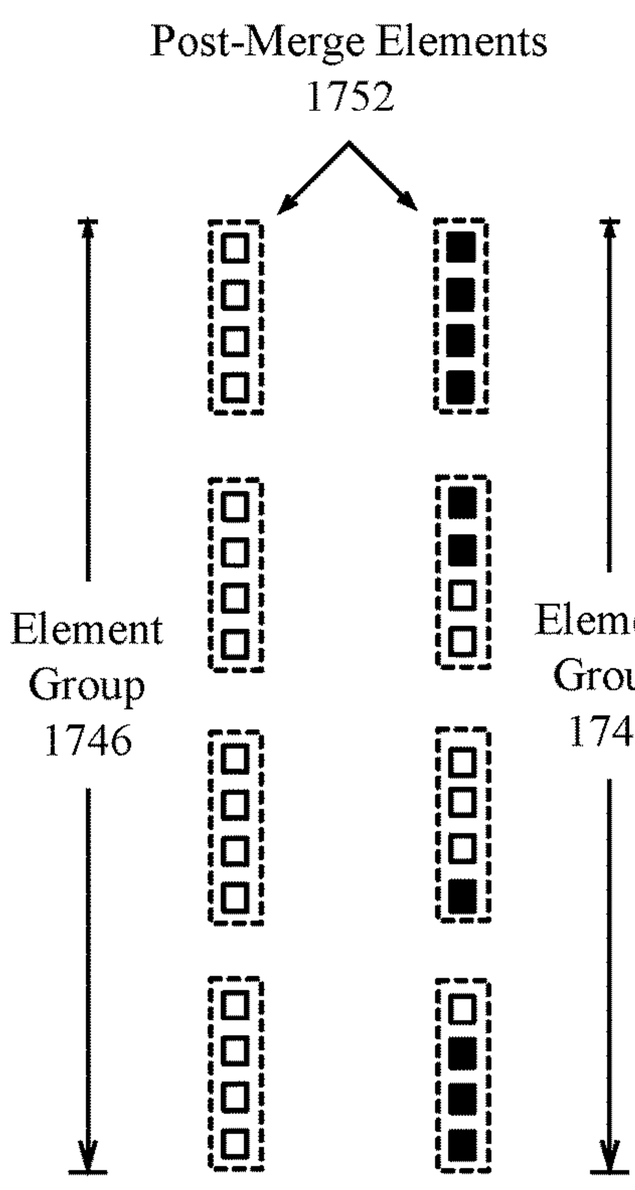


FIG. 17D

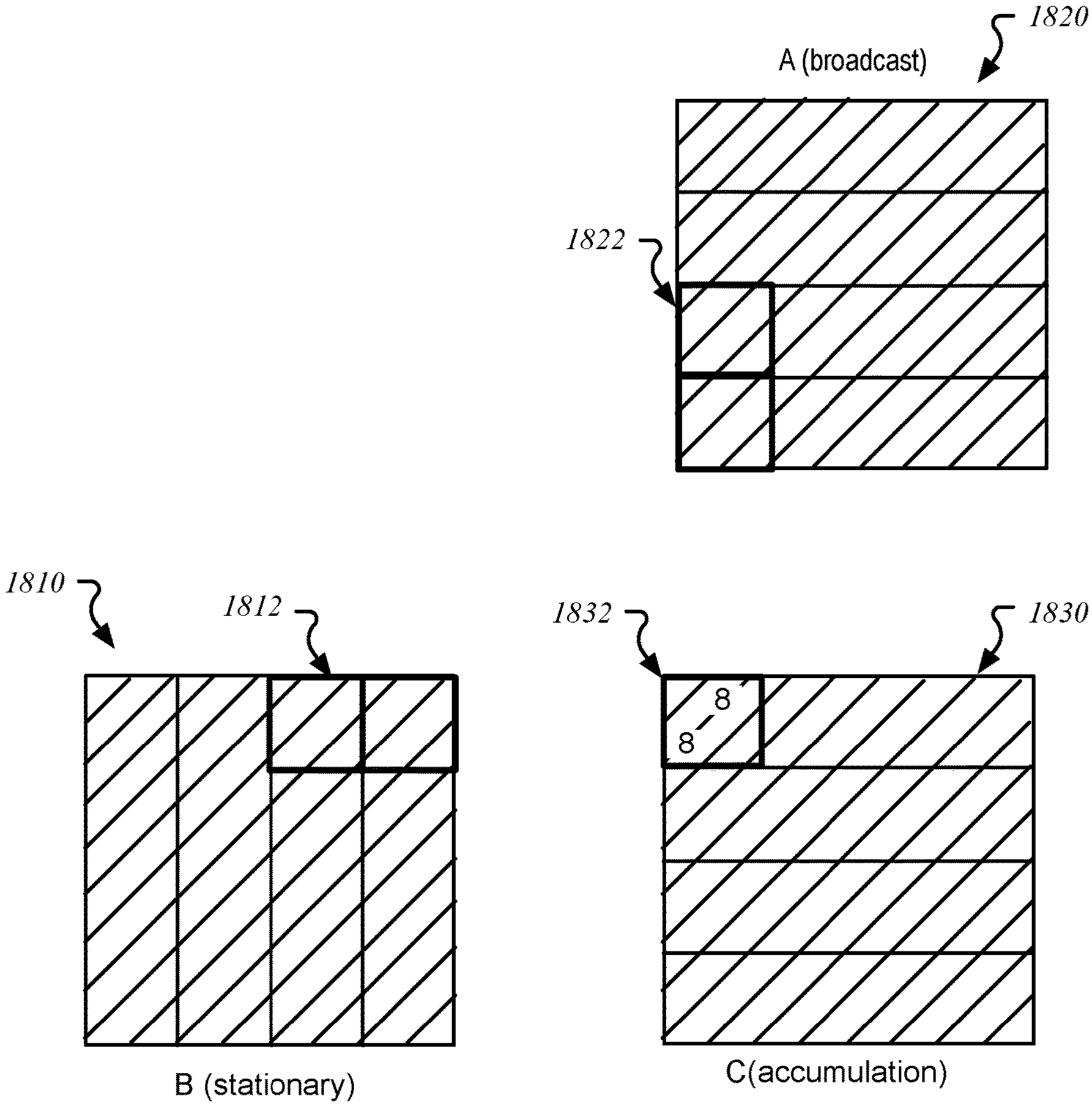

1800
1820
A (broadcast)
1822
1810
1812
B (stationary)
1832
1830
C(accumulation)

FIG. 18

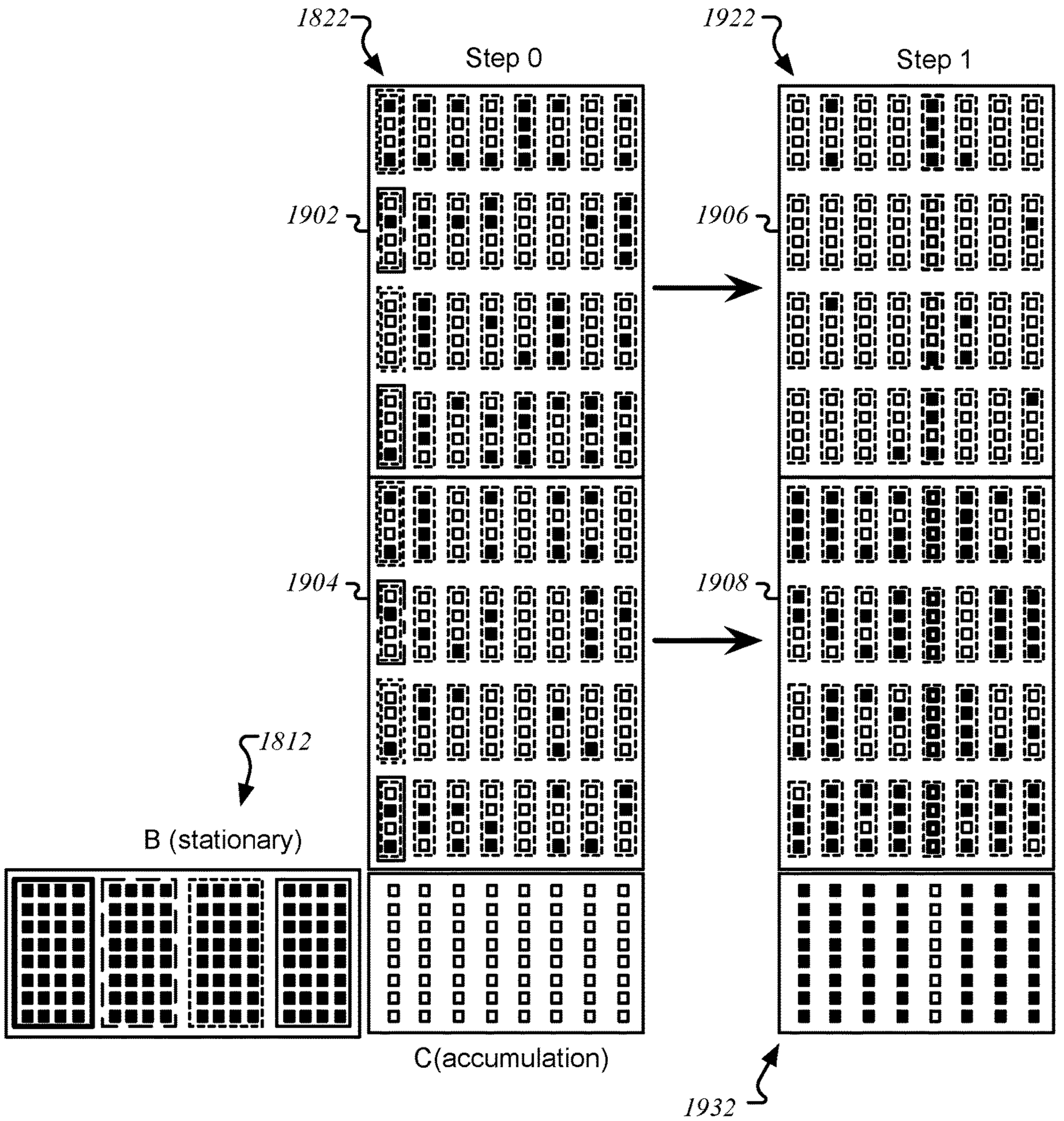

1900
1822
Step 0
1922
Step 1
1902
1906
1904
1908
1812
B (stationary)
C(accumulation)
1932

FIG. 19

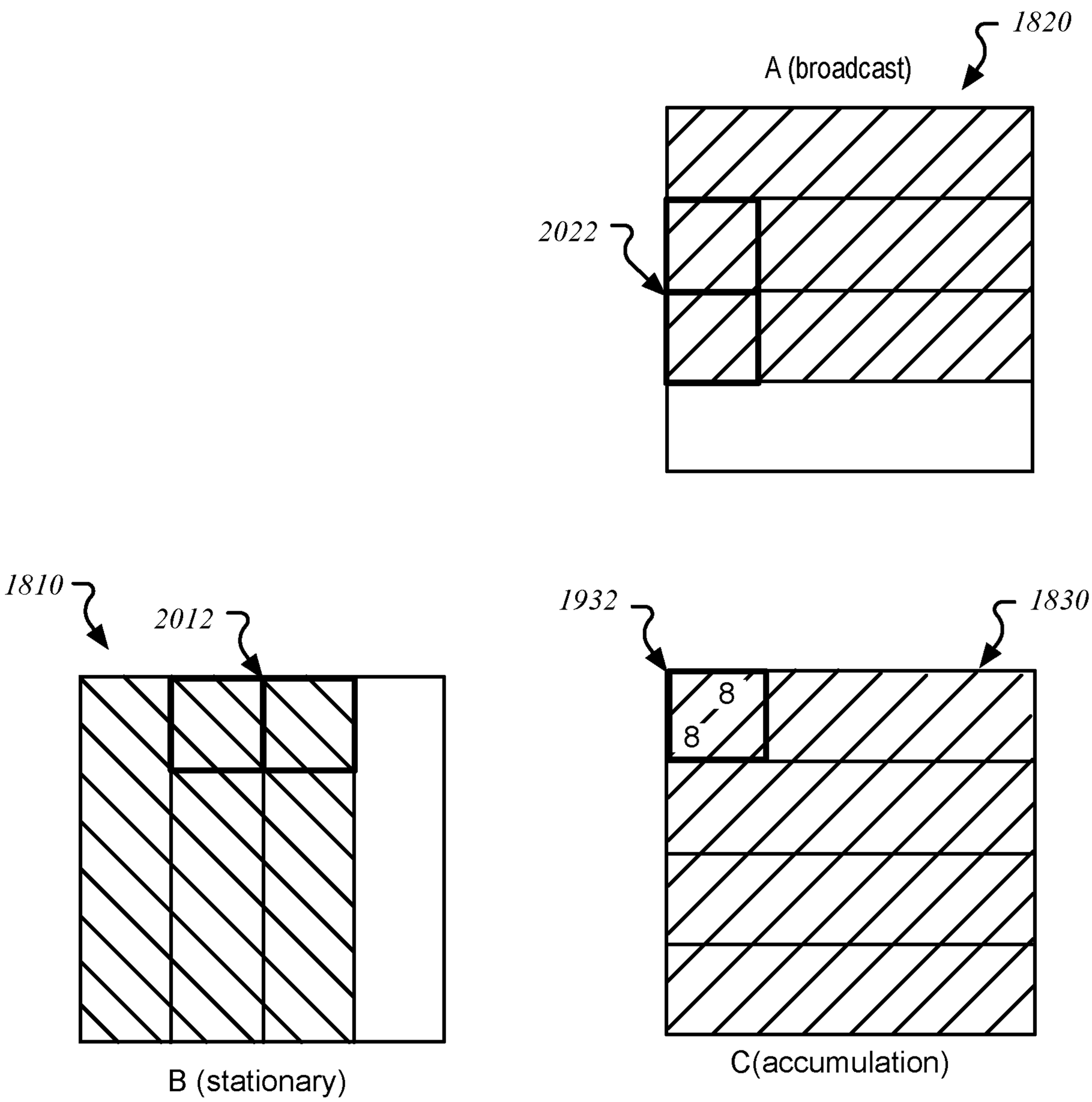

2000
1820
A (broadcast)
2022
1810
2012
B (stationary)
1932
1830
8
8
C(accumulation)

FIG. 20

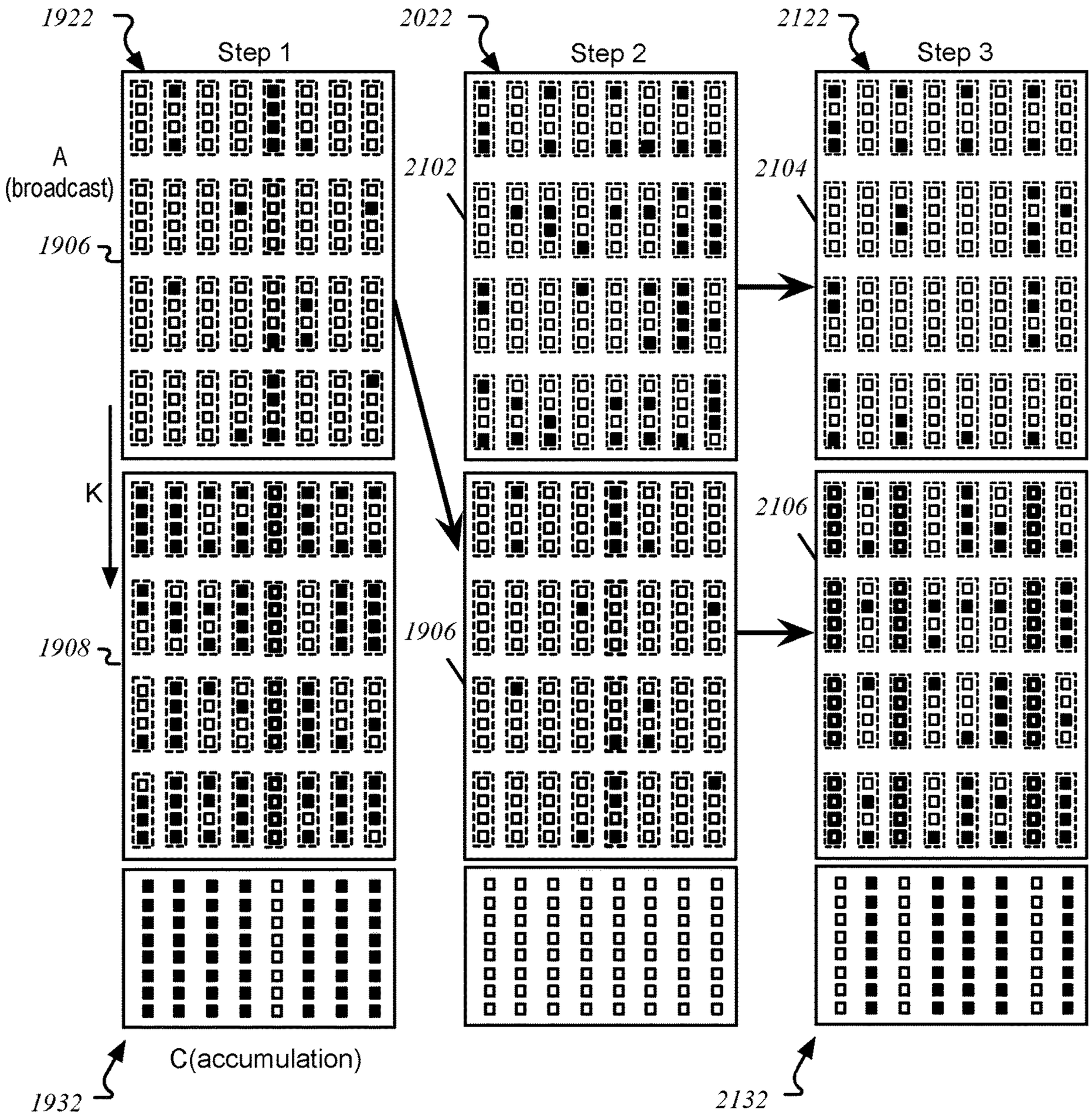

2100
1922
Step 1
2022
Step 2
2122
Step 3
A
(broadcast)
1906
2102
2104
K
2106
1908
1906
C(accumulation)
1932
2132

FIG. 21

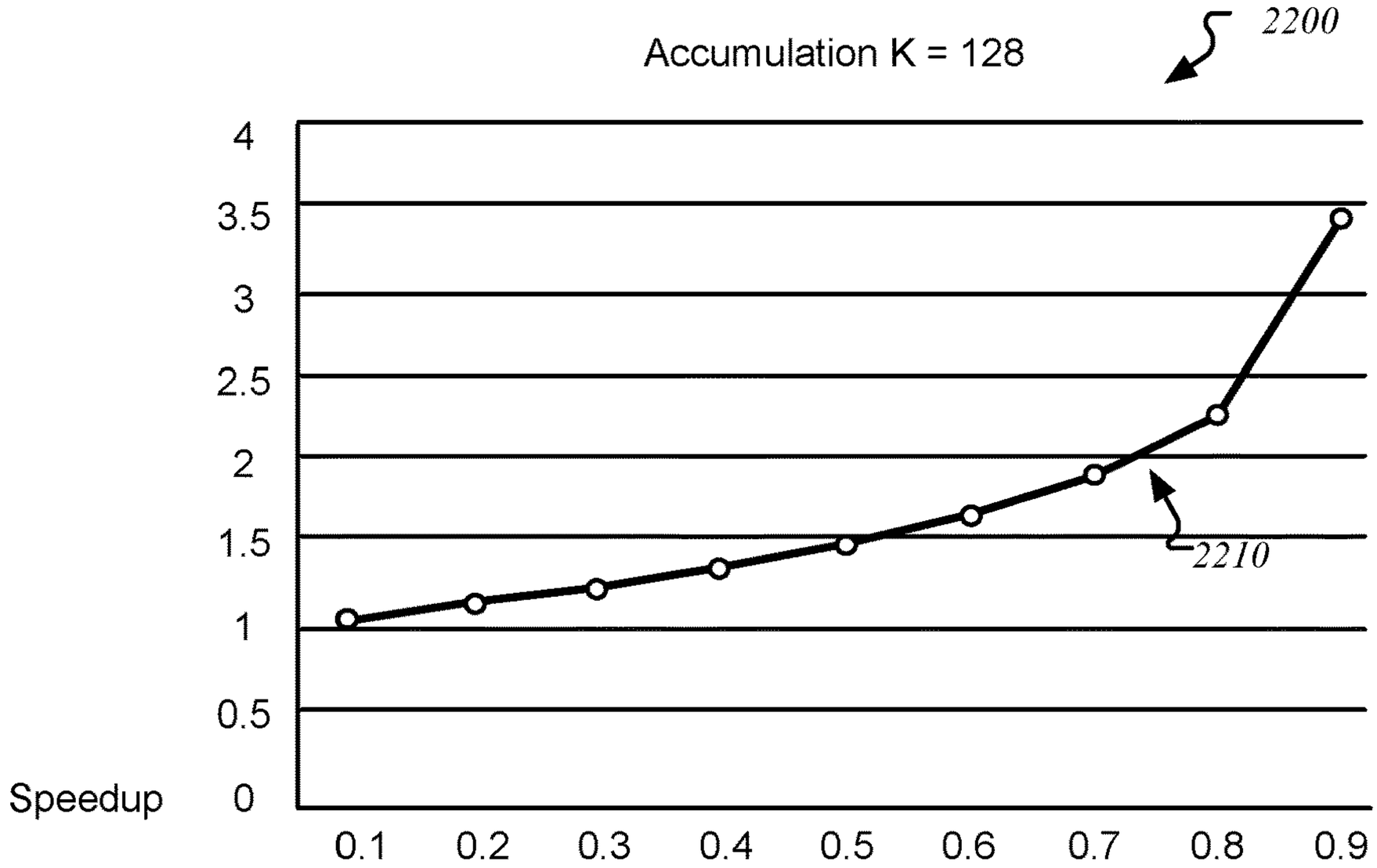

Accumulation K = 128
2200
4
3.5
3
2.5
2
1.5
1
0.5
0
Speedup
2210
0.1
0.2
0.3
0.4
0.5
0.6
0.7
0.8
0.9
Sparsity

FIG. 22

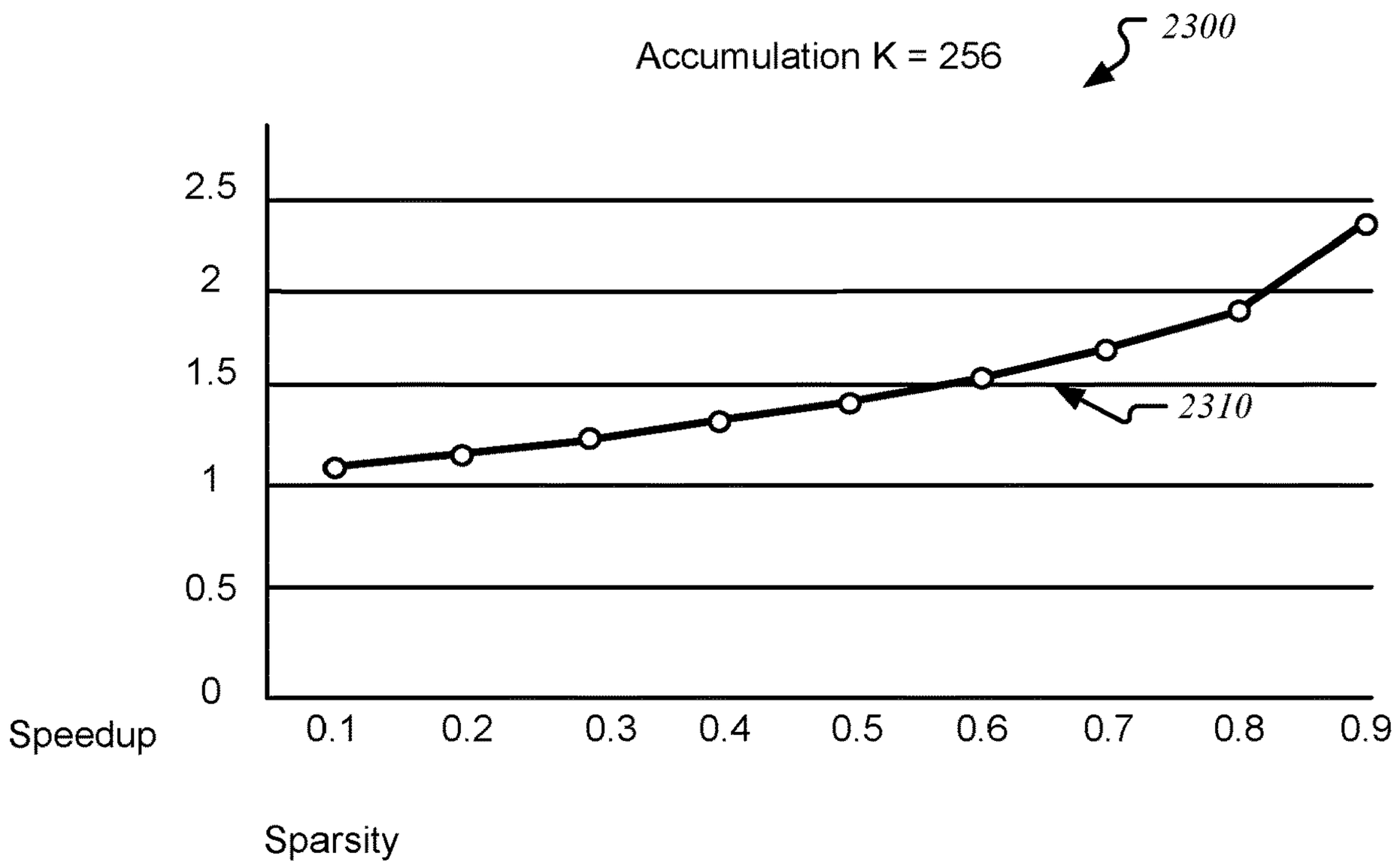

Accumulation K = 256
2300
2.5
2
1.5
1
0.5
0
Speedup
2310
0.1
0.2
0.3
0.4
0.5
0.6
0.7
0.8
0.9
Sparsity

FIG. 23

2400

LOAD MULTIPLE DATA ELEMENTS OF A FIRST SUBMATRIX AND A SECOND SUBMATRIX INTO MEMORY OF A PROCESSOR DEVICE
2402

DETERMINE A FIRST GROUPING FOR ELEMENTS OF THE FIRST SUBMATRIX AND A SECOND GROUPING FOR ELEMENTS OF THE SECOND SUBMATRIX
2404

MERGE ELEMENTS OF A FIRST GROUP OF THE FIRST GROUPING INTO A SECOND GROUP OF THE SECOND GROUPING
2406

GENERATE METADATA TO INDICATE A MERGE PATTERN FOR ELEMENTS OF THE FIRST GROUP
2408

PROVIDE THE SECOND GROUP AND THE METADATA TO A PROCESSING ELEMENT OF THE PROCESSOR DEVICE AS INPUT FOR A MATRIX OPERATION INCLUDING A MATRIX MULTIPLY
2410

FIG. 24

2500

READ A FIRST SET OF TWO OR MORE TILES OF ELEMENTS ASSOCIATED WITH A FIRST MATRIX
2502

MERGE A FIRST GROUP OF ELEMENTS IN A FIRST TILE OF THE TWO OR MORE TILES OF ELEMENTS INTO A SECOND GROUP OF ELEMENTS OF A CORRESPONDING GROUP OF ELEMENTS IN A SECOND TILE OF THE TWO OR MORE TILES OF ELEMENTS
2504

READING A SECOND SET OF TWO OR MORE TILES OF ELEMENTS ASSOCIATED WITH A SECOND MATRIX
2506

PERFORMING A MATRIX MULTIPLY OPERATION HAVING INPUT INCLUDING THE SECOND GROUP OF ELEMENTS IN THE SECOND TILE AND SELECTED ELEMENTS FROM THE SECOND SET OF TWO OR MORE TILES OF ELEMENTS
2508

FIG. 25A

2510

DURING A MERGE OPERATION, BYPASSING A MERGE OF A FIRST COLUMN OF ELEMENTS INTO A SECOND COLUMN OF ELEMENTS WHEN ALL ELEMENTS OF THE SECOND COLUMN ARE ZERO
2512

DURING A MATRIX MULTIPLY OPERATION, BYPASSING A DOT PRODUCT OPERATION INCLUDING THE SECOND COLUMN OF ELEMENTS WHEN ALL ELEMENTS OF THE SECOND COLUMN ARE ZERO
2514

FIG. 25B

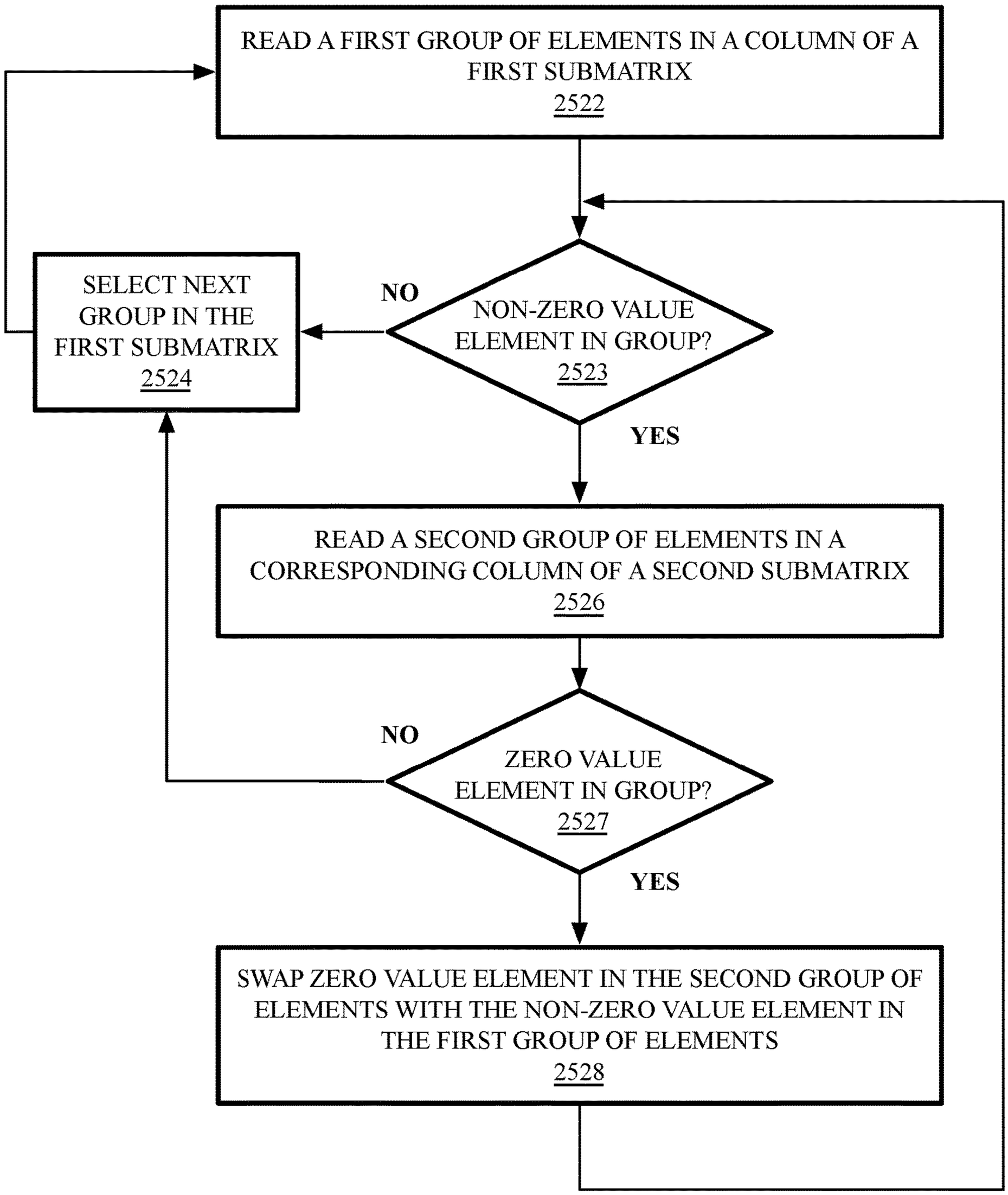

2520
READ A FIRST GROUP OF ELEMENTS IN A COLUMN OF A FIRST SUBMATRIX
2522
NON-ZERO VALUE ELEMENT IN GROUP?
2523
NO
SELECT NEXT GROUP IN THE FIRST SUBMATRIX
2524
YES
READ A SECOND GROUP OF ELEMENTS IN A CORRESPONDING COLUMN OF A SECOND SUBMATRIX
2526
ZERO VALUE ELEMENT IN GROUP?
2527
NO
YES
SWAP ZERO VALUE ELEMENT IN THE SECOND GROUP OF ELEMENTS WITH THE NON-ZERO VALUE ELEMENT IN THE FIRST GROUP OF ELEMENTS
2528

FIG. 25C

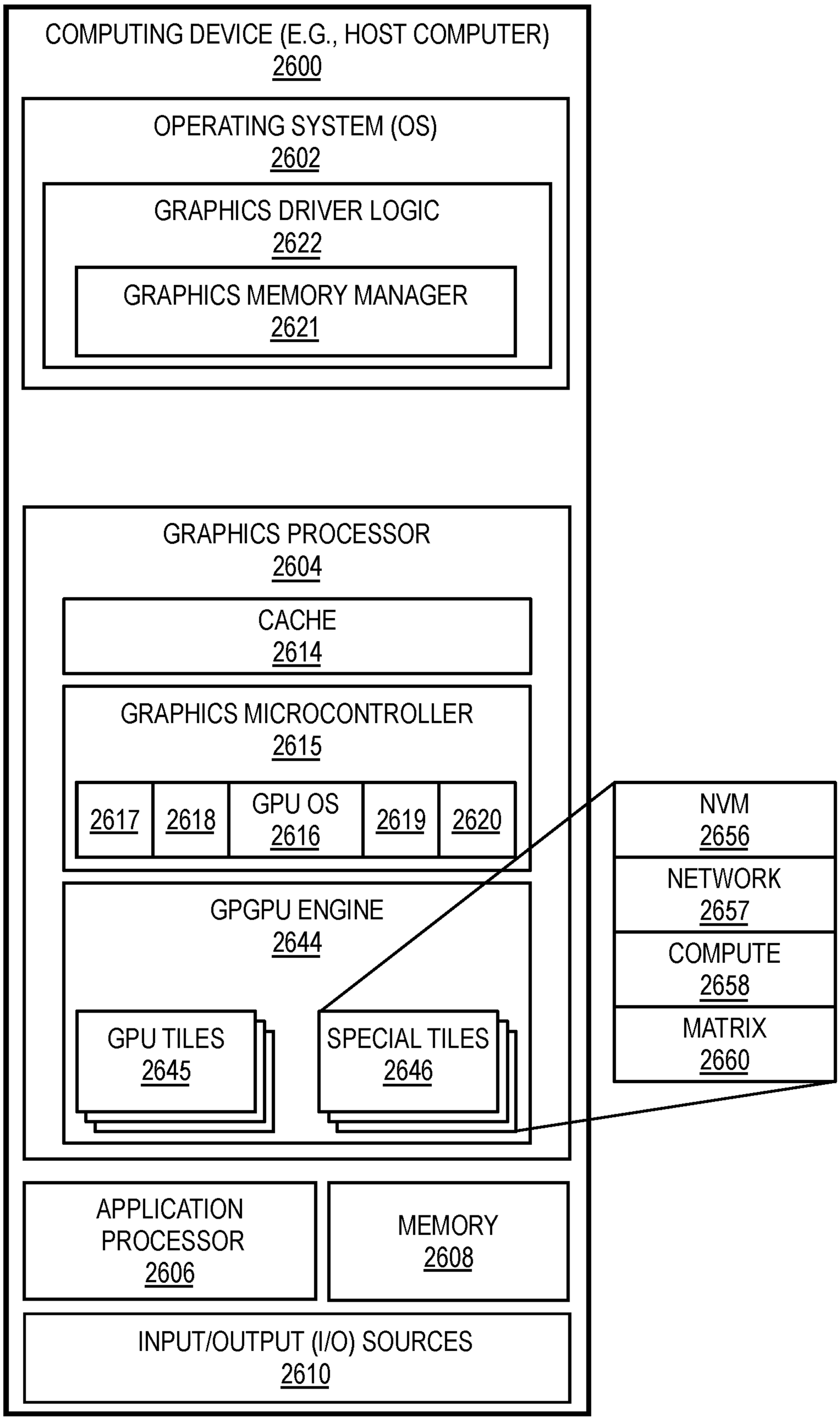

COMPUTING DEVICE (E.G., HOST COMPUTER)
2600
OPERATING SYSTEM (OS)
2602
GRAPHICS DRIVER LOGIC
2622
GRAPHICS MEMORY MANAGER
2621
GRAPHICS PROCESSOR
2604
CACHE
2614
GRAPHICS MICROCONTROLLER
2615
2617
2618
GPU OS
2616
2619
2620
GPGPU ENGINE
2644
GPU TILES
2645
SPECIAL TILES
2646
NVM
2656
NETWORK
2657
COMPUTE
2658
MATRIX
2660
APPLICATION PROCESSOR
2606
MEMORY
2608
INPUT/OUTPUT (I/O) SOURCES
2610

FIG. 26

RANDOM SPARSITY HANDLING IN A SYSTOLIC ARRAY

BACKGROUND

In deep learning applications, random sparsity is very common in all types of data including activations, gradients, and weights. Data sparsity exists in both inference and training cases. The sparsity mainly come from two sources, RELU function and pruning. RELU function clamps negative activation values to zeros which serve as input to next layer; pruning process drops weights that are less important to save storage. Matrix multiply is a foundation of deep learning computation. Zeros in activation, weights, or gradient input to a matrix multiply unit produce zero as result and have no impact on accumulation. If an output element is known to be zero beforehand, the entire compute effort for that element is wasted.

BRIEF DESCRIPTION OF THE DRAWINGS

The present invention is illustrated by way of example and not limitation in the figures of the accompanying drawings in which like references indicate similar elements, and in which:

FIG. **1** is a block diagram of a processing system, according to an embodiment;

FIG. **2**A-**2**D illustrate computing systems and graphics processors provided by embodiments described herein;

FIG. **3**A-**3**C illustrate block diagrams of additional graphics processor and compute accelerator architectures provided by embodiments described herein;

FIG. **4** is a block diagram of a graphics processing engine of a graphics processor in accordance with some embodiments;

FIG. **5**A-**5**B illustrate thread execution logic including an array of processing elements employed in a graphics processor core according to embodiments described herein;

FIG. **6** illustrates an additional execution unit, according to an embodiment;

FIG. **7** is a block diagram illustrating a graphics processor instruction formats according to some embodiments;

FIG. **8** is a block diagram of a graphics processor according to another embodiment;

FIG. **9**A-**9**B illustrate a graphics processor command format and command sequence, according to some embodiments;

FIG. **10** illustrates exemplary graphics software architecture for a data processing system according to some embodiments;

FIG. **11**A is a block diagram illustrating an IP core development system, according to an embodiment;

FIG. **11**B illustrates a cross-section side view of an integrated circuit package assembly, according to some embodiments described herein;

FIG. **11**C illustrates a package assembly that includes multiple units of hardware logic chiplets connected to a substrate;

FIG. **11**D illustrates a package assembly including interchangeable chiplets, according to an embodiment;

FIG. **12** is a block diagram illustrating an exemplary system on a chip integrated circuit that may be fabricated using one or more IP cores, according to an embodiment;

FIG. **13**A-**13**B are block diagrams illustrating exemplary graphics processors for use within an SoC, according to embodiments described herein;

FIG. **14** is a block diagram of a data processing system, according to an embodiment;

FIG. **15** illustrates a matrix operation performed by an instruction pipeline, according to an embodiment;

FIG. **16**A-**16**B illustrate details of hardware-based systolic array, according to some embodiments;

FIG. **17**A-**17**D illustrates a sparse matrix multiply accelerator using systolic arrays with feedback inputs;

FIG. **18** illustrates a matrix multiply in which random sparsity is handled via element merges;

FIG. **19** illustrates operations for column merging to handle random sparsity in an input matrix of a matrix accelerator;

FIG. **20** illustrates a successive set of operations that are performed to merge residual input elements during a successive iteration;

FIG. **21** illustrates operations for a second round of merging;

FIG. **22** and FIG. **23** illustrate throughput gains for a matrix multiply unit having support for random sparsity;

FIG. **24** illustrates a method of merging sparse matrix input having random sparsity;

FIG. **25**A-**25**C illustrates methods of handling random sparsity of an input matrix during a matrix multiply operation;

FIG. **26** is a block diagram of a computing device including a graphics processor, according to an embodiment.

DETAILED DESCRIPTION

For the purposes of explanation, numerous specific details are set forth to provide a thorough understanding of the various embodiments described below. However, it will be apparent to a skilled practitioner in the art that the embodiments may be practiced without some of these specific details. In other instances, well-known structures and devices are shown in block diagram form to avoid obscuring the underlying principles, and to provide a more thorough understanding of embodiments. Although some of the following embodiments are described with reference to a graphics processor, the techniques and teachings described herein may be applied to various types of circuits or semiconductor devices, including general purpose processing devices or graphic processing devices. Reference herein to "one embodiment" or "an embodiment" indicate that a particular feature, structure, or characteristic described in connection or association with the embodiment can be included in at least one of such embodiments. However, the appearances of the phrase "in one embodiment" in various places in the specification do not necessarily all refer to the same embodiment.

In the following description and claims, the terms "coupled" and "connected," along with their derivatives, may be used. It should be understood that these terms are not intended as synonyms for each other. "Coupled" is used to indicate that two or more elements, which may or may not be in direct physical or electrical contact with each other, co-operate or interact with each other. "Connected" is used to indicate the establishment of communication between two or more elements that are coupled with each other.

In the description that follows, FIGS. **1** through **13**A-**13**B provide an overview of exemplary data processing system and graphics processor logic that incorporates or relates to the various embodiments. FIGS. **14-26** provide specific details of the various embodiments. Some aspects of the following embodiments are described with reference to a graphics processor, while other aspects are described with

respect to a general-purpose processor, such as a central processing unit (CPU). Similar techniques and teachings can be applied to other types of circuits or semiconductor devices, including but not limited to a many integrated core processor, a GPU cluster, or one or more instances of a field programmable gate array (FPGA). In general, the teachings are applicable to any processor or machine that manipulates or processes image (e.g., sample, pixel), vertex data, or geometry data or that performs parallel processing operations for machine learning and high-performance computing applications.

System Overview

FIG. **1** is a block diagram of a processing system **100**, according to an embodiment. Processing system **100** may be used in a single processor desktop system, a multiprocessor workstation system, or a server system having a large number of processors **102** or processor cores **107**. In one embodiment, the processing system **100** is a processing platform incorporated within a system-on-a-chip (SoC) integrated circuit for use in mobile, handheld, or embedded devices such as within Internet-of-things (IoT) devices with wired or wireless connectivity to a local or wide area network.

In one embodiment, processing system **100** can include, couple with, or be integrated within: a server-based gaming platform; a game console, including a game and media console; a mobile gaming console, a handheld game console, or an online game console. In some embodiments the processing system **100** is part of a mobile phone, smart phone, tablet computing device or mobile Internet-connected device such as a laptop with low internal storage capacity. Processing system **100** can also include, couple with, or be integrated within: a wearable device, such as a smart watch wearable device; smart eyewear or clothing enhanced with augmented reality (AR) or virtual reality (VR) features to provide visual, audio or tactile outputs to supplement real world visual, audio or tactile experiences or otherwise provide text, audio, graphics, video, holographic images or video, or tactile feedback; other augmented reality (AR) device; or other virtual reality (VR) device. In some embodiments, the processing system **100** includes or is part of a television or set top box device. In one embodiment, processing system **100** can include, couple with, or be integrated within a self-driving vehicle such as a bus, tractor trailer, car, motor or electric power cycle, plane or glider (or any combination thereof). The self-driving vehicle may use processing system **100** to process the environment sensed around the vehicle.

In some embodiments, the one or more processors **102** each include one or more processor cores **107** to process instructions which, when executed, perform operations for system or user software. In some embodiments, at least one of the one or more processor cores **107** is configured to process a specific instruction set **109**. In some embodiments, instruction set **109** may facilitate Complex Instruction Set Computing (CISC), Reduced Instruction Set Computing (RISC), or computing via a Very Long Instruction Word (VLIW). One or more processor cores **107** may process a different instruction set **109**, which may include instructions to facilitate the emulation of other instruction sets. Processor core **107** may also include other processing devices, such as a Digital Signal Processor (DSP).

In some embodiments, the processor **102** includes cache memory **104**. Depending on the architecture, the processor **102** can have a single internal cache or multiple levels of internal cache. In some embodiments, the cache memory is shared among various components of the processor **102**. In some embodiments, the processor **102** also uses an external cache (e.g., a Level-3 (L3) cache or Last Level Cache (LLC)) (not shown), which may be shared among processor cores **107** using known cache coherency techniques. A register file **106** can be additionally included in processor **102** and may include different types of registers for storing different types of data (e.g., integer registers, floating point registers, status registers, and an instruction pointer register). Some registers may be general-purpose registers, while other registers may be specific to the design of the processor **102**.

In some embodiments, one or more processor(s) **102** are coupled with one or more interface bus(es) **110** to transmit communication signals such as address, data, or control signals between processor **102** and other components in the processing system **100**. The interface bus **110**, in one embodiment, can be a processor bus, such as a version of the Direct Media Interface (DMI) bus. However, processor busses are not limited to the DMI bus, and may include one or more Peripheral Component Interconnect buses (e.g., PCI, PCI express), memory busses, or other types of interface busses. In one embodiment the processor(s) **102** include an integrated memory controller **116** and a platform controller hub **130**. The memory controller **116** facilitates communication between a memory device and other components of the processing system **100**, while the platform controller hub (PCH) **130** provides connections to I/O devices via a local I/O bus.

The memory device **120** can be a dynamic random-access memory (DRAM) device, a static random-access memory (SRAM) device, flash memory device, phase-change memory device, or some other memory device having suitable performance to serve as process memory. In one embodiment the memory device **120** can operate as system memory for the processing system **100**, to store data **122** and instructions **121** for use when the one or more processors **102** executes an application or process. Memory controller **116** also couples with an optional external graphics processor **118**, which may communicate with the one or more graphics processors **108** in processors **102** to perform graphics and media operations. In some embodiments, graphics, media, and or compute operations may be assisted by an accelerator **112** which is a coprocessor that can be configured to perform a specialized set of graphics, media, or compute operations. For example, in one embodiment the accelerator **112** is a matrix multiplication accelerator used to optimize machine learning or compute operations. In one embodiment the accelerator **112** is a ray-tracing accelerator that can be used to perform ray-tracing operations in concert with the graphics processor **108**. In one embodiment, an external accelerator **119** may be used in place of or in concert with the accelerator **112**.

In some embodiments a display device **111** can connect to the processor(s) **102**. The display device **111** can be one or more of an internal display device, as in a mobile electronic device or a laptop device or an external display device attached via a display interface (e.g., DisplayPort, etc.). In one embodiment the display device **111** can be a head mounted display (HMD) such as a stereoscopic display device for use in virtual reality (VR) applications or augmented reality (AR) applications.

In some embodiments the platform controller hub **130** enables peripherals to connect to memory device **120** and processor **102** via a high-speed I/O bus. The I/O peripherals include, but are not limited to, an audio controller **146**, a network controller **134**, a firmware interface **128**, a wireless transceiver **126**, touch sensors **125**, a data storage device **124**

(e.g., non-volatile memory, volatile memory, hard disk drive, flash memory, NAND, 3D NAND, 3D XPoint, etc.). The data storage device **124** can connect via a storage interface (e.g., SATA) or via a peripheral bus, such as a Peripheral Component Interconnect bus (e.g., PCI, PCI express). The touch sensors **125** can include touch screen sensors, pressure sensors, or fingerprint sensors. The wireless transceiver **126** can be a Wi-Fi transceiver, a Bluetooth transceiver, or a mobile network transceiver such as a 3G, 4G, 5G, or Long-Term Evolution (LTE) transceiver. The firmware interface **128** enables communication with system firmware, and can be, for example, a unified extensible firmware interface (UEFI). The network controller **134** can enable a network connection to a wired network. In some embodiments, a high-performance network controller (not shown) couples with the interface bus **110**. The audio controller **146**, in one embodiment, is a multi-channel high definition audio controller. In one embodiment the processing system **100** includes an optional legacy I/O controller **140** for coupling legacy (e.g., Personal System 2 (PS/2)) devices to the system. The platform controller hub **130** can also connect to one or more Universal Serial Bus (USB) controllers **142** connect input devices, such as keyboard and mouse **143** combinations, a camera **144**, or other USB input devices.

It will be appreciated that the processing system **100** shown is exemplary and not limiting, as other types of data processing systems that are differently configured may also be used. For example, an instance of the memory controller **116** and platform controller hub **130** may be integrated into a discreet external graphics processor, such as the external graphics processor **118**. In one embodiment the platform controller hub **130** and/or memory controller **116** may be external to the one or more processor(s) **102**. For example, the processing system **100** can include an external memory controller **116** and platform controller hub **130**, which may be configured as a memory controller hub and peripheral controller hub within a system chipset that is in communication with the processor(s) **102**.

For example, circuit boards ("sleds") can be used on which components such as CPUs, memory, and other components are placed are designed for increased thermal performance. In some examples, processing components such as the processors are located on a top side of a sled while near memory, such as DIMMs, are located on a bottom side of the sled. As a result of the enhanced airflow provided by this design, the components may operate at higher frequencies and power levels than in typical systems, thereby increasing performance. Furthermore, the sleds are configured to blindly mate with power and data communication cables in a rack, thereby enhancing their ability to be quickly removed, upgraded, reinstalled, and/or replaced. Similarly, individual components located on the sleds, such as processors, accelerators, memory, and data storage drives, are configured to be easily upgraded due to their increased spacing from each other. In the illustrative embodiment, the components additionally include hardware attestation features to prove their authenticity.

A data center can utilize a single network architecture ("fabric") that supports multiple other network architectures including Ethernet and Omni-Path. The sleds can be coupled to switches via optical fibers, which provide higher bandwidth and lower latency than typical twisted pair cabling (e.g., Category 5, Category 5e, Category 6, etc.). Due to the high bandwidth, low latency interconnections and network architecture, the data center may, in use, pool resources, such as memory, accelerators (e.g., GPUs, graphics accelerators, FPGAs, ASICs, neural network and/or artificial intelligence accelerators, etc.), and data storage drives that are physically disaggregated, and provide them to compute resources (e.g., processors) on an as needed basis, enabling the compute resources to access the pooled resources as if they were local.

A power supply or source can provide voltage and/or current to processing system **100** or any component or system described herein. In one example, the power supply includes an AC to DC (alternating current to direct current) adapter to plug into a wall outlet. Such AC power can be renewable energy (e.g., solar power) power source. In one example, power source includes a DC power source, such as an external AC to DC converter. In one example, power source or power supply includes wireless charging hardware to charge via proximity to a charging field. In one example, power source can include an internal battery, alternating current supply, motion-based power supply, solar power supply, or fuel cell source.

FIG. **2**A-**2**D illustrate computing systems and graphics processors provided by embodiments described herein. The elements of FIG. **2**A-**2**D having the same reference numbers (or names) as the elements of any other figure herein can operate or function in any manner similar to that described elsewhere herein, but are not limited to such.

FIG. **2**A is a block diagram of an embodiment of a processor **200** having one or more processor cores **202**A-**202**N, an integrated memory controller **214**, and an integrated graphics processor **208**. Processor **200** can include additional cores up to and including additional core **202**N represented by the dashed lined boxes. Each of processor cores **202**A-**202**N includes one or more internal cache units **204**A-**204**N. In some embodiments each processor core also has access to one or more shared cached units **206**. The internal cache units **204**A-**204**N and shared cache units **206** represent a cache memory hierarchy within the processor **200**. The cache memory hierarchy may include at least one level of instruction and data cache within each processor core and one or more levels of shared mid-level cache, such as a Level 2 (L2), Level 3 (L3), Level 4 (L4), or other levels of cache, where the highest level of cache before external memory is classified as the LLC. In some embodiments, cache coherency logic maintains coherency between the various cache units **206** and **204**A-**204**N.

In some embodiments, processor **200** may also include a set of one or more bus controller units **216** and a system agent core **210**. The one or more bus controller units **216** manage a set of peripheral buses, such as one or more PCI or PCI express busses. System agent core **210** provides management functionality for the various processor components. In some embodiments, system agent core **210** includes one or more integrated memory controllers **214** to manage access to various external memory devices (not shown).

In some embodiments, one or more of the processor cores **202**A-**202**N include support for simultaneous multi-threading. In such embodiment, the system agent core **210** includes components for coordinating and operating cores **202**A-**202**N during multi-threaded processing. System agent core **210** may additionally include a power control unit (PCU), which includes logic and components to regulate the power state of processor cores **202**A-**202**N and graphics processor **208**.

In some embodiments, processor **200** additionally includes graphics processor **208** to execute graphics processing operations. In some embodiments, the graphics processor **208** couples with the set of shared cache units **206**,

and the system agent core **210**, including the one or more integrated memory controllers **214**. In some embodiments, the system agent core **210** also includes a display controller **211** to drive graphics processor output to one or more coupled displays. In some embodiments, display controller **211** may also be a separate module coupled with the graphics processor via at least one interconnect, or may be integrated within the graphics processor **208**.

In some embodiments, a ring-based interconnect **212** is used to couple the internal components of the processor **200**. However, an alternative interconnect unit may be used, such as a point-to-point interconnect, a switched interconnect, or other techniques, including techniques well known in the art. In some embodiments, graphics processor **208** couples with the ring-based interconnect **212** via an I/O link **213**.

The exemplary I/O link **213** represents at least one of multiple varieties of I/O interconnects, including an on package I/O interconnect which facilitates communication between various processor components and a high-performance embedded memory module **218**, such as an eDRAM module. In some embodiments, each of the processor cores **202**A-**202**N and graphics processor **208** can use embedded memory modules **218** as a shared Last Level Cache.

In some embodiments, processor cores **202**A-**202**N are homogenous cores executing the same instruction set architecture. In another embodiment, processor cores **202**A-**202**N are heterogeneous in terms of instruction set architecture (ISA), where one or more of processor cores **202**A-**202**N execute a first instruction set, while at least one of the other cores executes a subset of the first instruction set or a different instruction set. In one embodiment, processor cores **202**A-**202**N are heterogeneous in terms of microarchitecture, where one or more cores having a relatively higher power consumption couple with one or more power cores having a lower power consumption. In one embodiment, processor cores **202**A-**202**N are heterogeneous in terms of computational capability. Additionally, processor **200** can be implemented on one or more chips or as an SoC integrated circuit having the illustrated components, in addition to other components.

FIG. **2**B is a block diagram of hardware logic of a graphics processor core **219**, according to some embodiments described herein. Elements of FIG. **2**B having the same reference numbers (or names) as the elements of any other figure herein can operate or function in any manner similar to that described elsewhere herein, but are not limited to such. The graphics processor core **219**, sometimes referred to as a core slice, can be one or multiple graphics cores within a modular graphics processor. The graphics processor core **219** is exemplary of one graphics core slice, and a graphics processor as described herein may include multiple graphics core slices based on target power and performance envelopes. Each graphics processor core **219** can include a fixed function block **230** coupled with multiple sub-cores **221**A-**221**F, also referred to as sub-slices, that include modular blocks of general-purpose and fixed function logic.

In some embodiments, the fixed function block **230** includes a geometry/fixed function pipeline **231** that can be shared by all sub-cores in the graphics processor core **219**, for example, in lower performance and/or lower power graphics processor implementations. In various embodiments, the geometry/fixed function pipeline **231** includes a 3D fixed function pipeline (e.g., 3D pipeline **312** as in FIG. **3**A and FIG. **4**, described below) a video front-end unit, a thread spawner and thread dispatcher, and a unified return buffer manager, which manages unified return buffers (e.g., unified return buffer **418** in FIG. **4**, as described below).

In one embodiment the fixed function block **230** also includes a graphics SoC interface **232**, a graphics microcontroller **233**, and a media pipeline **234**. The graphics SoC interface **232** provides an interface between the graphics processor core **219** and other processor cores within a system on a chip integrated circuit. The graphics microcontroller **233** is a programmable sub-processor that is configurable to manage various functions of the graphics processor core **219**, including thread dispatch, scheduling, and pre-emption. The media pipeline **234** (e.g., media pipeline **316** of FIG. **3**A and FIG. **4**) includes logic to facilitate the decoding, encoding, pre-processing, and/or post-processing of multimedia data, including image and video data. The media pipeline **234** implement media operations via requests to compute or sampling logic within the sub-cores **221**-**221**F.

In one embodiment the SoC interface **232** enables the graphics processor core **219** to communicate with general-purpose application processor cores (e.g., CPUs) and/or other components within an SoC, including memory hierarchy elements such as a shared last level cache memory, the system RAM, and/or embedded on-chip or on-package DRAM. The SoC interface **232** can also enable communication with fixed function devices within the SoC, such as camera imaging pipelines, and enables the use of and/or implements global memory atomics that may be shared between the graphics processor core **219** and CPUs within the SoC. The SoC interface **232** can also implement power management controls for the graphics processor core **219** and enable an interface between a clock domain of the graphics processor core **219** and other clock domains within the SoC. In one embodiment the SoC interface **232** enables receipt of command buffers from a command streamer and global thread dispatcher that are configured to provide commands and instructions to each of one or more graphics cores within a graphics processor. The commands and instructions can be dispatched to the media pipeline **234**, when media operations are to be performed, or a geometry and fixed function pipeline (e.g., geometry and fixed function pipeline **231**, geometry and fixed function pipeline **237**) when graphics processing operations are to be performed.

The graphics microcontroller **233** can be configured to perform various scheduling and management tasks for the graphics processor core **219**. In one embodiment the graphics microcontroller **233** can perform graphics and/or compute workload scheduling on the various graphics parallel engines within execution unit (EU) arrays **222**A-**222**F, **224**A-**224**F within the sub-cores **221**A-**221**F. In this scheduling model, host software executing on a CPU core of an SoC including the graphics processor core **219** can submit workloads one of multiple graphic processor doorbells, which invokes a scheduling operation on the appropriate graphics engine. Scheduling operations include determining which workload to run next, submitting a workload to a command streamer, pre-empting existing workloads running on an engine, monitoring progress of a workload, and notifying host software when a workload is complete. In one embodiment the graphics microcontroller **233** can also facilitate low-power or idle states for the graphics processor core **219**, providing the graphics processor core **219** with the ability to save and restore registers within the graphics processor core **219** across low-power state transitions independently from the operating system and/or graphics driver software on the system.

The graphics processor core **219** may have greater than or fewer than the illustrated sub-cores **221**A-**221**F, up to N

modular sub-cores. For each set of N sub-cores, the graphics processor core **219** can also include shared function logic **235**, shared and/or cache memory **236**, a geometry/fixed function pipeline **237**, as well as additional fixed function logic **238** to accelerate various graphics and compute processing operations. The shared function logic **235** can include logic units associated with the shared function logic **420** of FIG. **4** (e.g., sampler, math, and/or inter-thread communication logic) that can be shared by each N sub-cores within the graphics processor core **219**. The shared and/or cache memory **236** can be a last-level cache for the set of N sub-cores **221**A-**221**F within the graphics processor core **219**, and can also serve as shared memory that is accessible by multiple sub-cores. The geometry/fixed function pipeline **237** can be included instead of the geometry/fixed function pipeline **231** within the fixed function block **230** and can include the same or similar logic units.

In one embodiment the graphics processor core **219** includes additional fixed function logic **238** that can include various fixed function acceleration logic for use by the graphics processor core **219**. In one embodiment the additional fixed function logic **238** includes an additional geometry pipeline for use in position only shading. In position-only shading, two geometry pipelines exist, the full geometry pipeline within the geometry/fixed function pipeline **231** and a cull pipeline, which is an additional geometry pipeline which may be included within the additional fixed function logic **238**. In one embodiment the cull pipeline is a trimmed down version of the full geometry pipeline. The full pipeline and the cull pipeline can execute different instances of the same application, each instance having a separate context. Position only shading can hide long cull runs of discarded triangles, enabling shading to be completed earlier in some instances. For example and in one embodiment the cull pipeline logic within the additional fixed function logic **238** can execute position shaders in parallel with the main application and generally generates critical results faster than the full pipeline, as the cull pipeline fetches and shades only the position attribute of the vertices, without performing rasterization and rendering of the pixels to the frame buffer. The cull pipeline can use the generated critical results to compute visibility information for all the triangles without regard to whether those triangles are culled. The full pipeline (which in this instance may be referred to as a replay pipeline) can consume the visibility information to skip the culled triangles to shade only the visible triangles that are finally passed to the rasterization phase.

In one embodiment the additional fixed function logic **238** can also include machine-learning acceleration logic, such as fixed function matrix multiplication logic, for implementations including optimizations for machine learning training or inferencing.

Within each graphics sub-core **221**A-**221**F includes a set of execution resources that may be used to perform graphics, media, and compute operations in response to requests by graphics pipeline, media pipeline, or shader programs. The graphics sub-cores **221**A-**221**F include multiple EU arrays **222**A-**222**F, **224**A-**224**F, thread dispatch and inter-thread communication (TD/IC) logic **223**A-**223**F, a 3D (e.g., texture) sampler **225**A-**225**F, a media sampler **206**A-**206**F, a shader processor **227**A-**227**F, and shared local memory (SLM) **228**A-**228**F. The EU arrays **222**A-**222**F, **224**A-**224**F each include multiple execution units, which are general-purpose graphics processing units capable of performing floating-point and integer/fixed-point logic operations in service of a graphics, media, or compute operation, including graphics, media, or compute shader/GPGPU programs. The TD/IC logic **223**A-**223**F performs local thread dispatch and thread control operations for the execution units within a sub-core and facilitate communication between threads executing on the execution units of the sub-core. The 3D sampler **225**A-**225**F can read texture or other 3D graphics related data into memory. The 3D sampler can read texture data differently based on a configured sample state and the texture format associated with a given texture. The media sampler **206**A-**206**F can perform similar read operations based on the type and format associated with media data. In one embodiment, each graphics sub-core **221**A-**221**F can alternately include a unified 3D and media sampler. Threads executing on the execution units within each of the sub-cores **221**A-**221**F can make use of shared local memory **228**A-**228**F within each sub-core, to enable threads executing within a thread group to execute using a common pool of on-chip memory.

FIG. **2**C illustrates a graphics processing unit (GPU) **239** that includes dedicated sets of graphics processing resources arranged into multi-core groups **240**A-**240**N. The details of multi-core group **240**A are illustrated. Multi-core groups **240**B-**240**N may be equipped with the same or similar sets of graphics processing resources.

As illustrated, a multi-core group **240**A may include a set of graphics cores **243**, a set of tensor cores **244**, and a set of ray tracing cores **245**. A scheduler/dispatcher **241** schedules and dispatches the graphics threads for execution on the various cores **243**, **244**, **245**. In one embodiment the tensor cores **244** are sparse tensor cores with hardware to enable multiplication operations having a zero value input to be bypassed.

A set of register files **242** can store operand values used by the cores **243**, **244**, **245** when executing the graphics threads. These may include, for example, integer registers for storing integer values, floating point registers for storing floating point values, vector registers for storing packed data elements (integer and/or floating point data elements) and tile registers for storing tensor/matrix values. In one embodiment, the tile registers are implemented as combined sets of vector registers.

One or more combined level 1 (L1) caches and shared memory units **247** store graphics data such as texture data, vertex data, pixel data, ray data, bounding volume data, etc., locally within each multi-core group **240**A. One or more texture units **247** can also be used to perform texturing operations, such as texture mapping and sampling. A Level 2 (L2) cache **253** shared by all or a subset of the multi-core groups **240**A-**240**N stores graphics data and/or instructions for multiple concurrent graphics threads. As illustrated, the L2 cache **253** may be shared across a plurality of multi-core groups **240**A-**240**N. One or more memory controllers **248** couple the GPU **239** to a memory **249** which may be a system memory (e.g., DRAM) and/or a dedicated graphics memory (e.g., GDDR6 memory).

Input/output (I/O) circuitry **250** couples the GPU **239** to one or more I/O devices **252** such as digital signal processors (DSPs), network controllers, or user input devices. An on-chip interconnect may be used to couple the I/O devices **252** to the GPU **239** and memory **249**. One or more I/O memory management units (IOMMUs) **251** of the I/O circuitry **250** couple the I/O devices **252** directly to the memory **249**. In one embodiment, the IOMMU **251** manages multiple sets of page tables to map virtual addresses to physical addresses in memory **249**. In this embodiment, the I/O devices **252**, CPU(s) **246**, and GPU **239** may share the same virtual address space.

In one implementation, the IOMMU **251** supports virtualization. In this case, it may manage a first set of page tables to map guest/graphics virtual addresses to guest/graphics physical addresses and a second set of page tables to map the guest/graphics physical addresses to system/host physical addresses (e.g., within memory **249**). The base addresses of each of the first and second sets of page tables may be stored in control registers and swapped out on a context switch (e.g., so that the new context is provided with access to the relevant set of page tables). While not illustrated in FIG. **2**C, each of the cores **243**, **244**, **245** and/or multi-core groups **240**A-**240**N may include translation lookaside buffers (TLBs) to cache guest virtual to guest physical translations, guest physical to host physical translations, and guest virtual to host physical translations.

In one embodiment, the CPUs **246**, GPU **239**, and I/O devices **252** are integrated on a single semiconductor chip and/or chip package. The memory **249** may be integrated on the same chip or may be coupled to the memory controllers **248** via an off-chip interface. In one implementation, the memory **249** comprises GDDR6 memory which shares the same virtual address space as other physical system-level memories, although the underlying principles of the invention are not limited to this specific implementation.

In one embodiment, the tensor cores **244** include a plurality of execution units specifically designed to perform matrix operations, which are the fundamental compute operation used to perform deep learning operations. For example, simultaneous matrix multiplication operations may be used for neural network training and inferencing. The tensor cores **244** may perform matrix processing using a variety of operand precisions including single precision floating-point (e.g., 32 bits), half-precision floating point (e.g., 16 bits), integer words (16 bits), bytes (8 bits), and half-bytes (4 bits). In one embodiment, a neural network implementation extracts features of each rendered scene, potentially combining details from multiple frames, to construct a high-quality final image.

In deep learning implementations, parallel matrix multiplication work may be scheduled for execution on the tensor cores **244**. The training of neural networks, in particular, requires a significant number of matrix dot product operations. In order to process an inner-product formulation of an N×N×N matrix multiply, the tensor cores **244** may include at least N dot-product processing elements. Before the matrix multiply begins, one entire matrix is loaded into tile registers and at least one column of a second matrix is loaded each cycle for N cycles. Each cycle, there are N dot products that are processed.

Matrix elements may be stored at different precisions depending on the particular implementation, including 16-bit words, 8-bit bytes (e.g., INT8) and 4-bit half-bytes (e.g., INT4). Different precision modes may be specified for the tensor cores **244** to ensure that the most efficient precision is used for different workloads (e.g., such as inferencing workloads which can tolerate quantization to bytes and half-bytes).

In one embodiment, the ray tracing cores **245** accelerate ray tracing operations for both real-time ray tracing and non-real-time ray tracing implementations. In particular, the ray tracing cores **245** include ray traversal/intersection circuitry for performing ray traversal using bounding volume hierarchies (BVHs) and identifying intersections between rays and primitives enclosed within the BVH volumes. The ray tracing cores **245** may also include circuitry for performing depth testing and culling (e.g., using a Z buffer or similar arrangement). In one implementation, the ray tracing cores **245** perform traversal and intersection operations in concert with the image denoising techniques described herein, at least a portion of which may be executed on the tensor cores **244**. For example, in one embodiment, the tensor cores **244** implement a deep learning neural network to perform denoising of frames generated by the ray tracing cores **245**. However, the CPU(s) **246**, graphics cores **243**, and/or ray tracing cores **245** may also implement all or a portion of the denoising and/or deep learning algorithms.

In addition, as described above, a distributed approach to denoising may be employed in which the GPU **239** is in a computing device coupled to other computing devices over a network or high speed interconnect. In this embodiment, the interconnected computing devices share neural network learning/training data to improve the speed with which the overall system learns to perform denoising for different types of image frames and/or different graphics applications.

In one embodiment, the ray tracing cores **245** process all BVH traversal and ray-primitive intersections, saving the graphics cores **243** from being overloaded with thousands of instructions per ray. In one embodiment, each ray tracing core **245** includes a first set of specialized circuitry for performing bounding box tests (e.g., for traversal operations) and a second set of specialized circuitry for performing the ray-triangle intersection tests (e.g., intersecting rays which have been traversed). Thus, in one embodiment, the multi-core group **240**A can simply launch a ray probe, and the ray tracing cores **245** independently perform ray traversal and intersection and return hit data (e.g., a hit, no hit, multiple hits, etc.) to the thread context. The other cores **243**, **244** are freed to perform other graphics or compute work while the ray tracing cores **245** perform the traversal and intersection operations.

In one embodiment, each ray tracing core **245** includes a traversal unit to perform BVH testing operations and an intersection unit which performs ray-primitive intersection tests. The intersection unit generates a "hit", "no hit", or "multiple hit" response, which it provides to the appropriate thread. During the traversal and intersection operations, the execution resources of the other cores (e.g., graphics cores **243** and tensor cores **244**) are freed to perform other forms of graphics work.

In one particular embodiment described below, a hybrid rasterization/ray tracing approach is used in which work is distributed between the graphics cores **243** and ray tracing cores **245**.

In one embodiment, the ray tracing cores **245** (and/or other cores **243**, **244**) include hardware support for a ray tracing instruction set such as Microsoft's DirectX Ray Tracing (DXR) which includes a DispatchRays command, as well as ray-generation, closest-hit, any-hit, and miss shaders, which enable the assignment of unique sets of shaders and textures for each object. Another ray tracing platform which may be supported by the ray tracing cores **245**, graphics cores **243** and tensor cores **244** is Vulkan 1.1.85. Note, however, that the underlying principles of the invention are not limited to any particular ray tracing ISA.

In general, the various cores **245**, **244**, **243** may support a ray tracing instruction set that includes instructions/functions for ray generation, closest hit, any hit, ray-primitive intersection, per-primitive and hierarchical bounding box construction, miss, visit, and exceptions. More specifically, one embodiment includes ray tracing instructions to perform the following functions:

Ray Generation—Ray generation instructions may be executed for each pixel, sample, or other user-defined work assignment.

Closest Hit—A closest hit instruction may be executed to locate the closest intersection point of a ray with primitives within a scene.

Any Hit—An any hit instruction identifies multiple intersections between a ray and primitives within a scene, potentially to identify a new closest intersection point.

Intersection—An intersection instruction performs a ray-primitive intersection test and outputs a result.

Per-primitive Bounding box Construction—This instruction builds a bounding box around a given primitive or group of primitives (e.g., when building a new BVH or other acceleration data structure).

Miss—Indicates that a ray misses all geometry within a scene, or specified region of a scene.

Visit—Indicates the children volumes a ray will traverse.

Exceptions—Includes various types of exception handlers (e.g., invoked for various error conditions).

In one embodiment the ray tracing cores **245** may be adapted to accelerate general-purpose compute operations that can be accelerated using computational techniques that are analogous to ray intersection tests. A compute framework can be provided that enables shader programs to be compiled into low level instructions and/or primitives that perform general-purpose compute operations via the ray tracing cores. Exemplary computational problems that can benefit from compute operations performed on the ray tracing cores **245** include computations involving beam, wave, ray, or particle propagation within a coordinate space. Interactions associated with that propagation can be computed relative to a geometry or mesh within the coordinate space. For example, computations associated with electromagnetic signal propagation through an environment can be accelerated via the use of instructions or primitives that are executed via the ray tracing cores. Diffraction and reflection of the signals by objects in the environment can be computed as direct ray-tracing analogies.

Ray tracing cores **245** can also be used to perform computations that are not directly analogous to ray tracing. For example, mesh projection, mesh refinement, and volume sampling computations can be accelerated using the ray tracing cores **245**. Generic coordinate space calculations, such as nearest neighbor calculations can also be performed. For example, the set of points near a given point can be discovered by defining a bounding box in the coordinate space around the point. BVH and ray probe logic within the ray tracing cores **245** can then be used to determine the set of point intersections within the bounding box. The intersections constitute the origin point and the nearest neighbors to that origin point. Computations that are performed using the ray tracing cores **245** can be performed in parallel with computations performed on the graphics cores **243** and tensor cores **244**. A shader compiler can be configured to compile a compute shader or other general-purpose graphics processing program into low level primitives that can be parallelized across the graphics cores **243**, tensor cores **244**, and ray tracing cores **245**.

FIG. **2**D is a block diagram of general purpose graphics processing unit (GPGPU) **270** that can be configured as a graphics processor and/or compute accelerator, according to embodiments described herein. The GPGPU **270** can interconnect with host processors (e.g., one or more CPU(s) **246**) and memory **271**, **272** via one or more system and/or memory busses. In one embodiment the memory **271** is system memory that may be shared with the one or more CPU(s) **246**, while memory **272** is device memory that is dedicated to the GPGPU **270**. In one embodiment, components within the GPGPU **270** and memory **272** may be mapped into memory addresses that are accessible to the one or more CPU(s) **246**. Access to memory **271** and **272** may be facilitated via a memory controller **268**. In one embodiment the memory controller **268** includes an internal direct memory access (DMA) controller **269** or can include logic to perform operations that would otherwise be performed by a DMA controller.

The GPGPU **270** includes multiple cache memories, including an L2 cache **253**, L1 cache **254**, an instruction cache **255**, and shared memory **256**, at least a portion of which may also be partitioned as a cache memory. The GPGPU **270** also includes multiple compute units **260**A-**260**N. Each compute unit **260**A-**260**N includes a set of vector registers **261**, scalar registers **262**, vector logic units **263**, and scalar logic units **264**. The compute units **260**A-**260**N can also include local shared memory **265** and a program counter **266**. The compute units **260**A-**260**N can couple with a constant cache **267**, which can be used to store constant data, which is data that will not change during the run of kernel or shader program that executes on the GPGPU **270**. In one embodiment the constant cache **267** is a scalar data cache and cached data can be fetched directly into the scalar registers **262**.

During operation, the one or more CPU(s) **246** can write commands into registers or memory in the GPGPU **270** that has been mapped into an accessible address space. The command processors **257** can read the commands from registers or memory and determine how those commands will be processed within the GPGPU **270**. A thread dispatcher **258** can then be used to dispatch threads to the compute units **260**A-**260**N to perform those commands. Each compute unit **260**A-**260**N can execute threads independently of the other compute units. Additionally each compute unit **260**A-**260**N can be independently configured for conditional computation and can conditionally output the results of computation to memory. The command processors **257** can interrupt the one or more CPU(s) **246** when the submitted commands are complete.

FIG. **3**A-**3**C illustrate block diagrams of additional graphics processor and compute accelerator architectures provided by embodiments described herein. The elements of FIG. **3**A-**3**C having the same reference numbers (or names) as the elements of any other figure herein can operate or function in any manner similar to that described elsewhere herein, but are not limited to such.

FIG. **3**A is a block diagram of a graphics processor **300**, which may be a discrete graphics processing unit, or may be a graphics processor integrated with a plurality of processing cores, or other semiconductor devices such as, but not limited to, memory devices or network interfaces. In some embodiments, the graphics processor communicates via a memory mapped I/O interface to registers on the graphics processor and with commands placed into the processor memory. In some embodiments, graphics processor **300** includes a memory interface **314** to access memory. Memory interface **314** can be an interface to local memory, one or more internal caches, one or more shared external caches, and/or to system memory.

In some embodiments, graphics processor **300** also includes a display controller **302** to drive display output data to a display device **318**. Display controller **302** includes hardware for one or more overlay planes for the display and composition of multiple layers of video or user interface elements. The display device **318** can be an internal or external display device. In one embodiment the display device **318** is a head mounted display device, such as a virtual reality (VR) display device or an augmented reality

(AR) display device. In some embodiments, graphics processor **300** includes a video codec engine **306** to encode, decode, or transcode media to, from, or between one or more media encoding formats, including, but not limited to Moving Picture Experts Group (MPEG) formats such as MPEG-2, Advanced Video Coding (AVC) formats such as H.264/MPEG-4 AVC, H.265/HEVC, Alliance for Open Media (AOMedia) VP8, VP9, AV1 as well as the Society of Motion Picture & Television Engineers (SMPTE) 421M/VC-1, and Joint Photographic Experts Group (JPEG) formats such as JPEG, and Motion JPEG (MJPEG) formats.

In some embodiments, graphics processor **300** includes a block image transfer (BLIT) engine **304** to perform two-dimensional (2D) rasterizer operations including, for example, bit-boundary block transfers. However, in one embodiment, 2D graphics operations are performed using one or more components of graphics processing engine (GPE) **310**. In some embodiments, GPE **310** is a compute engine for performing graphics operations, including three-dimensional (3D) graphics operations and media operations.

In some embodiments, GPE **310** includes a 3D pipeline **312** for performing 3D operations, such as rendering three-dimensional images and scenes using processing functions that act upon 3D primitive shapes (e.g., rectangle, triangle, etc.). The 3D pipeline **312** includes programmable and fixed function elements that perform various tasks within the element and/or spawn execution threads to a 3D/Media subsystem **315**. While 3D pipeline **312** can be used to perform media operations, an embodiment of GPE **310** also includes a media pipeline **316** that is specifically used to perform media operations, such as video post-processing and image enhancement.

In some embodiments, media pipeline **316** includes fixed function or programmable logic units to perform one or more specialized media operations, such as video decode acceleration, video de-interlacing, and video encode acceleration in place of, or on behalf of video codec engine **306**. In some embodiments, media pipeline **316** additionally includes a thread spawning unit to spawn threads for execution on 3D/Media subsystem **315**. The spawned threads perform computations for the media operations on one or more graphics execution units included in 3D/Media subsystem **315**.

In some embodiments, 3D/Media subsystem **315** includes logic for executing threads spawned by 3D pipeline **312** and media pipeline **316**. In one embodiment, the pipelines send thread execution requests to 3D/Media subsystem **315**, which includes thread dispatch logic for arbitrating and dispatching the various requests to available thread execution resources. The execution resources include an array of graphics execution units to process the 3D and media threads. In some embodiments, 3D/Media subsystem **315** includes one or more internal caches for thread instructions and data. In some embodiments, the subsystem also includes shared memory, including registers and addressable memory, to share data between threads and to store output data.

FIG. **3**B illustrates a graphics processor **320** having a tiled architecture, according to embodiments described herein. In one embodiment the graphics processor **320** includes a graphics processing engine cluster **322** having multiple instances of the graphics processing engine **310** of FIG. **3**A within a graphics engine tile **310**A-**310**D. Each graphics engine tile **310**A-**310**D can be interconnected via a set of tile interconnects **323**A-**323**F. Each graphics engine tile **310**A-**310**D can also be connected to a memory module or memory device **326**A-**326**D via memory interconnects **325**A-**325**D. The memory devices **326**A-**326**D can use any graphics memory technology. For example, the memory devices **326**A-**326**D may be graphics double data rate (GDDR) memory. The memory devices **326**A-**326**D, in one embodiment, are high-bandwidth memory (HBM) modules that can be on-die with their respective graphics engine tile **310**A-**310**D. In one embodiment the memory devices **326**A-**326**D are stacked memory devices that can be stacked on top of their respective graphics engine tile **310**A-**310**D. In one embodiment, each graphics engine tile **310**A-**310**D and associated memory **326**A-**326**D reside on separate chiplets, which are bonded to a base die or base substrate, as described on further detail in FIG. **11**B-**11**D.

The graphics processor **320** may be configured with a non-uniform memory access (NUMA) system in which memory devices **326**A-**326**D are coupled with associated graphics engine tiles **310**A-**310**D. A given memory device may be accessed by graphics engine tiles other than the tile to which it is directly connected. However, access latency to the memory devices **326**A-**326**D may be lowest when accessing a local tile. In one embodiment, a cache coherent NUMA (ccNUMA) system is enabled that uses the tile interconnects **323**A-**323**F to enable communication between cache controllers within the graphics engine tiles **310**A-**310**D to maintain a consistent memory image when more than one cache stores the same memory location.

The graphics processing engine cluster **322** can connect with an on-chip or on-package fabric interconnect **324**. In one embodiment the fabric interconnect **324** includes a network processor, network on a chip (NoC), or another switching processor to enable the fabric interconnect **324** to act as a packet switched fabric interconnect that switches data packets between components of the graphics processor **320**. The fabric interconnect **324** can enable communication between graphics engine tiles **310**A-**310**D and components such as the video codec engine **306** and one or more copy engines **304**. The copy engines **304** can be used to move data out of, into, and between the memory devices **326**A-**326**D and memory that is external to the graphics processor **320** (e.g., system memory). The fabric interconnect **324** can also couple with one or more of the tile interconnects **323**A-**323**F to facilitate or enhance the interconnection between the graphics engine tiles **310**A-**310**D. The fabric interconnect **324** is also configurable to interconnect multiple instances of the graphics processor **320** (e.g., via the host interface **328**), enabling tile-to-tile communication between graphics engine tiles **310**A-**310**D of multiple GPUs. In one embodiment, the graphics engine tiles **310**A-**310**D of multiple GPUs can be presented to a host system as a single logical device.

The graphics processor **320** may optionally include a display controller **302** to enable a connection with the display device **318**. The graphics processor may also be configured as a graphics or compute accelerator. In the accelerator configuration, the display controller **302** and display device **318** may be omitted.

The graphics processor **320** can connect to a host system via a host interface **328**. The host interface **328** can enable communication between the graphics processor **320**, system memory, and/or other system components. The host interface **328** can be, for example a PCI express bus or another type of host system interface. For example, the host interface **328** may be an NVLink or NVSwitch interface. The host interface **328** and fabric interconnect **324** can cooperate to enable multiple instances of the graphics processor **320** to act as single logical device. Cooperation between the host interface **328** and fabric interconnect **324** can also enable the

individual graphics engine tiles **310**A-**310**D to be presented to the host system as distinct logical graphics devices.

FIG. **3**C illustrates a compute accelerator **330**, according to embodiments described herein. The compute accelerator **330** can include architectural similarities with the graphics processor **320** of FIG. **3**B and is optimized for compute acceleration. A compute engine cluster **332** can include a set of compute engine tiles **340**A-**340**D that include execution logic that is optimized for parallel or vector-based general-purpose compute operations. In some embodiments, the compute engine tiles **340**A-**340**D do not include fixed function graphics processing logic, although in one embodiment one or more of the compute engine tiles **340**A-**340**D can include logic to perform media acceleration. The compute engine tiles **340**A-**340**D can connect to memory **326**A-**326**D via memory interconnects **325**A-**325**D. The memory **326**A-**326**D and memory interconnects **325**A-**325**D may be similar technology as in graphics processor **320**, or can be different. The graphics compute engine tiles **340**A-**340**D can also be interconnected via a set of tile interconnects **323**A-**323**F and may be connected with and/or interconnected by a fabric interconnect **324**. Cross-tile communications can be facilitated via the fabric interconnect **324**. The fabric interconnect **324** (e.g., via the host interface **328**) can also facilitate communication between compute engine tiles **340**A-**340**D of multiple instances of the compute accelerator **330**. In one embodiment the compute accelerator **330** includes a large L3 cache **336** that can be configured as a device-wide cache. The compute accelerator **330** can also connect to a host processor and memory via a host interface **328** in a similar manner as the graphics processor **320** of FIG. **3**B.

The compute accelerator **330** can also include an integrated network interface **342**. In one embodiment the integrated network interface **342** includes a network processor and controller logic that enables the compute engine cluster **332** to communicate over a physical layer interconnect **344** without requiring data to traverse memory of a host system. In one embodiment, one of the compute engine tiles **340**A-**340**D is replaced by network processor logic and data to be transmitted or received via the physical layer interconnect **344** may be transmitted directly to or from memory **326**A-**326**D. Multiple instances of the compute accelerator **330** may be joined via the physical layer interconnect **344** into a single logical device. Alternatively, the various compute engine tiles **340**A-**340**D may be presented as distinct network accessible compute accelerator devices.

Graphics Processing Engine

FIG. **4** is a block diagram of a graphics processing engine **410** of a graphics processor in accordance with some embodiments. In one embodiment, the graphics processing engine (GPE) **410** is a version of the GPE **310** shown in FIG. **3**A, and may also represent a graphics engine tile **310**A-**310**D of FIG. **3**B. Elements of FIG. **4** having the same reference numbers (or names) as the elements of any other figure herein can operate or function in any manner similar to that described elsewhere herein, but are not limited to such. For example, the 3D pipeline **312** and media pipeline **316** of FIG. **3**A are illustrated. The media pipeline **316** is optional in some embodiments of the GPE **410** and may not be explicitly included within the GPE **410**. For example and in at least one embodiment, a separate media and/or image processor is coupled to the GPE **410**.

In some embodiments, GPE **410** couples with or includes a command streamer **403**, which provides a command stream to the 3D pipeline **312** and/or media pipelines **316**. Alternatively or additionally, the command streamer **403** may be directly coupled to a unified return buffer **418**. The unified return buffer **418** may be communicatively coupled to a graphics core array **414**. In some embodiments, command streamer **403** is coupled with memory, which can be system memory, or one or more of internal cache memory and shared cache memory. In some embodiments, command streamer **403** receives commands from the memory and sends the commands to 3D pipeline **312** and/or media pipeline **316**. The commands are directives fetched from a ring buffer, which stores commands for the 3D pipeline **312** and media pipeline **316**. In one embodiment, the ring buffer can additionally include batch command buffers storing batches of multiple commands. The commands for the 3D pipeline **312** can also include references to data stored in memory, such as but not limited to vertex and geometry data for the 3D pipeline **312** and/or image data and memory objects for the media pipeline **316**. The 3D pipeline **312** and media pipeline **316** process the commands and data by performing operations via logic within the respective pipelines or by dispatching one or more execution threads to a graphics core array **414**. In one embodiment the graphics core array **414** include one or more blocks of graphics cores (e.g., graphics core(s) **415**A, graphics core(s) **415**B), each block including one or more graphics cores. Each graphics core includes a set of graphics execution resources that includes general-purpose and graphics specific execution logic to perform graphics and compute operations, as well as fixed function texture processing and/or machine learning and artificial intelligence acceleration logic.

In various embodiments the 3D pipeline **312** can include fixed function and programmable logic to process one or more shader programs, such as vertex shaders, geometry shaders, pixel shaders, fragment shaders, compute shaders, or other shader and/or GPGPU programs, by processing the instructions and dispatching execution threads to the graphics core array **414**. The graphics core array **414** provides a unified block of execution resources for use in processing these shader programs. Multi-purpose execution logic (e.g., execution units) within the graphics core(s) **415**A-**414**B of the graphics core array **414** includes support for various 3D API shader languages and can execute multiple simultaneous execution threads associated with multiple shaders.

In some embodiments, the graphics core array **414** includes execution logic to perform media functions, such as video and/or image processing. In one embodiment, the execution units include general-purpose logic that is programmable to perform parallel general-purpose computational operations, in addition to graphics processing operations. The general-purpose logic can perform processing operations in parallel or in conjunction with general-purpose logic within the processor core(s) **107** of FIG. **1** or core **202**A-**202**N as in FIG. **2**A.

Output data generated by threads executing on the graphics core array **414** can output data to memory in a unified return buffer (URB) **418**. The URB **418** can store data for multiple threads. In some embodiments the URB **418** may be used to send data between different threads executing on the graphics core array **414**. In some embodiments the URB **418** may additionally be used for synchronization between threads on the graphics core array and fixed function logic within the shared function logic **420**.

In some embodiments, graphics core array **414** is scalable, such that the array includes a variable number of graphics cores, each having a variable number of execution units based on the target power and performance level of GPE **410**. In one embodiment the execution resources are dynamically scalable, such that execution resources may be enabled or disabled as needed.

The graphics core array **414** couples with shared function logic **420** that includes multiple resources that are shared between the graphics cores in the graphics core array. The shared functions within the shared function logic **420** are hardware logic units that provide specialized supplemental functionality to the graphics core array **414**. In various embodiments, shared function logic **420** includes but is not limited to sampler **421**, math **422**, and inter-thread communication (ITC) **423** logic. Additionally, some embodiments implement one or more cache(s) **425** within the shared function logic **420**.

A shared function is implemented at least in a case where the demand for a given specialized function is insufficient for inclusion within the graphics core array **414**. Instead a single instantiation of that specialized function is implemented as a stand-alone entity in the shared function logic **420** and shared among the execution resources within the graphics core array **414**. The precise set of functions that are shared between the graphics core array **414** and included within the graphics core array **414** varies across embodiments. In some embodiments, specific shared functions within the shared function logic **420** that are used extensively by the graphics core array **414** may be included within shared function logic **416** within the graphics core array **414**. In various embodiments, the shared function logic **416** within the graphics core array **414** can include some or all logic within the shared function logic **420**. In one embodiment, all logic elements within the shared function logic **420** may be duplicated within the shared function logic **416** of the graphics core array **414**. In one embodiment the shared function logic **420** is excluded in favor of the shared function logic **416** within the graphics core array **414**.

Execution Units

FIG. **5**A-**5**B illustrate thread execution logic **500** including an array of processing elements employed in a graphics processor core according to embodiments described herein. Elements of FIG. **5**A-**5**B having the same reference numbers (or names) as the elements of any other figure herein can operate or function in any manner similar to that described elsewhere herein, but are not limited to such. FIG. **5**A-**5**B illustrates an overview of thread execution logic **500**, which may be representative of hardware logic illustrated with each sub-core **221**A-**221**F of FIG. **2**B. FIG. **5**A is representative of an execution unit within a general-purpose graphics processor, while FIG. **5**B is representative of an execution unit that may be used within a compute accelerator.

As illustrated in FIG. **5**A, in some embodiments thread execution logic **500** includes a shader processor **502**, a thread dispatcher **504**, instruction cache **506**, a scalable execution unit array including a plurality of graphics execution units **508**A-**508**N, a sampler **510**, shared local memory **511**, a data cache **512**, and a data port **514**. In one embodiment the scalable execution unit array can dynamically scale by enabling or disabling one or more execution units (e.g., any of graphics execution units **508**A, **508**B, **508**C, **508**D, through **508**N-**1** and **508**N) based on the computational requirements of a workload. In one embodiment the included components are interconnected via an interconnect fabric that links to each of the components. In some embodiments, thread execution logic **500** includes one or more connections to memory, such as system memory or cache memory, through one or more of instruction cache **506**, data port **514**, sampler **510**, and graphics execution units **508**A-**508**N. In some embodiments, each execution unit (e.g. **508**A) is a stand-alone programmable general-purpose computational unit that is capable of executing multiple simultaneous hardware threads while processing multiple data elements in parallel for each thread. In various embodiments, the array of graphics execution units **508**A-**508**N is scalable to include any number individual execution units.

In some embodiments, the graphics execution units **508**A-**508**N are primarily used to execute shader programs. A shader processor **502** can process the various shader programs and dispatch execution threads associated with the shader programs via a thread dispatcher **504**. In one embodiment the thread dispatcher includes logic to arbitrate thread initiation requests from the graphics and media pipelines and instantiate the requested threads on one or more execution unit in the graphics execution units **508**A-**508**N. For example, a geometry pipeline can dispatch vertex, tessellation, or geometry shaders to the thread execution logic for processing. In some embodiments, thread dispatcher **504** can also process runtime thread spawning requests from the executing shader programs.

In some embodiments, the graphics execution units **508**A-**508**N support an instruction set that includes native support for many standard 3D graphics shader instructions, such that shader programs from graphics libraries (e.g., Direct 3D, OpenGL, Vulkan, etc.) are executed with a minimal translation. The execution units support vertex and geometry processing (e.g., vertex programs, geometry programs, vertex shaders), pixel processing (e.g., pixel shaders, fragment shaders) and general-purpose processing (e.g., compute and media shaders). Each of the execution units **508**A-**508**N is capable of multi-issue single instruction multiple data (SIMD) execution and multi-threaded operation enables an efficient execution environment in the face of higher latency memory accesses. Each hardware thread within each execution unit has a dedicated high-bandwidth register file and associated independent thread-state. Execution is multi-issue per clock to pipelines capable of integer, single and double precision floating point operations, SIMD branch capability, logical operations, transcendental operations, and other miscellaneous operations. While waiting for data from memory or one of the shared functions, dependency logic within the graphics execution units **508**A-**508**N causes a waiting thread to sleep until the requested data has been returned. While the waiting thread is sleeping, hardware resources may be devoted to processing other threads. For example, during a delay associated with a vertex shader operation, an execution unit can perform operations for a pixel shader, fragment shader, or another type of shader program, including a different vertex shader. Various embodiments can apply to use execution by use of Single Instruction Multiple Thread (SIMT) as an alternate to use of SIMD or in addition to use of SIMD. Reference to a SIMD core or operation can apply also to SIMT or apply to SIMD in combination with SIMT.

Each execution unit in graphics execution units **508**A-**508**N operates on arrays of data elements. The number of data elements is the "execution size," or the number of channels for the instruction. An execution channel is a logical unit of execution for data element access, masking, and flow control within instructions. The number of channels may be independent of the number of physical Arithmetic Logic Units (ALUs), Floating Point Units (FPUs), or other logic units (e.g., tensor cores, ray tracing cores, etc.) for a particular graphics processor. In some embodiments, graphics execution units **508**A-**508**N support integer and floating-point data types.

The execution unit instruction set includes SIMD instructions. The various data elements can be stored as a packed data type in a register and the execution unit will process the various elements based on the data size of the elements. For

example, when operating on a 256-bit wide vector, the 256 bits of the vector are stored in a register and the execution unit operates on the vector as four separate 54-bit packed data elements (Quad-Word (QW) size data elements), eight separate 32-bit packed data elements (Double Word (DW) size data elements), sixteen separate 16-bit packed data elements (Word (W) size data elements), or thirty-two separate 8-bit data elements (byte (B) size data elements). However, different vector widths and register sizes are possible.

In one embodiment one or more execution units can be combined into a fused graphics execution unit **509**A-**509**N having thread control logic (**507**A-**507**N) that is common to the fused EUs. Multiple EUs can be fused into an EU group. Each EU in the fused EU group can be configured to execute a separate SIMD hardware thread. The number of EUs in a fused EU group can vary according to embodiments. Additionally, various SIMD widths can be performed per-EU, including but not limited to SIMD8, SIMD16, and SIMD32. Each fused graphics execution unit **509**A-**509**N includes at least two execution units. For example, fused execution unit **509**A includes a first EU **508**A, second EU **508**B, and thread control logic **507**A that is common to the first EU **508**A and the second EU **508**B. The thread control logic **507**A controls threads executed on the fused graphics execution unit **509**A, allowing each EU within the fused execution units **509**A-**509**N to execute using a common instruction pointer register.

One or more internal instruction caches (e.g., **506**) are included in the thread execution logic **500** to cache thread instructions for the execution units. In some embodiments, one or more data caches (e.g., **512**) are included to cache thread data during thread execution. Threads executing on the execution logic **500** can also store explicitly managed data in the shared local memory **511**. In some embodiments, a sampler **510** is included to provide texture sampling for 3D operations and media sampling for media operations. In some embodiments, sampler **510** includes specialized texture or media sampling functionality to process texture or media data during the sampling process before providing the sampled data to an execution unit.

During execution, the graphics and media pipelines send thread initiation requests to thread execution logic **500** via thread spawning and dispatch logic. Once a group of geometric objects has been processed and rasterized into pixel data, pixel processor logic (e.g., pixel shader logic, fragment shader logic, etc.) within the shader processor **502** is invoked to further compute output information and cause results to be written to output surfaces (e.g., color buffers, depth buffers, stencil buffers, etc.). In some embodiments, a pixel shader or fragment shader calculates the values of the various vertex attributes that are to be interpolated across the rasterized object. In some embodiments, pixel processor logic within the shader processor **502** then executes an application programming interface (API)-supplied pixel or fragment shader program. To execute the shader program, the shader processor **502** dispatches threads to an execution unit (e.g., **508**A) via thread dispatcher **504**. In some embodiments, shader processor **502** uses texture sampling logic in the sampler **510** to access texture data in texture maps stored in memory. Arithmetic operations on the texture data and the input geometry data compute pixel color data for each geometric fragment, or discards one or more pixels from further processing.

In some embodiments, the data port **514** provides a memory access mechanism for the thread execution logic **500** to output processed data to memory for further processing on a graphics processor output pipeline. In some embodiments, the data port **514** includes or couples to one or more cache memories (e.g., data cache **512**) to cache data for memory access via the data port.

In one embodiment, the execution logic **500** can also include a ray tracer **505** that can provide ray tracing acceleration functionality. The ray tracer **505** can support a ray tracing instruction set that includes instructions/functions for ray generation. The ray tracing instruction set can be similar to or different from the ray-tracing instruction set supported by the ray tracing cores **245** in FIG. **2**C.

FIG. **5**B illustrates exemplary internal details of an execution unit **508**, according to embodiments. A graphics execution unit **508** can include an instruction fetch unit **537**, a general register file array (GRF) **524**, an architectural register file array (ARF) **526**, a thread arbiter **522**, a send unit **530**, a branch unit **532**, a set of SIMD floating point units (FPUs) **534**, and in one embodiment a set of dedicated integer SIMD ALUs **535**. The GRF **524** and ARF **526** includes the set of general register files and architecture register files associated with each simultaneous hardware thread that may be active in the graphics execution unit **508**. In one embodiment, per thread architectural state is maintained in the ARF **526**, while data used during thread execution is stored in the GRF **524**. The execution state of each thread, including the instruction pointers for each thread, can be held in thread-specific registers in the ARF **526**.

In one embodiment the graphics execution unit **508** has an architecture that is a combination of Simultaneous Multi-Threading (SMT) and fine-grained Interleaved Multi-Threading (IMT). The architecture has a modular configuration that can be fine-tuned at design time based on a target number of simultaneous threads and number of registers per execution unit, where execution unit resources are divided across logic used to execute multiple simultaneous threads. The number of logical threads that may be executed by the graphics execution unit **508** is not limited to the number of hardware threads, and multiple logical threads can be assigned to each hardware thread.

In one embodiment, the graphics execution unit **508** can co-issue multiple instructions, which may each be different instructions. The thread arbiter **522** of the graphics execution unit thread **508** can dispatch the instructions to one of the send unit **530**, branch unit **532**, or SIMD FPU(s) **534** for execution. Each execution thread can access **128** general-purpose registers within the GRF **524**, where each register can store 32 bytes, accessible as a SIMD 8-element vector of 32-bit data elements. In one embodiment, each execution unit thread has access to 4 Kbytes within the GRF **524**, although embodiments are not so limited, and greater or fewer register resources may be provided in other embodiments. In one embodiment the graphics execution unit **508** is partitioned into seven hardware threads that can independently perform computational operations, although the number of threads per execution unit can also vary according to embodiments. For example, in one embodiment up to 16 hardware threads are supported. In an embodiment in which seven threads may access 4 Kbytes, the GRF **524** can store a total of 28 Kbytes. Where 16 threads may access 4 Kbytes, the GRF **524** can store a total of 64 Kbytes. Flexible addressing modes can permit registers to be addressed together to build effectively wider registers or to represent strided rectangular block data structures.

In one embodiment, memory operations, sampler operations, and other longer-latency system communications are dispatched via "send" instructions that are executed by the

message passing send unit **530**. In one embodiment, branch instructions are dispatched to a dedicated branch unit **532** to facilitate SIMD divergence and eventual convergence.

In one embodiment the graphics execution unit **508** includes one or more SIMD floating point units (FPU(s)) **534** to perform floating-point operations. In one embodiment, the FPU(s) **534** also support integer computation. In one embodiment the FPU(s) **534** can SIMD execute up to M number of 32-bit floating-point (or integer) operations, or SIMD execute up to 2M 16-bit integer or 16-bit floating-point operations. In one embodiment, at least one of the FPU(s) provides extended math capability to support high-throughput transcendental math functions and double precision 54-bit floating-point. In some embodiments, a set of 8-bit integer SIMD ALUs **535** are also present, and may be specifically optimized to perform operations associated with machine learning computations.

In one embodiment, arrays of multiple instances of the graphics execution unit **508** can be instantiated in a graphics sub-core grouping (e.g., a sub-slice). For scalability, product architects can choose the exact number of execution units per sub-core grouping. In one embodiment the execution unit **508** can execute instructions across a plurality of execution channels. In a further embodiment, each thread executed on the graphics execution unit **508** is executed on a different channel.

FIG. **6** illustrates an additional execution unit **600**, according to an embodiment. The execution unit **600** may be a compute-optimized execution unit for use in, for example, a compute engine tile **340**A-**340**D as in FIG. **3**C, but is not limited as such. Variants of the execution unit **600** may also be used in a graphics engine tile **310**A-**310**D as in FIG. **3**B. In one embodiment, the execution unit **600** includes a thread control unit **601**, a thread state unit **602**, an instruction fetch/prefetch unit **603**, and an instruction decode unit **604**. The execution unit **600** additionally includes a register file **606** that stores registers that can be assigned to hardware threads within the execution unit. The execution unit **600** additionally includes a send unit **607** and a branch unit **608**. In one embodiment, the send unit **607** and branch unit **608** can operate similarly as the send unit **530** and a branch unit **532** of the graphics execution unit **508** of FIG. **5**B.

The execution unit **600** also includes a compute unit **610** that includes multiple different types of functional units. The compute unit **610** can include an ALU **611**, a systolic array **612**, and a math unit **613**. The ALU **611** includes an array of arithmetic logic units. The ALU **611** can be configured to perform 64-bit, 32-bit, and 16-bit integer and floating point operations across multiple processing lanes and data channels and for multiple hardware and/or software threads. The ALU **611** can perform integer and floating point operations simultaneously (e.g., within the same clock cycle).

The systolic array **612** includes a W wide and D deep network of data processing units that can be used to perform vector or other data-parallel operations in a systolic manner. In one embodiment the systolic array **612** can be configured to perform various matrix operations, including as dot product, outer product, and general matrix-matrix multiplication (GEMM) operations. In one embodiment the systolic array **612** supports 16-bit floating point operations, as well as 8-bit, 4-bit, 2-bit, and binary integer operations. The systolic array **612** can be configured to accelerate specific machine learning operations, in addition to matrix multiply operations. In such embodiments, the systolic array **612** can be configured with support for the bfloat (brain floating point) 16-bit floating point format or a tensor float 32-bit floating point format (TF32) that have different numbers of mantissa and exponent bits relative to Institute of Electrical and Electronics Engineers (IEEE) 754 formats.

The systolic array **612** includes hardware to accelerate sparse matrix operations. In one embodiment, multiplication operations for sparse regions of input data can be bypassed at the processing element level by skipping multiply operations that have a zero value operand. In on embodiment, sparsity within input matrices can be detected and operations having known output values can be bypassed before being submitted to the processing elements of the systolic array **612**. Additionally, the loading of zero value operands into the processing elements can be bypassed and the processing elements can be configured to perform multiplications on the non-zero value input elements. Output can be generated in a compressed (e.g., dense) format, with associated decompression or decoding metadata. The output can be cached in the compressed format. The output can be maintained in the compressed format when written to local memory or host system memory. The output may also be decompressed before being written to local memory or host system memory.

In one embodiment, the systolic array **612** includes hardware to enable operations on sparse data having a compressed representation. A compressed representation of a sparse matrix stores non-zero values and metadata that identifies the positions of the non-zero values within the matrix. Exemplary compressed representations include but are not limited to compressed tensor representations such as compressed sparse row (CSR), compressed sparse column (CSC), compressed sparse fiber (CSF) representations. Support for compressed representations enable operations to be performed on input in a compressed tensor format without requiring the compressed representation to be decompressed or decoded. In such embodiment, operations can be performed only on non-zero input values and the resulting non-zero output values can be mapped into an output matrix. In some embodiments, hardware support is also provided for machine-specific lossless data compression formats that are used when transmitting data within hardware or across system busses. Such data may be retained in a compressed format for sparse input data and the systolic array **612** can used the compression metadata for the compressed data to enable operations to be performed on only non-zero values, or to enable blocks of zero data input to be bypassed for multiply operations.

In one embodiment, a math unit **613** can be included to perform a specific subset of mathematical operations in an efficient and lower-power manner than the ALU **611**. The math unit **613** can include a variant of math logic that may be found in shared function logic of a graphics processing engine provided by other embodiments (e.g., math logic **422** of the shared function logic **420** of FIG. **4**). In one embodiment the math unit **613** can be configured to perform 32-bit and 64-bit floating point operations.

The thread control unit **601** includes logic to control the execution of threads within the execution unit. The thread control unit **601** can include thread arbitration logic to start, stop, and preempt execution of threads within the execution unit **600**. The thread state unit **602** can be used to store thread state for threads assigned to execute on the execution unit **600**. Storing the thread state within the execution unit **600** enables the rapid pre-emption of threads when those threads become blocked or idle. The instruction fetch/prefetch unit **603** can fetch instructions from an instruction cache of higher-level execution logic (e.g., instruction cache **506** as in FIG. **5**A). The instruction fetch/prefetch unit **603** can also issue prefetch requests for instructions to be loaded

into the instruction cache based on an analysis of currently executing threads. The instruction decode unit **604** can be used to decode instructions to be executed by the compute units. In one embodiment, the instruction decode unit **604** can be used as a secondary decoder to decode complex instructions into constituent micro-operations.

The execution unit **600** additionally includes a register file **606** that can be used by hardware threads executing on the execution unit **600**. Registers in the register file **606** can be divided across the logic used to execute multiple simultaneous threads within the compute unit **610** of the execution unit **600**. The number of logical threads that may be executed by the graphics execution unit **600** is not limited to the number of hardware threads, and multiple logical threads can be assigned to each hardware thread. The size of the register file **606** can vary across embodiments based on the number of supported hardware threads. In one embodiment, register renaming may be used to dynamically allocate registers to hardware threads.

FIG. **7** is a block diagram illustrating graphics processor instruction formats **700** according to some embodiments. In one or more embodiment, the graphics processor execution units support an instruction set having instructions in multiple formats. The solid lined boxes illustrate the components that are generally included in an execution unit instruction, while the dashed lines include components that are optional or that are only included in a sub-set of the instructions. In some embodiments, the graphics processor instruction format **700** described and illustrated are macro-instructions, in that they are instructions supplied to the execution unit, as opposed to micro-operations resulting from instruction decode once the instruction is processed. Thus, a single instructions may cause hardware to perform multiple micro-operations.

In some embodiments, the graphics processor execution units natively support instructions in a 128-bit instruction format **710**. A 64-bit compacted instruction format **730** is available for some instructions based on the selected instruction, instruction options, and number of operands. The native 128-bit instruction format **710** provides access to all instruction options, while some options and operations are restricted in the 64-bit format **730**. The native instructions available in the 64-bit format **730** vary by embodiment. In some embodiments, the instruction is compacted in part using a set of index values in an index field **713**. The execution unit hardware references a set of compaction tables based on the index values and uses the compaction table outputs to reconstruct a native instruction in the 128-bit instruction format **710**. Other sizes and formats of instruction can be used.

For each format, instruction opcode **712** defines the operation that the execution unit is to perform. The execution units execute each instruction in parallel across the multiple data elements of each operand. For example, in response to an add instruction the execution unit performs a simultaneous add operation across each color channel representing a texture element or picture element. By default, the execution unit performs each instruction across all data channels of the operands. In some embodiments, instruction control field **714** enables control over certain execution options, such as channels selection (e.g., predication) and data channel order (e.g., swizzle). For instructions in the 128-bit instruction format **710** an exec-size field **716** limits the number of data channels that will be executed in parallel. In some embodiments, exec-size field **716** is not available for use in the 64-bit compact instruction format **730**.

Some execution unit instructions have up to three operands including two source operands, src0 **720**, src1 **722**, and one destination **718**. In some embodiments, the execution units support dual destination instructions, where one of the destinations is implied. Data manipulation instructions can have a third source operand (e.g., SRC2 **724**), where the instruction opcode **712** determines the number of source operands. An instruction's last source operand can be an immediate (e.g., hard-coded) value passed with the instruction.

In some embodiments, the 128-bit instruction format **710** includes an access/address mode field **726** specifying, for example, whether direct register addressing mode or indirect register addressing mode is used. When direct register addressing mode is used, the register address of one or more operands is directly provided by bits in the instruction.

In some embodiments, the 128-bit instruction format **710** includes an access/address mode field **726**, which specifies an address mode and/or an access mode for the instruction. In one embodiment the access mode is used to define a data access alignment for the instruction. Some embodiments support access modes including a 16-byte aligned access mode and a 1-byte aligned access mode, where the byte alignment of the access mode determines the access alignment of the instruction operands. For example, when in a first mode, the instruction may use byte-aligned addressing for source and destination operands and when in a second mode, the instruction may use 16-byte-aligned addressing for all source and destination operands.

In one embodiment, the address mode portion of the access/address mode field **726** determines whether the instruction is to use direct or indirect addressing. When direct register addressing mode is used bits in the instruction directly provide the register address of one or more operands. When indirect register addressing mode is used, the register address of one or more operands may be computed based on an address register value and an address immediate field in the instruction.

In some embodiments instructions are grouped based on opcode **712** bit-fields to simplify Opcode decode **740**. For an 8-bit opcode, bits **4**, **5**, and **6** allow the execution unit to determine the type of opcode. The precise opcode grouping shown is merely an example. In some embodiments, a move and logic opcode group **742** includes data movement and logic instructions (e.g., move (mov), compare (cmp)). In some embodiments, move and logic group **742** shares the five most significant bits (MSB), where move (mov) instructions are in the form of 0000xxxxb and logic instructions are in the form of 0001xxxxb. A flow control instruction group **744** (e.g., call, jump (jmp)) includes instructions in the form of 0010xxxxb (e.g., 0x20). A miscellaneous instruction group **746** includes a mix of instructions, including synchronization instructions (e.g., wait, send) in the form of 0011xxxxb (e.g., 0x30). A parallel math instruction group **748** includes component-wise arithmetic instructions (e.g., add, multiply (mul)) in the form of 0100xxxxb (e.g., 0x40). The parallel math instruction group **748** performs the arithmetic operations in parallel across data channels. The vector math group **750** includes arithmetic instructions (e.g., dp4) in the form of 0101xxxxb (e.g., 0x50). The vector math group performs arithmetic such as dot product calculations on vector operands. The illustrated opcode decode **740**, in one embodiment, can be used to determine which portion of an execution unit will be used to execute a decoded instruction. For example, some instructions may be designated as systolic instructions that will be performed by a systolic array. Other instructions, such as ray-tracing instructions

(not shown) can be routed to a ray-tracing core or ray-tracing logic within a slice or partition of execution logic.

Graphics Pipeline

FIG. **8** is a block diagram of another embodiment of a graphics processor **800**. Elements of FIG. **8** having the same reference numbers (or names) as the elements of any other figure herein can operate or function in any manner similar to that described elsewhere herein, but are not limited to such.

In some embodiments, graphics processor **800** includes a geometry pipeline **820**, a media pipeline **830**, a display engine **840**, thread execution logic **850**, and a render output pipeline **870**. In some embodiments, graphics processor **800** is a graphics processor within a multi-core processing system that includes one or more general-purpose processing cores. The graphics processor is controlled by register writes to one or more control registers (not shown) or via commands issued to graphics processor **800** via a ring interconnect **802**. In some embodiments, ring interconnect **802** couples graphics processor **800** to other processing components, such as other graphics processors or general-purpose processors. Commands from ring interconnect **802** are interpreted by a command streamer **803**, which supplies instructions to individual components of the geometry pipeline **820** or the media pipeline **830**.

In some embodiments, command streamer **803** directs the operation of a vertex fetcher **805** that reads vertex data from memory and executes vertex-processing commands provided by command streamer **803**. In some embodiments, vertex fetcher **805** provides vertex data to a vertex shader **807**, which performs coordinate space transformation and lighting operations to each vertex. In some embodiments, vertex fetcher **805** and vertex shader **807** execute vertex-processing instructions by dispatching execution threads to execution units **852**A-**852**B via a thread dispatcher **831**.

In some embodiments, execution units **852**A-**852**B are an array of vector processors having an instruction set for performing graphics and media operations. In some embodiments, execution units **852**A-**852**B have an attached L1 cache **851** that is specific for each array or shared between the arrays. The cache can be configured as a data cache, an instruction cache, or a single cache that is partitioned to contain data and instructions in different partitions.

In some embodiments, geometry pipeline **820** includes tessellation components to perform hardware-accelerated tessellation of 3D objects. In some embodiments, a programmable hull shader **811** configures the tessellation operations. A programmable domain shader **817** provides back-end evaluation of tessellation output. A tessellator **813** operates at the direction of hull shader **811** and contains special purpose logic to generate a set of detailed geometric objects based on a coarse geometric model that is provided as input to geometry pipeline **820**. In some embodiments, if tessellation is not used, tessellation components (e.g., hull shader **811**, tessellator **813**, and domain shader **817**) can be bypassed. The tessellation components can operate based on data received from the vertex shader **807**.

In some embodiments, complete geometric objects can be processed by a geometry shader **819** via one or more threads dispatched to execution units **852**A-**852**B, or can proceed directly to the clipper **829**. In some embodiments, the geometry shader operates on entire geometric objects, rather than vertices or patches of vertices as in previous stages of the graphics pipeline. If the tessellation is disabled the geometry shader **819** receives input from the vertex shader **807**. In some embodiments, geometry shader **819** is programmable by a geometry shader program to perform geometry tessellation if the tessellation units are disabled.

Before rasterization, a clipper **829** processes vertex data. The clipper **829** may be a fixed function clipper or a programmable clipper having clipping and geometry shader functions. In some embodiments, a rasterizer and depth test component **873** in the render output pipeline **870** dispatches pixel shaders to convert the geometric objects into per pixel representations. In some embodiments, pixel shader logic is included in thread execution logic **850**. In some embodiments, an application can bypass the rasterizer and depth test component **873** and access un-rasterized vertex data via a stream out unit **823**.

The graphics processor **800** has an interconnect bus, interconnect fabric, or some other interconnect mechanism that allows data and message passing amongst the major components of the processor. In some embodiments, execution units **852**A-**852**B and associated logic units (e.g., L1 cache **851**, sampler **854**, texture cache **858**, etc.) interconnect via a data port **856** to perform memory access and communicate with render output pipeline components of the processor. In some embodiments, sampler **854**, caches **851**, **858** and execution units **852**A-**852**B each have separate memory access paths. In one embodiment the texture cache **858** can also be configured as a sampler cache.

In some embodiments, render output pipeline **870** contains a rasterizer and depth test component **873** that converts vertex-based objects into an associated pixel-based representation. In some embodiments, the rasterizer logic includes a windower/masker unit to perform fixed function triangle and line rasterization. An associated render cache **878** and depth cache **879** are also available in some embodiments. A pixel operations component **877** performs pixel-based operations on the data, though in some instances, pixel operations associated with 2D operations (e.g. bit block image transfers with blending) are performed by the 2D engine **841**, or substituted at display time by the display controller **843** using overlay display planes. In some embodiments, a shared L3 cache **875** is available to all graphics components, allowing the sharing of data without the use of main system memory.

In some embodiments, media pipeline **830** includes a media engine **837** and a video front-end **834**. In some embodiments, video front-end **834** receives pipeline commands from the command streamer **803**. In some embodiments, media pipeline **830** includes a separate command streamer. In some embodiments, video front-end **834** processes media commands before sending the command to the media engine **837**. In some embodiments, media engine **837** includes thread spawning functionality to spawn threads for dispatch to thread execution logic **850** via thread dispatcher **831**.

In some embodiments, graphics processor **800** includes a display engine **840**. In some embodiments, display engine **840** is external to processor **800** and couples with the graphics processor via the ring interconnect **802**, or some other interconnect bus or fabric. In some embodiments, display engine **840** includes a 2D engine **841** and a display controller **843**. In some embodiments, display engine **840** contains special purpose logic capable of operating independently of the 3D pipeline. In some embodiments, display controller **843** couples with a display device (not shown), which may be a system integrated display device, as in a laptop computer, or an external display device attached via a display device connector.

In some embodiments, the geometry pipeline **820** and media pipeline **830** are configurable to perform operations

based on multiple graphics and media programming interfaces and are not specific to any one application programming interface (API). In some embodiments, driver software for the graphics processor translates API calls that are specific to a particular graphics or media library into commands that can be processed by the graphics processor. In some embodiments, support is provided for the Open Graphics Library (OpenGL), Open Computing Language (OpenCL), and/or Vulkan graphics and compute API, all from the Khronos Group. In some embodiments, support may also be provided for the Direct3D library from the Microsoft Corporation. In some embodiments, a combination of these libraries may be supported. Support may also be provided for the Open Source Computer Vision Library (OpenCV). A future API with a compatible 3D pipeline would also be supported if a mapping can be made from the pipeline of the future API to the pipeline of the graphics processor.

Graphics Pipeline Programming

FIG. **9**A is a block diagram illustrating a graphics processor command format **900** that may be used to program graphics processing pipelines according to some embodiments. FIG. **9**B is a block diagram illustrating a graphics processor command sequence **910** according to an embodiment. The solid lined boxes in FIG. **9**A illustrate the components that are generally included in a graphics command while the dashed lines include components that are optional or that are only included in a sub-set of the graphics commands. The exemplary graphics processor command format **900** of FIG. **9**A includes data fields to identify a client **902**, a command operation code (opcode) **904**, and a data field **906** for the command. A sub-opcode **905** and a command size **908** are also included in some commands.

In some embodiments, client **902** specifies the client unit of the graphics device that processes the command data. In some embodiments, a graphics processor command parser examines the client field of each command to condition the further processing of the command and route the command data to the appropriate client unit. In some embodiments, the graphics processor client units include a memory interface unit, a render unit, a 2D unit, a 3D unit, and a media unit. Each client unit has a corresponding processing pipeline that processes the commands. Once the command is received by the client unit, the client unit reads the opcode **904** and, if present, sub-opcode **905** to determine the operation to perform. The client unit performs the command using information in data field **906**. For some commands an explicit command size **908** is expected to specify the size of the command. In some embodiments, the command parser automatically determines the size of at least some of the commands based on the command opcode. In some embodiments commands are aligned via multiples of a double word. Other command formats can be used.

The flow diagram in FIG. **9**B illustrates an exemplary graphics processor command sequence **910**. In some embodiments, software or firmware of a data processing system that features an embodiment of a graphics processor uses a version of the command sequence shown to set up, execute, and terminate a set of graphics operations. A sample command sequence is shown and described for purposes of example only as embodiments are not limited to these specific commands or to this command sequence. Moreover, the commands may be issued as batch of commands in a command sequence, such that the graphics processor will process the sequence of commands in at least partially concurrence.

In some embodiments, the graphics processor command sequence **910** may begin with a pipeline flush command **912** to cause any active graphics pipeline to complete the currently pending commands for the pipeline. In some embodiments, the 3D pipeline **922** and the media pipeline **924** do not operate concurrently. The pipeline flush is performed to cause the active graphics pipeline to complete any pending commands. In response to a pipeline flush, the command parser for the graphics processor will pause command processing until the active drawing engines complete pending operations and the relevant read caches are invalidated. Optionally, any data in the render cache that is marked 'dirty' can be flushed to memory. In some embodiments, pipeline flush command **912** can be used for pipeline synchronization or before placing the graphics processor into a low power state.

In some embodiments, a pipeline select command **913** is used when a command sequence requires the graphics processor to explicitly switch between pipelines. In some embodiments, a pipeline select command **913** is required only once within an execution context before issuing pipeline commands unless the context is to issue commands for both pipelines. In some embodiments, a pipeline flush command **912** is required immediately before a pipeline switch via the pipeline select command **913**.

In some embodiments, a pipeline control command **914** configures a graphics pipeline for operation and is used to program the 3D pipeline **922** and the media pipeline **924**. In some embodiments, pipeline control command **914** configures the pipeline state for the active pipeline. In one embodiment, the pipeline control command **914** is used for pipeline synchronization and to clear data from one or more cache memories within the active pipeline before processing a batch of commands.

In some embodiments, commands related to the return buffer state **916** are used to configure a set of return buffers for the respective pipelines to write data. Some pipeline operations require the allocation, selection, or configuration of one or more return buffers into which the operations write intermediate data during processing. In some embodiments, the graphics processor also uses one or more return buffers to store output data and to perform cross thread communication. In some embodiments, the return buffer state **916** includes selecting the size and number of return buffers to use for a set of pipeline operations.

The remaining commands in the command sequence differ based on the active pipeline for operations. Based on a pipeline determination **920**, the command sequence is tailored to the 3D pipeline **922** beginning with the 3D pipeline state **930** or the media pipeline **924** beginning at the media pipeline state **940**.

The commands to configure the 3D pipeline state **930** include 3D state setting commands for vertex buffer state, vertex element state, constant color state, depth buffer state, and other state variables that are to be configured before 3D primitive commands are processed. The values of these commands are determined at least in part based on the particular 3D API in use. In some embodiments, 3D pipeline state **930** commands are also able to selectively disable or bypass certain pipeline elements if those elements will not be used.

In some embodiments, 3D primitive **932** command is used to submit 3D primitives to be processed by the 3D pipeline. Commands and associated parameters that are passed to the graphics processor via the 3D primitive **932** command are forwarded to the vertex fetch function in the graphics pipeline. The vertex fetch function uses the 3D

primitive **932** command data to generate vertex data structures. The vertex data structures are stored in one or more return buffers. In some embodiments, 3D primitive **932** command is used to perform vertex operations on 3D primitives via vertex shaders. To process vertex shaders, 3D pipeline **922** dispatches shader execution threads to graphics processor execution units.

In some embodiments, 3D pipeline **922** is triggered via an execute **934** command or event. In some embodiments, a register write triggers command execution. In some embodiments execution is triggered via a 'go' or 'kick' command in the command sequence. In one embodiment, command execution is triggered using a pipeline synchronization command to flush the command sequence through the graphics pipeline. The 3D pipeline will perform geometry processing for the 3D primitives. Once operations are complete, the resulting geometric objects are rasterized and the pixel engine colors the resulting pixels. Additional commands to control pixel shading and pixel back end operations may also be included for those operations.

In some embodiments, the graphics processor command sequence **910** follows the media pipeline **924** path when performing media operations. In general, the specific use and manner of programming for the media pipeline **924** depends on the media or compute operations to be performed. Specific media decode operations may be offloaded to the media pipeline during media decode. In some embodiments, the media pipeline can also be bypassed and media decode can be performed in whole or in part using resources provided by one or more general-purpose processing cores. In one embodiment, the media pipeline also includes elements for general-purpose graphics processor unit (GPGPU) operations, where the graphics processor is used to perform SIMD vector operations using computational shader programs that are not explicitly related to the rendering of graphics primitives.

In some embodiments, media pipeline **924** is configured in a similar manner as the 3D pipeline **922**. A set of commands to configure the media pipeline state **940** are dispatched or placed into a command queue before the media object commands **942**. In some embodiments, commands for the media pipeline state **940** include data to configure the media pipeline elements that will be used to process the media objects. This includes data to configure the video decode and video encode logic within the media pipeline, such as encode or decode format. In some embodiments, commands for the media pipeline state **940** also support the use of one or more pointers to "indirect" state elements that contain a batch of state settings.

In some embodiments, media object commands **942** supply pointers to media objects for processing by the media pipeline. The media objects include memory buffers containing video data to be processed. In some embodiments, all media pipeline states must be valid before issuing a media object command **942**. Once the pipeline state is configured and media object commands **942** are queued, the media pipeline **924** is triggered via an execute command **944** or an equivalent execute event (e.g., register write). Output from media pipeline **924** may then be post processed by operations provided by the 3D pipeline **922** or the media pipeline **924**. In some embodiments, GPGPU operations are configured and executed in a similar manner as media operations.

Graphics Software Architecture

FIG. **10** illustrates an exemplary graphics software architecture for a data processing system **1000** according to some embodiments. In some embodiments, software architecture includes a 3D graphics application **1010**, an operating system **1020**, and at least one processor **1030**. In some embodiments, processor **1030** includes a graphics processor **1032** and one or more general-purpose processor core(s) **1034**. The graphics application **1010** and operating system **1020** each execute in the system memory **1050** of the data processing system.

In some embodiments, 3D graphics application **1010** contains one or more shader programs including shader instructions **1012**. The shader language instructions may be in a high-level shader language, such as the High-Level Shader Language (HLSL) of Direct3D, the OpenGL Shader Language (GLSL), and so forth. The application also includes executable instructions **1014** in a machine language suitable for execution by the general-purpose processor core **1034**. The application also includes graphics objects **1016** defined by vertex data.

In some embodiments, operating system **1020** is a Microsoft® Windows® operating system from the Microsoft Corporation, a proprietary UNIX-like operating system, or an open source UNIX-like operating system using a variant of the Linux kernel. The operating system **1020** can support a graphics API **1022** such as the Direct3D API, the OpenGL API, or the Vulkan API. When the Direct3D API is in use, the operating system **1020** uses a front-end shader compiler **1024** to compile any shader instructions **1012** in HLSL into a lower-level shader language. The compilation may be a just-in-time (JIT) compilation or the application can perform shader pre-compilation. In some embodiments, high-level shaders are compiled into low-level shaders during the compilation of the 3D graphics application **1010**. In some embodiments, the shader instructions **1012** are provided in an intermediate form, such as a version of the Standard Portable Intermediate Representation (SPIR) used by the Vulkan API.

In some embodiments, user mode graphics driver **1026** contains a back-end shader compiler **1027** to convert the shader instructions **1012** into a hardware specific representation. When the OpenGL API is in use, shader instructions **1012** in the GLSL high-level language are passed to a user mode graphics driver **1026** for compilation. In some embodiments, user mode graphics driver **1026** uses operating system kernel mode functions **1028** to communicate with a kernel mode graphics driver **1029**. In some embodiments, kernel mode graphics driver **1029** communicates with graphics processor **1032** to dispatch commands and instructions.

IP Core Implementations

One or more aspects of at least one embodiment may be implemented by representative code stored on a machine-readable medium which represents and/or defines logic within an integrated circuit such as a processor. For example, the machine-readable medium may include instructions which represent various logic within the processor. When read by a machine, the instructions may cause the machine to fabricate the logic to perform the techniques described herein. Such representations, known as "IP cores," are reusable units of logic for an integrated circuit that may be stored on a tangible, machine-readable medium as a hardware model that describes the structure of the integrated circuit. The hardware model may be supplied to various customers or manufacturing facilities, which load the hardware model on fabrication machines that manufacture the integrated circuit. The integrated circuit may be fabricated such that the circuit performs operations described in association with any of the embodiments described herein.

FIG. **11**A is a block diagram illustrating an IP core development system **1100** that may be used to manufacture

an integrated circuit to perform operations according to an embodiment. The IP core development system **1100** may be used to generate modular, re-usable designs that can be incorporated into a larger design or used to construct an entire integrated circuit (e.g., an SOC integrated circuit). A design facility **1130** can generate a software simulation **1110** of an IP core design in a high-level programming language (e.g., C/C++). The software simulation **1110** can be used to design, test, and verify the behavior of the IP core using a simulation model **1112**. The simulation model **1112** may include functional, behavioral, and/or timing simulations. A register transfer level (RTL) design **1115** can then be created or synthesized from the simulation model **1112**. The RTL design **1115** is an abstraction of the behavior of the integrated circuit that models the flow of digital signals between hardware registers, including the associated logic performed using the modeled digital signals. In addition to an RTL design **1115**, lower-level designs at the logic level or transistor level may also be created, designed, or synthesized. Thus, the particular details of the initial design and simulation may vary.

The RTL design **1115** or equivalent may be further synthesized by the design facility into a hardware model **1120**, which may be in a hardware description language (HDL), or some other representation of physical design data. The HDL may be further simulated or tested to verify the IP core design. The IP core design can be stored for delivery to a 3rd party fabrication facility **1165** using non-volatile memory **1140** (e.g., hard disk, flash memory, or any non-volatile storage medium). Alternatively, the IP core design may be transmitted (e.g., via the Internet) over a wired connection **1150** or wireless connection **1160**. The fabrication facility **1165** may then fabricate an integrated circuit that is based at least in part on the IP core design. The fabricated integrated circuit can be configured to perform operations in accordance with at least one embodiment described herein.

FIG. **11**B illustrates a cross-section side view of an integrated circuit package assembly **1170**, according to some embodiments described herein. The integrated circuit package assembly **1170** illustrates an implementation of one or more processor or accelerator devices as described herein. The package assembly **1170** includes multiple units of hardware logic **1172**, **1174** connected to a substrate **1180**. The logic **1172**, **1174** may be implemented at least partly in configurable logic or fixed-functionality logic hardware, and can include one or more portions of any of the processor core(s), graphics processor(s), or other accelerator devices described herein. Each unit of logic **1172**, **1174** can be implemented within a semiconductor die and coupled with the substrate **1180** via an interconnect structure **1173**. The interconnect structure **1173** may be configured to route electrical signals between the logic **1172**, **1174** and the substrate **1180**, and can include interconnects such as, but not limited to bumps or pillars. In some embodiments, the interconnect structure **1173** may be configured to route electrical signals such as, for example, input/output (I/O) signals and/or power or ground signals associated with the operation of the logic **1172**, **1174**. In some embodiments, the substrate **1180** is an epoxy-based laminate substrate. The substrate **1180** may include other suitable types of substrates in other embodiments. The package assembly **1170** can be connected to other electrical devices via a package interconnect **1183**. The package interconnect **1183** may be coupled to a surface of the substrate **1180** to route electrical signals to other electrical devices, such as a motherboard, other chipset, or multi-chip module.

In some embodiments, the units of logic **1172**, **1174** are electrically coupled with a bridge **1182** that is configured to route electrical signals between the logic **1172**, **1174**. The bridge **1182** may be a dense interconnect structure that provides a route for electrical signals. The bridge **1182** may include a bridge substrate composed of glass or a suitable semiconductor material. Electrical routing features can be formed on the bridge substrate to provide a chip-to-chip connection between the logic **1172**, **1174**.

Although two units of logic **1172**, **1174** and a bridge **1182** are illustrated, embodiments described herein may include more or fewer logic units on one or more dies. The one or more dies may be connected by zero or more bridges, as the bridge **1182** may be excluded when the logic is included on a single die. Alternatively, multiple dies or units of logic can be connected by one or more bridges. Additionally, multiple logic units, dies, and bridges can be connected together in other possible configurations, including three-dimensional configurations.

FIG. **11**C illustrates a package assembly **1190** that includes multiple units of hardware logic chiplets connected to a substrate **1180**. A graphics processing unit, parallel processor, and/or compute accelerator as described herein can be composed from diverse silicon chiplets that are separately manufactured. In this context, a chiplet is an at least partially packaged integrated circuit that includes distinct units of logic that can be assembled with other chiplets into a larger package. A diverse set of chiplets with different IP core logic can be assembled into a single device. Additionally the chiplets can be integrated into a base die or base chiplet using active interposer technology. The concepts described herein enable the interconnection and communication between the different forms of IP within the GPU. IP cores can be manufactured using different process technologies and composed during manufacturing, which avoids the complexity of converging multiple IPs, especially on a large SoC with several flavors IPs, to the same manufacturing process. Enabling the use of multiple process technologies improves the time to market and provides a cost-effective way to create multiple product SKUs. Additionally, the disaggregated IPs are more amenable to being power gated independently, components that are not in use on a given workload can be powered off, reducing overall power consumption.

In various embodiments a package assembly **1190** can include components and chiplets that are interconnected by a fabric **1185** and/or one or more bridges **1187**. The chiplets within the package assembly **1190** may have a 2.5D arrangement using Chip-on-Wafer-on-Substrate stacking in which multiple dies are stacked side-by-side on a silicon interposer **1189** that couples the chiplets with the substrate **1180**. The substrate **1180** includes electrical connections to the package interconnect **1183**. In one embodiment the silicon interposer **1189** is a passive interposer that includes through-silicon vias (TSVs) to electrically couple chiplets within the package assembly **1190** to the substrate **1180**. In one embodiment, silicon interposer **1189** is an active interposer that includes embedded logic in addition to TSVs. In such embodiment, the chiplets within the package assembly **1190** are arranged using 3D face to face die stacking on top of the active interposer **1189**. The active interposer **1189** can include hardware logic for I/O **1191**, cache memory **1192**, and other hardware logic **1193**, in addition to interconnect fabric **1185** and a silicon bridge **1187**. The fabric **1185** enables communication between the various logic chiplets **1172**, **1174** and the logic **1191**, **1193** within the active interposer **1189**. The fabric **1185** may be an NoC intercon-

nect or another form of packet switched fabric that switches data packets between components of the package assembly. For complex assemblies, the fabric **1185** may be a dedicated chiplet enables communication between the various hardware logic of the package assembly **1190**.

Bridge structures **1187** within the active interposer **1189** may be used to facilitate a point to point interconnect between, for example, logic or I/O chiplets **1174** and memory chiplets **1175**. In some implementations, bridge structures **1187** may also be embedded within the substrate **1180**. The hardware logic chiplets can include special purpose hardware logic chiplets **1172**, logic or I/O chiplets **1174**, and/or memory, chiplets **1175**. The hardware logic chiplets **1172** and logic or I/O chiplets **1174** may be implemented at least partly in configurable logic or fixed-functionality logic hardware and can include one or more portions of any of the processor core(s), graphics processor(s), parallel processors, or other accelerator devices described herein. The memory chiplets **1175** can be DRAM (e.g., GDDR, IBM) memory or cache (SRAM) memory. Cache memory **1192** within the active interposer **1189** (or substrate **1180**) can act as a global cache for the package assembly **1190**, part of a distributed global cache, or as a dedicated cache for the fabric **1185**.

Each chiplet can be fabricated as separate semiconductor die and coupled with a base die that is embedded within or coupled with the substrate **1180**. The coupling with the substrate **1180** can be performed via an interconnect structure **1173**. The interconnect structure **1173** may be configured to route electrical signals between the various chiplets and logic within the substrate **1180**. The interconnect structure **1173** can include interconnects such as, but not limited to bumps or pillars. In some embodiments, the interconnect structure **1173** may be configured to route electrical signals such as, for example, input/output (I/O) signals and/or power or ground signals associated with the operation of the logic, I/O and memory chiplets. In one embodiment, an additional interconnect structure couples the active interposer **1189** with the substrate **1180**.

In some embodiments, the substrate **1180** is an epoxy-based laminate substrate. The substrate **1180** may include other suitable types of substrates in other embodiments. The package assembly **1190** can be connected to other electrical devices via a package interconnect **1183**. The package interconnect **1183** may be coupled to a surface of the substrate **1180** to route electrical signals to other electrical devices, such as a motherboard, other chipset, or multi-chip module.

In some embodiments, a logic or I/O chiplet **1174** and a memory chiplet **1175** can be electrically coupled via a bridge **1187** that is configured to route electrical signals between the logic or I/O chiplet **1174** and a memory chiplet **1175**. The bridge **1187** may be a dense interconnect structure that provides a route for electrical signals. The bridge **1187** may include a bridge substrate composed of glass or a suitable semiconductor material. Electrical routing features can be formed on the bridge substrate to provide a chip-to-chip connection between the logic or I/O chiplet **1174** and a memory chiplet **1175**. The bridge **1187** may also be referred to as a silicon bridge or an interconnect bridge. For example, the bridge **1187**, in some embodiments, is an Embedded Multi-die Interconnect Bridge (EMIB). In some embodiments, the bridge **1187** may simply be a direct connection from one chiplet to another chiplet.

FIG. **11**D illustrates a package assembly **1194** including interchangeable chiplets **1195**, according to an embodiment. The interchangeable chiplets **1195** can be assembled into standardized slots on one or more base chiplets **1196**, **1198**. The base chiplets **1196**, **1198** can be coupled via a bridge interconnect **1197**, which can be similar to the other bridge interconnects described herein and may be, for example, an EMIB. Memory chiplets can also be connected to logic or I/O chiplets via a bridge interconnect. I/O and logic chiplets can communicate via an interconnect fabric. The base chiplets can each support one or more slots in a standardized format for one of logic or I/O or memory/cache.

In one embodiment, SRAM and power delivery circuits can be fabricated into one or more of the base chiplets **1196**, **1198**, which can be fabricated using a different process technology relative to the interchangeable chiplets **1195** that are stacked on top of the base chiplets. For example, the base chiplets **1196**, **1198** can be fabricated using a larger process technology, while the interchangeable chiplets can be manufactured using a smaller process technology. One or more of the interchangeable chiplets **1195** may be memory (e.g., DRAM) chiplets. Different memory densities can be selected for the package assembly **1194** based on the power, and/or performance targeted for the product that uses the package assembly **1194**. Additionally, logic chiplets with a different number of type of functional units can be selected at time of assembly based on the power, and/or performance targeted for the product. Additionally, chiplets containing IP logic cores of differing types can be inserted into the interchangeable chiplet slots, enabling hybrid processor designs that can mix and match different technology IP blocks.

Exemplary System on a Chip Integrated Circuit

FIG. **12** and FIG. **13**A-**13**B illustrate exemplary integrated circuits and associated graphics processors that may be fabricated using one or more IP cores, according to various embodiments described herein. In addition to what is illustrated, other logic and circuits may be included, including additional graphics processors/cores, peripheral interface controllers, or general-purpose processor cores.

FIG. **12** is a block diagram illustrating an exemplary system on a chip integrated circuit **1200** that may be fabricated using one or more IP cores, according to an embodiment. Exemplary integrated circuit **1200** includes one or more application processor(s) **1205** (e.g., CPUs), at least one graphics processor **1210**, and may additionally include an image processor **1215** and/or a video processor **1220**, any of which may be a modular IP core from the same or multiple different design facilities. Integrated circuit **1200** includes peripheral or bus logic including a USB controller **1225**, UART controller **1230**, an SPI/SDIO controller **1235**, and an FS/FC controller **1240**. Additionally, the integrated circuit can include a display device **1245** coupled to one or more of a high-definition multimedia interface (HDMI) controller **1250** and a mobile industry processor interface (MIPI) display interface **1255**. Storage may be provided by a flash memory subsystem **1260** including flash memory and a flash memory controller. Memory interface may be provided via a memory controller **1265** for access to SDRAM or SRAM memory devices. Some integrated circuits additionally include an embedded security engine **1270**.

FIG. **13**A-**13**B are block diagrams illustrating exemplary graphics processors for use within an SoC, according to embodiments described herein. FIG. **13**A illustrates an exemplary graphics processor **1310** of a system on a chip integrated circuit that may be fabricated using one or more IP cores, according to an embodiment. FIG. **13**B illustrates an additional exemplary graphics processor **1340** of a system on a chip integrated circuit that may be fabricated using one or more IP cores, according to an embodiment. Graphics

processor **1310** of FIG. **13**A is an example of a low power graphics processor core. Graphics processor **1340** of FIG. **13**B is an example of a higher performance graphics processor core. Each of graphics processor **1310** and graphics processor **1340** can be variants of the graphics processor **1210** of FIG. **12**.

As shown in FIG. **13**A, graphics processor **1310** includes a vertex processor **1305** and one or more fragment processor(s) **1315**A-**1315**N (e.g., **1315**A, **1315**B, **1315**C, **1315**D, through **1315**N-**1**, and **1315**N). Graphics processor **1310** can execute different shader programs via separate logic, such that the vertex processor **1305** is optimized to execute operations for vertex shader programs, while the one or more fragment processor(s) **1315**A-**1315**N execute fragment (e.g., pixel) shading operations for fragment or pixel shader programs. The vertex processor **1305** performs the vertex processing stage of the 3D graphics pipeline and generates primitives and vertex data. The fragment processor(s) **1315**A-**1315**N use the primitive and vertex data generated by the vertex processor **1305** to produce a framebuffer that is displayed on a display device. In one embodiment, the fragment processor(s) **1315**A-**1315**N are optimized to execute fragment shader programs as provided for in the OpenGL API, which may be used to perform similar operations as a pixel shader program as provided for in the Direct 3D API.

Graphics processor **1310** additionally includes one or more memory management units (MMUs) **1320**A-**1320**B, cache(s) **1325**A-**1325**B, and circuit interconnect(s) **1330**A-**1330**B. The one or more MMU(s) **1320**A-**1320**B provide for virtual to physical address mapping for the graphics processor **1310**, including for the vertex processor **1305** and/or fragment processor(s) **1315**A-**1315**N, which may reference vertex or image/texture data stored in memory, in addition to vertex or image/texture data stored in the one or more cache(s) **1325**A-**1325**B. In one embodiment the one or more MMU(s) **1320**A-**1320**B may be synchronized with other MMUs within the system, including one or more MMUs associated with the one or more application processor(s) **1205**, image processor **1215**, and/or video processor **1220** of FIG. **12**, such that each processor **1205**-**1220** can participate in a shared or unified virtual memory system. The one or more circuit interconnect(s) **1330**A-**1330**B enable graphics processor **1310** to interface with other IP cores within the SoC, either via an internal bus of the SoC or via a direct connection, according to embodiments.

As shown FIG. **13**B, graphics processor **1340** includes the one or more MMU(s) **1320**A-**1320**B, cache(s) **1325**A-**1325**B, and circuit interconnect(s) **1330**A-**1330**B of the graphics processor **1310** of FIG. **13**A. Graphics processor **1340** includes one or more shader core(s) **1355**A-**1355**N (e.g., **1455**A, **1355**B, **1355**C, **1355**D, **1355**E, **1355**F, through **1355**N-**1**, and **1355**N), which provides for a unified shader core architecture in which a single core or type or core can execute all types of programmable shader code, including shader program code to implement vertex shaders, fragment shaders, and/or compute shaders. The unified shader core architecture is also configurable to execute direct compiled high-level GPGPU programs (e.g., CUDA). The exact number of shader cores present can vary among embodiments and implementations. Additionally, graphics processor **1340** includes an inter-core task manager **1345**, which acts as a thread dispatcher to dispatch execution threads to one or more shader cores **1355**A-**1355**N and a tiling unit **1358** to accelerate tiling operations for tile-based rendering, in which rendering operations for a scene are subdivided in image space, for example to exploit local spatial coherence within a scene or to optimize use of internal caches.

Random Sparsity Handling in a Systolic Array

Matrix multiply units can take advantage of input sparsity by zero gating ALUs, which saves power consumption, but compute throughput does not increase. To improve compute throughput from sparsity, processing resources in a matrix accelerator can skip computation with zero involved in input or output. The typical level of sparsity is about 50% for activations and corresponding gradient, and in case of pruning the level of sparsity can reaches as high as 90% in weights. If zeros in input can be skipped, the processing units can focus calculations on generating meaningful non-zero output. Accordingly, compute throughput can be increased theoretically by 2× for 50% sparsity, and by 10× for 90% sparsity in pruning case.

Described herein is a systolic array optimization for random sparsity to improve the performance of a broad range of machine learning applications. Unlike structured sparsity where certain patterns of sparsity is required and performance benefits are limited, random sparsity support covers networks from generic pruning process and takes advantage of higher level of sparsity in many networks. The systolic array described herein takes advantage of random sparsity in one input, either weights or feature maps for neural network inference or training operations. The technique described herein squeezes sparse input matrix at accumulation dimension and skips computation for zero-value elements after merging input vectors, which increases computation throughput for sparse neural networks or other matrix operations on sparse input data.

This technique improves computation throughput on systolic array for random sparse input, for example 1.5× improvement for 50% random sparsity. This technique covers structured sparsity as well, with similar 2× improvement for 50% structured sparsity. This technique is built on top of systolic array for dense matrices, without any impact on computation throughput for dense matrices.

Tensor Acceleration Logic for Machine Learning Workloads

FIG. **14** is a block diagram of a data processing system **1400**, according to an embodiment. The data processing system **1400** is a heterogeneous processing system having a processor **1402**, unified memory **1410**, and a GPGPU **1420** including machine learning acceleration logic. The processor **1402** and the GPGPU **1420** can be any of the processors and GPGPU/parallel processors as described herein. The processor **1402** can execute instructions for a compiler **1415** stored in system memory **1412**. The compiler **1415** executes on the processor **1402** to compile source code **1414**A into compiled code **1414**B. The compiled code **1414**B can include instructions that may be executed by the processor **1402** and/or instructions that may be executed by the GPGPU **1420**. During compilation, the compiler **1415** can perform operations to insert metadata, including hints as to the level of data parallelism present in the compiled code **1414**B and/or hints regarding the data locality associated with threads to be dispatched based on the compiled code **1414**B. The compiler **1415** can include the information necessary to perform such operations or the operations can be performed with the assistance of a runtime library **1416**. The runtime library **1416** can also assist the compiler **1415** in the compilation of the source code **1414**A and can also include instructions that are linked at runtime with the compiled code **1414**B to facilitate execution of the compiled instructions on the GPGPU **1420**.

The unified memory **1410** represents a unified address space that may be accessed by the processor **1402** and the

GPGPU **1420**. The unified memory can include system memory **1412** as well as GPGPU memory **1418**. The GPGPU memory **1418** is memory within an address pace of the GPGPU **1420** and can include some or all of system memory **1412**. In one embodiment the GPGPU memory **1418** can also include at least a portion of any memory dedicated for use exclusively by the GPGPU **1420**. In one embodiment, compiled code **1414**B stored in system memory **1412** can be mapped into GPGPU memory **1418** for access by the GPGPU **1420**.

The GPGPU **1420** includes multiple compute blocks **1424**A-**1424**N, which can include one or more of a variety of processing resources described herein. The processing resources can be or include a variety of different computational resources such as, for example, execution units, compute units, streaming multiprocessors, graphics multiprocessors, or multi-core groups. In one embodiment the GPGPU **1420** additionally includes a tensor (e.g., matrix) accelerator **1423**, which can include one or more special function compute units that are designed to accelerate a subset of matrix operations (e.g., dot product, etc.). The tensor accelerator **1423** may also be referred to as a tensor accelerator or tensor core. In one embodiment, logic components within the tensor accelerator **1423** may be distributed across the processing resources of the multiple compute blocks **1424**A-**1424**N.

The GPGPU **1420** can also include a set of resources that can be shared by the compute blocks **1424**A-**1424**N and the tensor accelerator **1423**, including but not limited to a set of registers **1425**, a power and performance module **1426**, and a cache **1427**. In one embodiment the registers **1425** include directly and indirectly accessible registers, where the indirectly accessible registers are optimized for use by the tensor accelerator **1423**. The power and performance module **1426** can be configured to adjust power delivery and clock frequencies for the compute blocks **1424**A-**1424**N to power gate idle components within the compute blocks **1424**A-**1424**N. In various embodiments the cache **1427** can include an instruction cache and/or a lower level data cache.

The GPGPU **1420** can additionally include an L3 data cache **1430**, which can be used to cache data accessed from the unified memory **1410** by the tensor accelerator **1423** and/or the compute elements within the compute blocks **1424**A-**1424**N. In one embodiment the L3 data cache **1430** includes shared local memory **1432** that can be shared by the compute elements within the compute blocks **1424**A-**1424**N and the tensor accelerator **1423**.

In one embodiment the GPGPU **1420** includes instruction handling logic, such as a fetch and decode unit **1421** and a scheduler controller **1422**. The fetch and decode unit **1421** includes a fetch unit and decode unit to fetch and decode instructions for execution by one or more of the compute blocks **1424**A-**1424**N or the tensor accelerator **1423**. The instructions can be scheduled to the appropriate functional unit within the compute block **1424**A-**1424**N or the tensor accelerator via the scheduler controller **1422**. In one embodiment the scheduler controller **1422** is an ASIC configurable to perform advanced scheduling operations. In one embodiment the scheduler controller **1422** is a micro-controller or a low energy-per-instruction processing core capable of executing scheduler instructions loaded from a firmware module.

In one embodiment some functions to be performed by the compute blocks **1424**A-**1424**N can be directly scheduled to or offloaded to the tensor accelerator **1423**. In various embodiments the tensor accelerator **1423** includes processing element logic configured to efficiently perform matrix compute operations, such as multiply and add operations and dot product operations used by 3D graphics or compute shader programs. In one embodiment the tensor accelerator **1423** can be configured to accelerate operations used by machine learning frameworks. In one embodiment the tensor accelerator **1423** is an application specific integrated circuit explicitly configured to perform a specific set of parallel matrix multiplication and/or addition operations. In one embodiment the tensor accelerator **1423** is a field programmable gate array (FPGA) that provides fixed function logic that can updated between workloads. The set of matrix operations that can be performed by the tensor accelerator **1423** may be limited relative to the operations that can be performed by the compute block **1424**A-**1424**N. However, the tensor accelerator **1423** can perform those the operations at a significantly higher throughput relative to the compute block **1424**A-**1424**N.

FIG. **15** illustrates a matrix operation **1505** performed by an instruction pipeline **1500**, according to an embodiment. The instruction pipeline **1500** can be configured to perform a matrix operation **1505**, such as, but not limited to a dot product operation and/or a matrix multiply and accumulate operation. The dot product of two vectors is a scalar value that is equal to sum of products of corresponding components of the vectors. The dot product can be calculated as shown in equation (1) below.

$$\vec{a} \cdot \vec{b} = \sum_{i=1}^{n} a_i b_i = a_1 b_1 + \ldots + a_n b_n \tag{1}$$

A matrix multiply and accumulate operation multiplies the elements of two matrices to generate a third matrix. To generate the third matrix, successive dot product operations are performed on rows and columns of the input matrices to generate elements of the output matrix.

The dot product can be used in a convolution operation for a convolutional neural network (CNN). FIG. **15** illustrates a two-dimensional (2D) convolution using a matrix operation **1505** including a dot product operation. While 2D convolution is illustrated, N-dimensional convolution can be performed on an N-dimensional volume using N-dimensional filters. A receptive field tile **1502** highlights a portion of an input volume in an input volume buffer **1504**. The input volume buffer can be stored in memory **1530**. A dot product matrix operation **1505** can be performed between the data within the receptive field tile **1502** and a convolutional filter to generate a data point within output buffer **1506**, which can also be stored in memory **1530**. The memory **1530** can be any of the memory described herein, including system memory **1412**, GPGPU memory **1418**, or one or more cache memories **1427**, **1430** as in FIG. **14**.

The combination of the data points within the output buffer **1506** represents an activation map generated by the convolution operation. Each point within the activation map is generated by sliding the receptive field tile across the input volume buffer **1504**. The activation map data can be input to an activation function to determine an output activation value. In one embodiment, convolution of the input volume buffer **1504** can be defined within a framework as high-level matrix operation **1505**. The high-level matrix operations can be performed via primitive operations, such as a basic linear algebra subprogram (BLAS) operation. The primitive operations can be accelerated via hardware instructions executed by the instruction pipeline **1500**.

The instruction pipeline **1500** used to accelerate hardware instructions can include the instruction fetch and decode unit **1421**, which can fetch and decode hardware instructions, and the scheduler controller **1422** which can schedule decoded instructions to one or more processing resources within the compute blocks **1424**A-**1424**N and/or the tensor accelerator **1423**. In one embodiment, a hardware instruction can be scheduled to the compute blocks **1424**A-**1424**N and offloaded to the tensor accelerator **1423**. The one or more hardware instructions and associated data to perform the matrix operation **1505** can be stored in the memory **1530**. Output of the hardware instruction can also be stored in the memory **1530**.

In one embodiment, the tensor accelerator **1423** can execute one or more hardware instructions to perform the matrix operation **1505** using an integrated systolic array **1508** (DP logic). The systolic array **1508** can include a combination of programmable and fixed function hardware that is configurable to perform dot product operations. While functional units within the compute blocks **1424**A-**1424**N can also be configured to perform dot product operations, the systolic array **1508** can be configured to perform a limited subset of dot product operations at a significantly higher throughput relative to the compute block **1424**A-**1424**N. Additionally, other types of matrix operations can be performed, including matrix multiply and accumulate operations.

FIG. **16**A-**16**B illustrate details of hardware-based systolic array **1508**, according to some embodiments. FIG. **16**A illustrates a grid of multiple functional units that are configurable to perform multiple dot product operations within a single clock cycle. FIG. **16**B illustrates a single exemplary functional unit.

As shown in FIG. **16**A, in one embodiment the systolic array **1508** is configurable to perform a set of parallel dot product operations using a variety of functional units. The dot products can be performed in a 'systolic' manner, in which SIMD data is pumped across multiple layers of functional units. As shown in FIG. **16**A, in one embodiment the systolic array **1508** is configurable to perform a set of parallel dot product operations using a variety of functional units. The dot products can be performed in a 'systolic' manner, in which SIMD data is pumped across multiple layers of functional units. The systolic array **1508** is a collection of functional units that are arranged in a grid. The grid of functional units work in lockstep and are optimized to perform multiply-accumulate operations. Matrices to be operated on by the systolic array **1508** are divided in to sub-matrices, which are pumped across the grid of functional units.

In one embodiment the systolic array **1508** can process a configurable number of SIMD channels of data using a configurable systolic depth. For a given instruction, a SIMD width and a systolic depth can be selected to process a set of source data. The systolic depth defines the number of systolic layers of hardware logic that will be used to process an instruction. A systolic layer is a group of multiplier and adder logic units having a variable SIMD width, where the systolic layer can receive, as input, an initial accumulator value and generates a dot product value for output to a successive systolic layer or to an output register.

In some embodiments, three sources can be processed, where each source can be a vector register or an immediate value. In one embodiment, source **1600** (SRC0) can be one or more initial accumulator values, which can be a single value or a vector of accumulator values. The initial accumulator value will be added to the first set of dot products computed by each functional unit within the first systolic layer. The dot product computed by a functional unit can be provided to the next systolic layer for the given SIMD channel. The dot products can be computed based on source **1601** (SRC1) and source **1602** (SRC2), which are vector registers that can contain one more channels of packed data, each channel containing a four-element vector. In one embodiment, each channel is 32-bits wide and provides four, 8-bit vector elements. In one embodiment, each channel is 64-bits wide and provides eight, 8-bit vector elements. Some embodiments are configurable to calculate dot products from input vectors having 32-bit elements, 16-bit elements, 8-bit elements, 4-bit elements, and/or 2-bit elements. In one embodiment, mixed precision operations can be performed using any combination of supported element sizes (e.g., 8-bit×2-bit, 8-bit×4-bit, 4-bit×4-bit, etc.). In one embodiment, the systolic array **1508** is configured for integer calculation, although automatic fixed-point operation is configurable in some embodiments. Although the instruction described herein is a four-element dot product, in some embodiments the systolic array **1508** may also be configured to support floating-point dot-product calculations on a different number of elements per vector.

In one embodiment, multiple channels of four-element vectors can be packed into a single vector register of various widths (e.g., 64-bit, 128-bit, 256-bit, 512-bit, etc.). Simultaneous dot products can be computed via the systolic array **1508** for multiple channels of vector elements provided via source **1601** and source **1602**. The number of channels of vector elements to be processed can be configured based on a selected execution size and systolic depth for the dot product calculation. In one embodiment, source vectors that are wider than the specified execution size and/or systolic depth may be calculated using multiple cycles of the systolic array **1508**.

The number of calculations that can be performed within a given clock cycle can vary based on the number of SIMD lanes and systolic layers. The systolic array **1508**, as illustrated, can perform sixteen dot products per SIMD lane of throughput using a systolic depth of four. If configured for eight SIMD lanes, the logic can perform 128 eight-bit integer (INT8) dot products within a given cycle. If configured for eight SIMD lanes and a systolic depth of eight, each lane can perform 32 eight-bit integer (INT8) dot products and 256 dot products in total. These specific number of operations are exemplary of one embodiment, and other embodiments vary in throughput. Furthermore, if the data types are different, then the number of operations will be scaled based on the different data types.

At each functional unit, a dot product is computed via multiplier and adder logic and the dot product is added to an accumulator value. The resulting data can be output to a destination register or provide to the accumulator of the next systolic layer. Details of a functional unit **1612** are shown in FIG. **16**B.

As shown in FIG. **16**B a functional unit **1612** can include a set of input data buffers **1604**, **1606** and an accumulator **1622**, which can each accept input data. In one embodiment, data buffer **1606** can accept source **1602**, (SRC2), which can be a packed vector of input data. Input data buffer **1604** can accept a source **1601** (SRC1), which can also be a packed vector of input data. The accumulator **1622** can accept source **1600** (SRC0) that provides an initial accumulator value for the functional unit **1612**. The initial accumulator value is added to the dot product computed from the elements of source **1601** and source **1602**. The dot product is computed via an element-wise multiplication of the source

vectors using a set of multipliers **1623**A-**1623**D and an adder **1624**. The multipliers **1623**A-**1623**D are used to compute a set of products. A sum of the set of products is computed by the adder **1624**. The sum can be accumulated with (e.g., added to) any initial value provided via source **1600**. In one embodiment, this accumulated value can be provided as an input value **1626** to the next accumulator, which can reside in a subsequent systolic layer. In one embodiment, source **1601** may include multiple channels of input data. Additional channels of source **1601** can be relayed as SRC1 input to additional SIMD lanes **1628**. In one embodiment, source **1602** may include multiple channels of input data. Additional channels of source **1602** can be used as SRC2 input data to logic units within additional systolic depths. In one embodiment, source **1600** can optionally include multiple channels, with additional channels provided as input to the accumulator within additional functional units. In one embodiment, source **1600** can be a single value that is added to each accumulator in each functional unit of the initial systolic layer.

FIG. **17**A-**17**D illustrates a sparse matrix multiply accelerator **1700** using systolic arrays with feedback inputs. FIG. **17**A shows a scalable, multi-path sparse matrix multiply accelerator **1700**. FIG. **17**B illustrates element merge logic within the sparse matrix multiply accelerator **1700**. FIG. **17**C-**17**D illustrate merging columns of matrix elements within a sparse matrix.

As shown in FIG. **17**A, the sparse matrix multiply accelerator **1700** includes processing elements **1702**A-**1702**D that include arrays of multipliers and adders. In one embodiment, processing elements **1702**A-**1702**D are structurally similar to functional unit **1612** of FIG. **16**B. Processing elements **1702**A-**1702**B at the beginning of each path include input logic for Src0. Each stage of each path of scalable sparse matrix multiply accelerator **1700** can receive any element of an independent or shared Src1 via input selectors **1712**A-**1712**D. Each stage of each path can also receive any element of a Src2 input. Independent Src2 inputs can be provided via separate input element selectors (e.g., Src2A via input selector **1710**A and input selector **1711**A, Src2B via input selector **1710**B and input selector **1711**B). The separate Src2 input enables the separate paths to compute different instructions if necessary, although the paths can be used for the same instruction. Separate output logic **1722**A-**1722**B is present for each path to enable output for the different instructions. A feedback loop can be used to feed output from processing elements **1702**C-**1702**D back to processing elements **1702**A-**1702**B to enable any number of systolic pipeline stages.

Output **1722**A-**1722**B from the final stage is labeled as Dst. Where d=the systolic depth and e=the number of data elements per channel, the output of a channel is described by equation (2) below:

$$Dst_i = Src0_i + \sum_{j=0}^{d}\sum_{k=0}^{e}(Src1 + j)_{element\ k\ of\ channel\ i} * Src2_{element\ k\ of\ channel\ j} \quad (2)$$

As shown in equation (2), each channel can include multiple data elements on which operations are performed in parallel. In one embodiment, each channel represents a four element data vector, although a different number of elements can be configured for each channel. In one embodiment, the number of data elements within a channel can vary based on the size of each data element. Dot products can be performed using, for example, four element vectors with 8-bit data types per element, two element vectors with 16-bit data types, eight element vectors with 4-bit data types (e.g., INT4), or 16 element vectors with 2-bit data types (e.g., INT2). The number of channels can be automatically adjusted depending on the datatype of Src1 and Src2. An instruction can also specify a required systolic depth to be used for the instruction.

In one embodiment the processing elements **1702**A-**1702**D may read inputs **1710**A-**1710**B, **1711**A-**1711**B directly from the general-purpose register file. In one embodiment systolic array **1700** includes logic to read inputs **1710**A-**1710**B, **1711**A-**1711**B from the general purpose register file and store input data in registers, buffers, or memory that is internal to the systolic array. Internal logic can then feed the input data elements to the processing elements **1702**A-**1702**D for processing. Output **1722**A-**1722**B can be written to internal registers or memory of the systolic array **1700** and/or written directly to the general-purpose register file.

Matrix Multiply with Random Sparsity

Embodiments described herein provide hardware and an associated processing technique that builds on top of the inner-product systolic array described herein, which accepts a first matrix (Matrix A) as broadcast vector input, a second matrix (Matrix B) as stationary matrix input, and multiplies Matrix A with Matrix B and adds to the third input Matrix C to produce output Matrix D using the formula:

$$D=A*B+C$$

Matrix accelerators described herein can take advantage of sparsity in one input matrix, while treading other inputs as dense matrices. The zero value elements in an input vector are filled with non-zero values from a paired input vector input elements positions within a vector that are zeros are filled with non-zero elements in order to fully utilize ALUs in a systolic array. This is achieved by merging input vectors before providing the vectors to the systolic array. This invention merges input vectors at accumulation dimension so it has no impact on output matrix. Unlike structured sparsity, random sparsity doesn't not guarantee perfect merging which leaves no residuals. The sparsity is increased in residual vectors and some of them will be fully empty after merging. The speedup is achieved by skipping empty vectors. This invention merges remaining residual vectors with input vector of next iteration.

To multiply with merged sparse input vector, two iteration worth of stationary Input B is stored in systolic array. Metadata of Vector A is sent along with input itself for systolic array to determine which B element to select. There is no change to the flow of how input Matrix C and output Matrix D are processed, except for higher throughput.

Structured sparsity is treated as special case of random sparsity. Taking Input A with structured sparsity, every other iteration is fully empty and completely skipped. In this case, this invention provides similar performance improvement as other technique only handle structured sparsity.

As shown in FIG. **17**B, in one embodiment the sparse matrix multiply accelerator **1700** includes or couples with memory **1720** that can store matrix elements **1722** for a Matrix A (e.g., Src2) input and matrix elements **1724** for a Matrix B (e.g., Src1) input. A load unit **1731** can load a subset of matrix element **1722** into a memory or register of the sparse matrix multiply accelerator **1700**. An element merge unit **1742** can merge elements in a first set of column vectors into a second set of column vectors. Output of the element merge unit **1742** can be stored in a matrix element buffer and fed to the functional units **1702** (e.g., **1702**A-

1702D) via a feed unit **1744** for Matrix A input (e.g., Src2 input). The merge process can generate metadata **1732** that indicates the original position of an element. The metadata **1732** can be used by a load unit **1737** to determine how to order vector elements of a Matrix B input vector, which is fed to the functional units via an additional feed unit **1738**.

As shown in FIG. **17**C, a first group of vectors from a sparse input matrix can be a first element group **1746** and a second group of vectors from the sparse input matrix can be a second element group **1747**. The element merge unit **1742** can perform an operation **1751** to merge non-zero elements from the first element group **1746** into the second element group **1747**. In one embodiment, each element group includes four vectors having four elements per vector. For a given vector, if any non-zero elements of a vector in the first element group **1746** can be merged into a corresponding vector of the second element group **1747**, then those non-zero elements are merged into the second element group **1747**. The original vector in the first element group **1746** becomes more sparse than before the merge, and in some instances may become fully sparse.

As shown in FIG. **17**D, the element merge unit **1742** can generate post-merge elements **1752** in which non-zero values in a pair of corresponding vectors of a sparse input are coalesced into one of the pair of vectors. The efficiency of parallel compute operations is increased for vectors that become more dense, while multiply operations for vectors that become fully sparse may be skipped.

FIG. **18** illustrates operations **1800** for a matrix multiply in which random sparsity is handled via element merges. A matrix multiply operation M×K×N generally accumulates results at K dimension through multiple iterations on inner-product systolic array (e.g., sparse matrix multiply accelerator **1700** of FIG. **17**). Elements of a first matrix **1810** (Matrix B, Src1) are loaded as stationary vector input and elements of a second matrix **1820** (Matrix A, Src0) are loaded as broadcast matrix input. Results of the matrix multiply operation performed between Matrix A and Matrix B are accumulated with a third matrix **1830** (Matrix C, Src0), which in some configurations may also be configured as a destination matrix (Matrix D, Dst). Depending on the size of the input, multiple iterations using multiple submatrix tiles are performed to process an entire matrix. Each iteration operates on submatrix tiles from each input. During each iteration, a previous partial sum or set of initial values is loaded, along with two input matrix tiles. A multiply and add operation is performed and a partial sum is stored to storage. To utilize sparsity in Matrix A, two input tiles **1822** are loaded and merged together to remove zeros in the input. The two input tiles **1822** of Matrix A are processed with two input tiles **1812** of Matrix B. Elements selected from one of input tiles **1812** of Matrix B are multiplied by merged elements in a merge recipient tile of the input tiles **1822** of Matrix A. Metadata generated during the merge of columns in the input tiles **1822** of Matrix A can be used to select elements from the two input tiles **1812** of Matrix B to feed to processing elements of the matrix accelerator. Vector merging is shown in FIG. **17**C-**17**D. The use of vector merging to merge columns across two interactions of input tiles is shown in FIG. **19**.

FIG. **19** illustrates operations **1900** for column merging to handle random sparsity in an input matrix of a matrix accelerator. At Step 0, the two input tiles **1822** of the second matrix **1820** (Matrix A) are shown with exemplary original values before the merge. The two input tiles **1812** of the first matrix **1810** are treated as dense matrices and are not merged. At Step 1, each column of a first tile **1902** of the two input tiles **1812** of the first matrix **1810** are merged with a corresponding column of a second tile **1904** of the two inputs **1822**. In one embodiment, each column is divided into 4-element groups or vectors, and each pair of groups are merge together to consolidate zero and non-zero values. In such embodiment, elements are merged within the vector or group of elements. However, other embodiments can enable free-form merging across tiles. Metadata is generated to record the element swaps that occur while merging. In various embodiments, the metadata can differ based on the underlying implementation of the merge hardware. In one embodiment, metadata is stored for each vector or element group to indicate the merging pattern of each group pair. In such embodiment, the merge pattern may be referenced indirectly via a look-up table. In one embodiment, a bitfield can be generated for a tile that indicates the position in the original vector or group for an element that is merged.

In one embodiment, merging is performed for each pair of columns within the tiles unless the entire column to of the second tile **1904** is empty. For that case, the merge operation is bypassed for the column, as multiply operations for a fully sparse column may be skipped. A result of an exemplary merge of the first tile **1902** into the second tile **1904** is shown as the two input tiles **1922** of Step 1, which include a residual tile **1906** and a merged tile **1908**. Elements of the merged tile **1908** can be transmitted for processing by processing elements of the systolic array, along with metadata that is generated during the merge operation. Elements from two blocks of Input B (e.g., the two input tiles **1812** of Matrix B) are sent to the systolic array during an iteration. In one embodiment, the two sets of elements from Input B are stored at each processing unit of the systolic array as stationary input. The systolic array processing can use one or more multiplexers positioned in front of input B unit to shuffle input elements before processing (e.g., via input selectors **1712**A-**1712**D of FIG. **17**A). The multiplexers can use the merge metadata to select the corresponding input B element to multiply with the merged elements from input A to compensate for the position shifts caused by the merge. In one embodiment, instead of sending the entirety of the two sets of elements from input B, only selected elements are sent, with the selected elements to send being determined according to the merge metadata.

If all groups or vectors of a column are determined to be empty, operations for the entire column can be skipped and the systolic array and proceed directly to the next column, as the resulting partial sum associated with the entire column will be zero. The more columns that are empty in input block A, the higher the speed-up that is achieved on the systolic array. Input Matrix C and output Matrix D are processed in the same fashion as in the dense matrix multiply case. Given a zero value accumulation matrix, output of the matrix operation that is performed between the second tile **1904** of elements from input block A and the two input tiles **1812** of input block B is shown as output matrix **1932**, which includes a zero value column that corresponds to the fully zero value column of the second tile **1904** of elements from input Block A. While the output matrix **1932** is otherwise dense, speedup or power saving may be realized for each sparse group or vector of elements within a column of the merged input. Increased processing efficiency may be realized for those groups or vectors of elements that are made more dense within the column of merged input.

FIG. **20** illustrates a successive set of operations **2000** that are performed to merge residual input elements during a successive iteration. Two input tiles **2022** of elements associated with input block A can be merged, where one of the

two tiles includes residual elements from the previous merge and another of the two tiles includes previously unprocessed elements. Zero value elements within the vectors or groups of elements of the residual tile of the previous merge can be replaced with non-zero values of a corresponding group or vector of the previously unprocessed tile. The tile having the merged elements can be multiplied by elements selected from one of the two input tiles **2012** associated with input block B based on merge metadata. As with the operations **1800** of FIG. **18**, elements of the two input tiles **2012** associated with input Block B can be selected based on the metadata output from the merge operation based on the original position of an element in the merged tiled. The output matrix **1932** from the previous iteration is read as input and added to the results of the multiply operation performed.

FIG. **21** illustrates operations **2100** for a second round of merging. The two input tiles **1922** of Step 1 (residual tile **1906**, merged tile **1908**) are shown. Accumulation operations along the K dimension continue with Step 2. Two input tiles **2022** of Step 2 include an incoming tile **2102** and the residual tile **1906** Step 1. In Step 3, elements of the incoming tile **2102** are merged with elements of the residual tile **1906** to create a new pair of input tiles **2122** that includes a new residual tile **2104** and a new merge tile **2106**. The merging process is repeated for each iteration and is performed for each pair of associated columns except if the destination column of the pair is full empty. For example, the illustrated new merge tile **2106**, which is the residual of the previous merge, includes three columns that are entirely zero. Merging into those columns are bypassed, as the multiply operation for those columns can be entirely skipped, as reflected in the output matrix **2132** that is generated after the iteration associated with Step 3.

The merging process described above can be performed as an on-the-fly operation for deep learning network training process. Furthermore, the merging process enables the handling of random sparsity in feature maps, which may not be able to be pruned into structured sparsity patterns as with weights. In one embodiment, merging can also be performed as an offline operation for weights that are used for inference applications. Additionally, while the merging of columns within two tiles is described, embodiments described herein can be configured to merge columns of two or more tiles. Merging can be performed for vectors of elements within a vector register file or packed elements that are configured to be distributed to scalar thread engines. While vectors/groups of four elements are illustrated, embodiments are not limited to any particular number of elements per vector or group, and elements can be merged within groups of two, four, eight, or sixteen or more elements depending on the size of the elements and the implementation of the processing elements of the systolic array, matrix accelerator, or tensor processor that implements the techniques described herein.

Experimental throughput increases are shown for an 8-deep systolic array that is configured to process 32-bit input. The systolic array can be configured as a 16-deep systolic array for 16-bit floating point input or a 32-deep systolic array for 8-bit integer input.

The speedup that will be realized from the random sparsity support described herein depends on the level of sparsity, data format, and size of input at the accumulation dimension. The results also depends on sparsity patterns in the sparse input matrix. Structurally sparse input enables a predetermined performance lift, for instance a 2× speedup from 50% structured sparsity with this scheme. While random sparsity may provide lower gains for the same level of sparsity, as the opportunity for merging zeros into empty vectors may be reduced for random and unstructured sparsity, random sparsity implementations support a higher level of sparsity, as the degree of sparsity is not restricted by a sparsity pattern. Accordingly, the potential gains for an architecture having support for random and unstructured sparsity are higher in comparison to structured sparsity implementations.

FIG. **22** and FIG. **23** illustrate throughput gains for a matrix multiply unit having support for random sparsity. FIG. **22** illustrates exemplary throughput gain **2200** for a 16-deep systolic array having 16-bit floating-point input. FIG. **23** illustrates exemplary throughput gain **2300** for a 32-deep systolic array having 8-bit integer input. The illustrated speedups **2210**, **2310** occur with a fully randomized input Matrix A, with a sweep of multiple sparsity levels. Performance benefits rise as sparsity level increases for both the 16-bit floating point input shown in FIG. **22** and the 8-bit integer input of FIG. **23**, with sizes of accumulation in the K dimension of K=128 for FIG. **22** and K=256 for FIG. **23**. As noted in the exemplary throughput gains, the techniques described herein show a performance improvement even in the presence of low sparsity. Accordingly, the techniques described herein can be generally enabled in hardware without a negative impact to performance when operating on dense matrices. However, separate sparse and non-sparse instructions may be provided to enable power saving by enabling the matrix multiply logic to disable zero detection and merge logic when inputs are known to be dense. In one embodiment the hardware can be configured to automatically disable zero detection and merge logic for dense input.

FIG. **24** illustrates a method **2400** of merging sparse matrix input having random sparsity. The method **2400** of FIG. **24** can be performed by hardware or firmware logic of a matrix accelerator unit of a graphics processor, compute accelerator, or other computing device, including a general-purpose computing device (CPU) or a field programmable gate array (FPGA). In some embodiments, a subset of operations can be performed by driver, compute framework logic, or machine learning framework logic associated with a processor or accelerator.

Logic configured to implement method **2400** can perform an operation to load multiple data elements of a first submatrix and a second submatrix into memory of a processor device (**2402**). The memory can be a memory within or coupled with a matrix accelerator unit of a processor device. In one embodiment the matrix accelerator includes include a systolic array of processing units. The logic can then determine a first grouping of elements of the first submatrix and a second grouping of elements of the second submatrix (**2404**). The first grouping and the second grouping can each include multiple groups, where each group in the first grouping has a corresponding group in the second grouping. Corresponding groups can be groups that are stored at the same location in the respective submatrices. For example, a group at the given row and column index of the first matrix has a corresponding group at the same row and column index of the second matrix.

In one embodiment, the groupings correspond with multiple-element vectors that are read from or stored to vector registers within the processor and/or matrix accelerator unit. In one embodiment the vectors include four matrix elements, although embodiments are not so limited. The number of elements within a vector can vary based on the size of the data elements and the size of the vector register. The groupings can also correspond with packed data elements

that are to be provided to scalar compute units, for example in a single instruction, multiple thread (SIMT) GPU.

The logic can then perform an operation to merge elements of a first group of the first grouping into a second group of the second grouping (**2406**). In one embodiment the second group, in to which elements are merged, is the corresponding group of the first group and is located at the same row and column index of the second submatrix as the first group is located in the first submatrix. In one embodiment, the merge process includes to read an element from the first group and determine if space exists within the second group at the corresponding location of the first group. Space exists within the second group if one or more elements of the second group are zero. If space exists in the second group, the first group and the second group can swap the corresponding elements, such that the zero value is written to the first group and the non-zero value is written to the second group. In one embodiment, instead of explicitly swapping elements, the non-zero value can be written to the second group and the original location in the first group can be cleared. The merge process can then repeat for each element in the first group until all values in the second group are non-zero.

The logic can then generate metadata to indicate a merge pattern for elements of the first group (**2408**). The metadata can include a bitfield that indicates an original position of a merged element in the original group from which the element is read. Other metadata formats may also be used. The logic can then provide the second group and the metadata to a processing element of the processor device as input for a matrix operation including a matrix multiply (**2410**). The second group can be provided as input along with elements of a third and fourth submatrix of a second input matrix, where elements are selected from the third or fourth submatrix based on the metadata.

FIG. **25**A-**25**C illustrates methods **2500**, **2510**, **2520** of handling random sparsity of an input matrix during a matrix multiply operation. The methods **2500**, **2510** can be performed by hardware or firmware logic of a matrix accelerator unit of a graphics processor, compute accelerator, or other computing device, including a general-purpose computing device (CPU) or a field programmable gate array (FPGA). In some embodiments, a subset of operations can be performed by driver, compute frame work logic, or machine learning framework logic associated with a processor or accelerator.

As shown in FIG. **25**A, logic configured to implement method **2500** can read a first set of two or more tiles of elements associated with a first matrix (**2502**). The first set of two or more tiles can include two or more submatrix tiles of a matrix input having elements to be broadcast across processing elements of the matrix accelerator unit. The logic can then merge a first group of elements in a first tile of the two or more tiles of elements into a second group of elements of a corresponding group of elements in a second tile of the two or more tiles of elements (**2504**). The merging can be performed based on operations described with respect to method **2400** of FIG. **24**. Merging the first group of elements is performed to reduce the sparsity of the second tile and increases sparsity of the second tile, such that non-zero elements of the first tile are coalesced into the second tile. The merge process produces metadata that indicates an original position for merged elements to enable corresponding elements of a matrix multiply operation to be identified.

The logic can additionally perform an operation to read a second set of two or more tiles of elements associated with a second matrix. The second matrix include elements that will remain stationary within the matrix accelerator during a systolic matrix multiply operation. (**2506**). The logic can then perform a matrix multiply operation having input including the second group of elements in the second tile and selected elements from the second set of two or more tiles of elements (**2508**). The selected elements from the second set of two or more tiles are selected based on the metadata generated based on the merging, such that the matrix multiply operation is performed between the correct elements, as though the merge process did not occur.

As shown in FIG. **25**B, during the merge operation and the matrix operation, the operations can be skipped when an entire column of a submatrix tile is zero, as the dot product associated with that column will be zero. According to method **2510**, merge logic, during a merge operation, can bypass a merge of a first column of elements into a second column of elements when all elements of the second column are zero (**2512**). Additionally, matrix multiply logic, during a matrix multiply operation, can bypass a dot product operation including the aforementioned second column of elements when all elements of the second column are zero (**2514**).

As shown in FIG. **25**C, according to method **2520**, the merge operation, in one embodiment, is performed on corresponding groups within columns of submatrix tiles of an input matrix for a matrix multiply operation. Method **2520** include operations performed by logic such as an element merge unit **1742** of FIG. **17**B. The operations include read a first element of a first group of elements (**2522**). The first group of elements can be elements of a vector stored in a vector register or an element in a packed group of elements. The operations additionally include to determine whether there is a non-zero value element in the first group (**2523**). If there are no non-zero values in the first group ("No," **2523**), the logic can select the next group in the first submatrix (**2524**). In one embodiment the next group is the next group along the K dimension in the same column as the first submatrix. If there is a non-zero value element in the first group ("Yes", **2523**), the logic can read a second group of elements in a corresponding column of a second submatrix (**2526**). The second group of elements is a group of elements of the same size and at the same location in the second submatrix as the first group in the first submatrix. If there is a zero value element in the second group ("Yes", **2527**), the logic can swap the zero value element in the second group of elements with the non-zero value element in the first group of elements (**2528**). The logic can then determine if additional non-zero value elements remain in the first group (**2523**). If there are no zero value elements in the second group ("No", **2527**), the logic can select the next group in the first submatrix (**2524**) and operations can continue by reading the selected next group (**2522**).

According to the above disclosure, one embodiment described herein provides a method comprising loading multiple data elements of a first submatrix and a second submatrix into memory of a processor device, determining a first grouping of elements of the first submatrix and a second grouping of elements of the second submatrix, wherein the first grouping and the second grouping include multiple groups and each group in the first grouping has a corresponding group in the second grouping, merging elements of a first group of the first grouping into a second group of the second grouping, wherein the second group is the corresponding group of the first group, generating metadata to indicate a merge pattern for elements of the first group, and providing the second group and the metadata to

a processing element of the processor device as input for a matrix operation including a matrix multiply.

A further embodiment provides a method comprising reading a first set of two or more tiles of elements associated with a first matrix, merging a first group of elements in a first tile of the two or more tiles of elements into a second group of elements of a corresponding group of elements in a second tile of the two or more tiles of elements, wherein merging the first group of elements reduces sparsity of the second tile and increases sparsity of the second tile and generates metadata based on the merging of the first group of elements into the second group of elements, reading a second set of two or more tiles of elements associated with a second matrix, and performing a matrix multiply operation having input including the second group of elements in the second tile and selected elements from the second set of two or more tiles of elements, the selected elements from the second set of two or more tiles selected based on the metadata generated based on the merging.

Additional Exemplary Computing Device

FIG. **26** is a block diagram of a computing device **2600** including a graphics processor **2604**, according to an embodiment. Versions of the computing device **2600** may be or be included within a communication device such as a set-top box (e.g., Internet-based cable television set-top boxes, etc.), global positioning system (GPS)-based devices, etc. The computing device **2600** may also be or be included within mobile computing devices such as cellular phones, smartphones, personal digital assistants (PDAs), tablet computers, laptop computers, e-readers, smart televisions, television platforms, wearable devices (e.g., glasses, watches, bracelets, smartcards, jewelry, clothing items, etc.), media players, etc. For example, in one embodiment, the computing device **2600** includes a mobile computing device employing an integrated circuit ("IC"), such as system on a chip ("SoC" or "SOC"), integrating various hardware and/or software components of computing device **2600** on a single chip. The computing device **2600** can be a computing device such as the data processing system **100** as in of FIG. **1**.

The computing device **2600** includes a graphics processor **2604**. The graphics processor **2604** represents any graphics processor described herein. In one embodiment, the graphics processor **2604** includes a cache **2614**, which can be a single cache or divided into multiple segments of cache memory, including but not limited to any number of L1, L2, L3, or L4 caches, render caches, depth caches, sampler caches, and/or shader unit caches. In one embodiment the cache **2614** may be a last level cache that is shared with the application processor **2606**.

In one embodiment the graphics processor **2604** includes a graphics microcontroller that implements control and scheduling logic for the graphics processor. The control and scheduling logic can be firmware executed by the graphics microcontroller **2615**. The firmware may be loaded at boot by the graphics driver logic **2622**. The firmware may also be programmed to an electronically erasable programmable read only memory or loaded from a flash memory device within the graphics microcontroller **2615**. The firmware may enable a GPU OS **2616** that includes device management/driver logic **2617**, **2618**, and a scheduler **2619**. The GPU OS **2616** may also include a graphics memory manager **2620** that can supplement or replace the graphics memory manager **2621** within the graphics driver logic **2622**.

The graphics processor **2604** also includes a GPGPU engine **2644** that includes one or more graphics engine(s), graphics processor cores, and other graphics execution resources as described herein. Such graphics execution resources can be presented in the forms including but not limited to execution units, shader engines, fragment processors, vertex processors, streaming multiprocessors, graphics processor clusters, or any collection of computing resources suitable for the processing of graphics resources or image resources, or performing general purpose computational operations in a heterogeneous processor. The processing resources of the GPGPU engine **2644** can be included within multiple tiles of hardware logic connected to a substrate, as illustrated in FIG. **11**B-**11**D. The GPGPU engine **2644** can include GPU tiles **2645** that include graphics processing and execution resources, caches, samplers, etc. The GPU tiles **2645** may also include local volatile memory or can be coupled with one or more memory tiles, for example, as shown in FIG. **3**B-**3**C.

The GPGPU engine **2644** can also include and one or more special tiles **2646** that include, for example, a non-volatile memory tile **2656**, a network processor tile **2657**, and/or a general-purpose compute tile **2658**. The GPGPU engine **2644** also includes a matrix multiply accelerator **2660**. The general-purpose compute tile **2658** may also include logic to accelerate matrix multiplication operations. The non-volatile memory tile **2656** can include non-volatile memory cells and controller logic. The controller logic of the non-volatile memory tile **2656** may be managed by one of device management/driver logic **2617**, **2618**. The network processor tile **2657** can include network processing resources that are coupled to a physical interface within the input/output (I/O) sources **2610** of the computing device **2600**. The network processor tile **2657** may be managed by one or more of device management/driver logic **2617**, **2618**.

The matrix multiply accelerator **2660** is a modular scalable sparse matrix multiply accelerator as described herein. The matrix multiply accelerator **2660** can includes multiple processing paths, with each processing path including multiple pipeline stages. Each processing path can execute a separate instruction. In various embodiments, the matrix multiply accelerator **2660** can have architectural features of any one of more of the matrix multiply accelerators described herein. For example, in one embodiment, the matrix multiply accelerator **2660** is a four-deep systolic array **1700** with a feedback loop that is configurable to operate with a multiple of four number of logical stages (e.g., four, eight, twelve, sixteen, etc.). In one embodiment the matrix multiply accelerator **2660** includes one or more instances of a two-path matrix multiply accelerator **1900** with a four stage pipeline or a four-path matrix multiply accelerator **2000** with a two stage pipeline. In one embodiment the matrix multiply accelerator **2660** includes processing elements configured as the scalable sparse matrix multiply accelerator **2100** or the scalable sparse matrix multiply accelerator **2300**. The matrix multiply accelerator **2660** can be configured to operate only on non-zero values of at least one input matrix. Operations on entire columns or submatrices can be bypassed where block sparsity is present. The matrix multiply accelerator **2660** can also include any logic based on any combination of these embodiments, and particularly include logic to enable support for random sparsity, according to embodiments described herein.

As illustrated, in one embodiment, and in addition to the graphics processor **2604**, the computing device **2600** may further include any number and type of hardware components and/or software components, including, but not limited to an application processor **2606**, memory **2608**, and input/output (I/O) sources **2610**. The application processor **2606** can interact with a hardware graphics pipeline, as illustrated with reference to FIG. **3**A, to share graphics

pipeline functionality. Processed data is stored in a buffer in the hardware graphics pipeline and state information is stored in memory **2608**. The resulting data can be transferred to a display controller for output via a display device, such as the display device **318** of FIG. **3**A. The display device may be of various types, such as Cathode Ray Tube (CRT), Thin Film Transistor (TFT), Liquid Crystal Display (LCD), Organic Light Emitting Diode (OLED) array, etc., and may be configured to display information to a user via a graphical user interface.

The application processor **2606** can include one or processors, such as processor(s) **102** of FIG. **1** and may be the central processing unit (CPU) that is used at least in part to execute an operating system (OS) **2602** for the computing device **2600**. The OS **2602** can serve as an interface between hardware and/or physical resources of the computing device **2600** and one or more users. The OS **2602** can include driver logic for various hardware devices in the computing device **2600**. The driver logic can include graphics driver logic **2622**, which can include the user mode graphics driver **1026** and/or kernel mode graphics driver **1029** of FIG. **10**. The graphics driver logic can include a graphics memory manager **2621** to manage a virtual memory address space for the graphics processor **2604**.

It is contemplated that in some embodiments the graphics processor **2604** may exist as part of the application processor **2606** (such as part of a physical CPU package) in which case, at least a portion of the memory **2608** may be shared by the application processor **2606** and graphics processor **2604**, although at least a portion of the memory **2608** may be exclusive to the graphics processor **2604**, or the graphics processor **2604** may have a separate store of memory. The memory **2608** may comprise a pre-allocated region of a buffer (e.g., framebuffer); however, it should be understood by one of ordinary skill in the art that the embodiments are not so limited, and that any memory accessible to the lower graphics pipeline may be used. The memory **2608** may include various forms of random-access memory (RAM) (e.g., SDRAM, SRAM, etc.) comprising an application that makes use of the graphics processor **2604** to render a desktop or 3D graphics scene. A memory controller hub, such as memory controller **116** of FIG. **1**, may access data in the memory **2608** and forward it to graphics processor **2604** for graphics pipeline processing. The memory **2608** may be made available to other components within the computing device **2600**. For example, any data (e.g., input graphics data) received from various I/O sources **2610** of the computing device **2600** can be temporarily queued into memory **2608** prior to their being operated upon by one or more processor(s) (e.g., application processor **2606**) in the implementation of a software program or application. Similarly, data that a software program determines should be sent from the computing device **2600** to an outside entity through one of the computing system interfaces, or stored into an internal storage element, is often temporarily queued in memory **2608** prior to its being transmitted or stored.

The I/O sources can include devices such as touchscreens, touch panels, touch pads, virtual or regular keyboards, virtual or regular mice, ports, connectors, network devices, or the like, and can attach via a platform controller hub **130** as referenced in FIG. **1**. Additionally, the I/O sources **2610** may include one or more I/O devices that are implemented for transferring data to and/or from the computing device **2600** (e.g., a networking adapter); or, for a large-scale non-volatile storage within the computing device **2600** (e.g., SSD/HDD). User input devices, including alphanumeric and other keys, may be used to communicate information and command selections to graphics processor **2604**. Another type of user input device is cursor control, such as a mouse, a trackball, a touchscreen, a touchpad, or cursor direction keys to communicate direction information and command selections to GPU and to control cursor movement on the display device. Camera and microphone arrays of the computing device **2600** may be employed to observe gestures, record audio and video and to receive and transmit visual and audio commands.

The I/O sources **2610** can include one or more network interfaces. The network interfaces may include associated network processing logic and/or be coupled with the network processor tile **2657**. The one or more network interface can provide access to a LAN, a wide area network (WAN), a metropolitan area network (MAN), a personal area network (PAN), Bluetooth, a cloud network, a cellular or mobile network (e.g., 3^{rd} Generation (3G), 4^{th} Generation (4G), 5^{th} Generation (5G), etc.), an intranet, the Internet, etc. Network interface(s) may include, for example, a wireless network interface having one or more antenna(e). Network interface(s) may also include, for example, a wired network interface to communicate with remote devices via network cable, which may be, for example, an Ethernet cable, a coaxial cable, a fiber optic cable, a serial cable, or a parallel cable.

Network interface(s) may provide access to a LAN, for example, by conforming to IEEE 802.11 standards, and/or the wireless network interface may provide access to a personal area network, for example, by conforming to Bluetooth standards. Other wireless network interfaces and/or protocols, including previous and subsequent versions of the standards, may also be supported. In addition to, or instead of, communication via the wireless LAN standards, network interface(s) may provide wireless communication using, for example, Time Division, Multiple Access (TDMA) protocols, Global Systems for Mobile Communications (GSM) protocols, Code Division, Multiple Access (CDMA) protocols, and/or any other type of wireless communications protocols.

It is to be appreciated that a lesser or more equipped system than the example described above may be preferred for certain implementations. Therefore, the configuration of the computing devices described herein may vary from implementation to implementation depending upon numerous factors, such as price constraints, performance requirements, technological improvements, or other circumstances. Examples include (without limitation) a mobile device, a personal digital assistant, a mobile computing device, a smartphone, a cellular telephone, a handset, a one-way pager, a two-way pager, a messaging device, a computer, a personal computer (PC), a desktop computer, a laptop computer, a notebook computer, a handheld computer, a tablet computer, a server, a server array or server farm, a web server, a network server, an Internet server, a work station, a mini-computer, a main frame computer, a supercomputer, a network appliance, a web appliance, a distributed computing system, multiprocessor systems, processor-based systems, consumer electronics, programmable consumer electronics, television, digital television, set top box, wireless access point, base station, subscriber station, mobile subscriber center, radio network controller, router, hub, gateway, bridge, switch, machine, or combinations thereof.

One embodiment provides a processing apparatus comprising a tile of processing resources including a general-purpose parallel processing engine and a matrix accelerator, the matrix accelerator including first circuitry to load multiple data elements of a first submatrix and a second sub-

matrix into memory accessible to the matrix accelerator and second circuitry determine a first grouping of elements of the first submatrix and a second grouping of elements of the second submatrix. The first grouping and the second grouping include multiple groups and each group in the first grouping has a corresponding group in the second grouping. The apparatus additionally includes third circuitry to merge elements of a first group of the first grouping into a second group of the second grouping and generate metadata to indicate a merge pattern for elements of the first group. The second group is the corresponding group of the first group. The processing apparatus additionally includes fourth circuitry to provide the second group and the metadata to an array of processing elements within the matrix accelerator as input for a matrix operation.

In one embodiment, the memory accessible to the matrix accelerator is internal to the matrix accelerator. Additionally, the matrix operation to be performed can include a dot product operation. The dot product operation may be a sub-operation of a matrix multiply operation. The array of processing elements can include a systolic array. In one embodiment, to merge elements of a first group of the first grouping into a second group of the second grouping includes to read a first group of elements in a column of the first submatrix, read a second group of elements in a corresponding column of the second submatrix, and swap a non-zero value element in the first group of elements with a zero value element in the second group of elements. To swap the non-zero value element in the first group of elements with the zero value element in the second group of elements includes to write the value of the non-zero value element to a position in the second group of elements and clear the memory that stores the position of the non-zero value element in the first group of elements. In one embodiment, the first group of elements and the second group of elements are multi-element vectors. The group of elements may also be a packed group of elements to be operated on by a scalar and/or SIMT processor. To merge elements of the first group of the first grouping into the second group of the second grouping includes to determine that the column of the second submatrix that includes the second grouping includes only zero value elements and bypass merge operations for the column. In one embodiment, the metadata to indicate the merge pattern for elements of the first group includes a bitfield to indicate an origin position of a merged element.

One embodiment provides an apparatus comprising means for reading a first set of two or more tiles of elements associated with a first matrix, means for merging a first group of elements in a first tile of the two or more tiles of elements into a second group of elements of a corresponding group of elements in a second tile of the two or more tiles of elements, wherein merging the first group of elements reduces sparsity of the second tile and increases sparsity of the second tile and generates metadata based on the merging of the first group of elements into the second group of elements, means for reading a second set of two or more tiles of elements associated with a second matrix, and means for performing a matrix multiply operation having input including the second group of elements in the second tile and selected elements from the second set of two or more tiles of elements, the selected elements from the second set of two or more tiles selected based on the metadata generated based on the merging.

Those skilled in the art will appreciate from the foregoing description that the broad techniques of the embodiments can be implemented in a variety of forms. Therefore, while the embodiments have been described in connection with particular examples thereof, the true scope of the embodiments should not be so limited since other modifications will become apparent to the skilled practitioner upon a study of the drawings, specification, and following claims.

What is claimed is:

1. A processing apparatus including:

a tile of processing resources including a general-purpose parallel processing engine and a matrix accelerator, the matrix accelerator including:

first circuitry to load multiple data elements of a first submatrix and a second submatrix into memory accessible to the matrix accelerator;

second circuitry to determine a first grouping of elements of the first submatrix and a second grouping of elements of the second submatrix, wherein the first grouping and the second grouping include multiple groups and each group in the first grouping has a corresponding group in the second grouping;

third circuitry to merge elements of a first group of the first grouping into a second group of the second grouping, wherein the second group is the corresponding group of the first group, and generate metadata to indicate a merge pattern for elements of the first group; and

fourth circuitry to provide the second group and the metadata to an array of processing elements within the matrix accelerator as input for a matrix operation.

2. The processing apparatus as in claim **1**, wherein the memory accessible to the matrix accelerator is internal to the matrix accelerator.

3. The processing apparatus as in claim **1**, wherein the matrix operation to be performed includes a dot product operation.

4. The processing apparatus as in claim **3**, wherein the dot product operation is a sub-operation of a matrix multiply operation.

5. The processing apparatus as in claim **4**, wherein the array of processing elements includes a systolic array.

6. The processing apparatus as in claim **1**, wherein to merge elements of a first group of the first grouping into a second group of the second grouping includes to:

read a first group of elements in a column of the first submatrix;

read a second group of elements in a corresponding column of the second submatrix; and

swap a non-zero value element in the first group of elements with a zero value element in the second group of elements.

7. The processing apparatus as in claim **6**, wherein to swap the non-zero value element in the first group of elements with the zero value element in the second group of elements includes to:

write the value of the non-zero value element to a position in the second group of elements; and

clear the memory that stores the position of the non-zero value element in the first group of elements.

8. The processing apparatus as in claim **6**, wherein the first group of elements and the second group of elements are multi-element vectors.

9. The processing apparatus as in claim **6**, wherein to merge elements of the first group of the first grouping into the second group of the second grouping includes to:

determine that the column of the second submatrix that includes the second grouping includes only zero value elements; and

bypass merge operations for the column.

10. The processing apparatus as in claim 1, wherein the metadata to indicate the merge pattern for elements of the first group includes a bitfield to indicate an origin position of a merged element.

11. A method including:

loading multiple data elements of a first submatrix and a second submatrix into memory of a processor device;

determining a first grouping of elements of the first submatrix and a second grouping of elements of the second submatrix, wherein the first grouping and the second grouping include multiple groups and each group in the first grouping has a corresponding group in the second grouping;

merging elements of a first group of the first grouping into a second group of the second grouping, wherein the second group is the corresponding group of the first group;

generating metadata to indicate a merge pattern for elements of the first group; and

providing the second group and the metadata to an array of processing elements of the processor device as input for a matrix operation including a matrix multiply.

12. The method as in claim 11, wherein the memory of the processor device is internal to a matrix accelerator of the processor device and the matrix operation to be performed includes a dot product operation.

13. The method as in claim 12, wherein the dot product operation is a sub-operation of a matrix multiply operation.

14. The method as in claim 13, wherein the array of processing elements includes a systolic array.

15. The method as in claim 11, wherein merging elements of a first group of the first grouping into a second group of the second grouping includes:

reading a first group of elements in a column of the first submatrix;

reading a second group of elements in a corresponding column of the second submatrix; and

swapping a non-zero value element in the first group of elements with a zero value element in the second group of elements.

16. The method as in claim 15, wherein swapping the non-zero value element in the first group of elements with the zero value element in the second group of elements includes:

writing the value of the non-zero value element to a position in the second group of elements; and

clearing the memory that stores the position of the non-zero value element in the first group of elements.

17. The method as in claim 15, wherein the first group of elements and the second group of elements are multi-element vectors and merging elements of the first group of the first grouping into the second group of the second grouping includes:

determining that the column of the second submatrix that includes the second grouping includes only zero value elements; and

bypassing merge operations for the column.

18. The method as in claim 11, wherein the metadata to indicate the merge pattern for elements of the first group includes a bitfield to indicate an origin position of a merged element.

19. A system comprising:

a memory device; and

a graphics processor including:

a tile of processing resources including a general-purpose parallel processing engine and a matrix accelerator, the matrix accelerator including:

first circuitry to load multiple data elements of a first submatrix and a second submatrix into memory accessible to the matrix accelerator;

second circuitry to determine a first grouping of elements of the first submatrix and a second grouping of elements of the second submatrix, wherein the first grouping and the second grouping include multiple groups and each group in the first grouping has a corresponding group in the second grouping;

third circuitry to merge elements of a first group of the first grouping into a second group of the second grouping, wherein the second group is the corresponding group of the first group, and generate metadata to indicate a merge pattern for elements of the first group; and

fourth circuitry to provide the second group and the metadata to an array of processing elements within the matrix accelerator as input for a matrix operation.

20. The system as in claim 19, wherein the memory accessible to the matrix accelerator is internal to the matrix accelerator, the matrix operation to be performed includes a dot product operation, and the dot product operation is a sub-operation of a matrix multiply operation.

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